Section 6 Technical Data

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Specifications

It is impossible to characterize the listening quality of even the simplest limiter or compressor on the basis of the usual specifications, because such specifications cannot adequately describe the crucial dynamic processes that occur under program conditions. Therefore, the only way to meaningfully evaluate the sound of an audio processor is by subjective listening tests.

Certain specifications are presented here to assure the engineer that they are reasonable, to help plan the installation, and to help make certain comparisons with other processing equipment.

Performance

Specifications for measurements from analog left/right input to stereo composite output and to analog left/right output are as follows:

Frequency Response (All structures, measured below gain reduction and clipping thresholds, high-pass filter off): Follows standard 50 μ s or 75 μ s pre-emphasis curve ± 0.20 dB, 5Hz-15kHz. Analog left/right output can be user-configured for flat or pre-emphasized output.

Noise: Output noise floor will depend upon how much gain the processor is set for (LIMIT DRIVE, AGC DRIVE, TWO-BAND DRIVE, and/or MULTI-BAND DRIVE), gating level, equalization, noise reduction, etc. It is primarily governed by the dynamic range of the A/D Converter, which has a manufacturer-specified overload-to-noise ratio of 97dB. The dynamic range of the digital signal processing is 144dB.

Total System Distortion (De-Emphasized, 100% Modulation): <0.01% THD, 20Hz-1kHz rising to <.05% at 15kHz.<0.02% SMPTE IM Distortion.

Total System Separation: >65dB, 20Hz-15kHz; 70dB typical.

Polarity (PROTECTION, TWO-BAND PURIST or BYPASS Structure): Absolute polarity maintained. Positive-going signal on input will result in positive-going signal on output.

Installation

Analog Audio Input

Configuration: Left and right.

Impedance: 600Ω or $10k\Omega$ load impedance, electronically balanced, jumper-selectable.

Common Mode Rejection: >70dB at 50-60Hz. >45dB at 60Hz-15kHz.

Sensitivity: -40dBu to +20dBu to produce 10dB gain reduction at 1kHz.

Maximum Input Level: +27dBu.

Connector: XLR-type, female, EMI-suppressed. Pin 1 Chassis Ground, Pins 2 and 3 electronically balanced, floating and symmetrical.

Analog Audio Output

Configuration: Left and right. Flat or pre-emphasized.

Source Impedance: 30Ω , $\pm 5\%$, electronically balanced and floating.

Load Impedance: 600Ω or greater, balanced or unbalanced. Termination not required.

Maximum Output Level: +23.7dBu into 600Ω or greater, balanced load.

Connector: XLR-type, male, EMI-suppressed. Pin 1 Chassis Ground, Pins 2 and 3 electroni-

cally balanced, floating and symmetrical.

Digital Input and Output (Optional)

Configuration: Two-channel AES/EBU-standard.

Sampling rate: 32kHz (8200D/32) or 32kHz, 44.1kHz, and 48kHz (8200D/SRC).

Connector: XLR-type, female, EMI-suppressed. Pin 1 Chassis Ground, Pins 2 and 3 trans-

former balanced and floating.

SCA Subcarrier Input

Configuration: Subcarrier input sums into composite baseband outputs.

Input Impedance: 600Ω .

Sensitivity: 1.0Vp-p for 10% modulation of main carrier.

Connector: BNC, floating over chassis ground. EMI-suppressed.

Composite Baseband Outputs

Configuration: Two (2) outputs, each with independent OUTPUT level control, output amplifier

and connector.

Source Impedance: 0Ω voltage source or 75Ω (jumper-selectable), single ended, floating over

chassis ground.

Load Impedance: 37Ω or greater. Termination not required.

Level (0 Ω Source Impedance, 75 Ω or higher Load Impedance): Adjustable 0-8Vp-p with

multi-turn OUTPUT LEVEL control.

Connector: BNC, floating over chassis ground. EMI-suppressed.

 $\label{lem:maximum Recommended Cable Length (0$\Omega Source Impedance): 100ft/30m RG-58A/U.$

Maximum permitted load capacitance 0.047μF.

Pilot Reference Output

Configuration: Buffered square-wave reference for RDS or other subcarrier services.

Source: HCMOS logic level output, 0-5V peak.

Connector: On Remote Control Interface. DB-25, EMI-suppressed.

Remote Computer Interface

Configuration: RS-232 and RS-422 interfaces to connect to IBM PC-compatible computers, directly or via modem, for remote control and metering.

Minimum Hardware: 386 computer or compatible with hard disk drive, 4MB RAM, VGA grayscale or color display, DOS 3.3 or higher, Micosoft[®] WindowsTM 3.1 or higher, and Hayes-compatible modem (2400 baud rate, V.42bis data compression).

Optimum Hardware: Pentium[®] or 486 computer with hard disk drive, 8MB RAM, VGA color display, DOS 5.0 or later, Micosoft[®] Windows[™] 3.1 or later, and Hayes-compatible modem (9600 baud rate, V.42bis data compression).

Connector — RS-232: DB-9, EMI-suppressed.
Connector — RS-422: DB-9, EMI-suppressed.

Remote Control Interface

Configuration: Eight (8) analog or digital inputs. User-programmable to select any eight of: user presets, factory presets, stereo, mono left, mono right, SC1 modulation reduction, SC2 modulation reduction, TX1 overshoot modulation reduction, TX2 overshoot modulation reduction, clock reset, EBS tone, exit test, input analog, input digital.

Voltage: 6-24VAC or DC, momentary or continuous, optically-isolated. Current-Limited 12VDC provided to facilitate use with contact closure.

Connector: DB-25, EMI-suppressed.

Power

Requirements: Switch-selectable on the rear panel, 90-130VAC or 180-260VAC, 50-60Hz; 55VA.

Connector: IEC; detachable 3-wire power cord supplied. AC is EMI-suppressed.

Ground: Circuit ground is independent of chassis ground; can be isolated or connected with a rear panel switch.

Safety Standards: IEC65, UL, CSA.

Dimensions

Dimensions (WxHxD): 19in/48.3cm wide, 7in/17.8cm high, 15in/38.1cm deep. 4 rack units.

Environmental

Operating Temperature Range: 32-122°F/0-50°C

Humidity: 0-95% RH, non-condensing.

Setup and Operation

Help Features

HELP Button: Available at all times. Push HELP, and a message will tell you what you are looking at on the screen, what can be done and how to do it. Press each button and the message will tell you the function of that button.

System Setup (I/O CALIB)

Function: Initial setup.

Controls: Studio chassis yes/no (defeats AGC), Pre-emphasis 50μs or 75μs, meter select VU or PPM, analog input clip level, analog input reference level, analog input balance, analog outputs flat or pre-emphasized, analog output level, input meters indicate ref/clip, modulation type, pilot on/off, clock sync to AC line/crystal, reduction of modulation for SC1 ON, reduction of modulation for SC2 ON, reduction of modulation for OSHOOT TX1 ON, reduction of modulation for OSHOOT TX2 ON; if Digital I/O is present: input A or D, digital input ref level.

Quick Setup

Function: Guided screen-by-screen setup for all required setup adjustments.

On-Screen Metering

Metering can be switched to indicate gain reduction (G/R) or input/output levels (I/O).

Gain reduction (G/R): Shows gain reduction of AGC, compressors, high-frequency limiters, and gate on/off, as appropriate to the programmable processing structure selected.

Input/Output (I/O): Left input (dB), right input (dB), left output (dB), right output (dB), composite output (% modulation).

Pilot: 7.5-10%, in 0.5% steps.

Preset Programming

Function: Save processing settings for recall from the front panel, by remote control, by remote computer or by Automatic Preset Switching.

Number of User Presets: 32.

Test Presets

BYPASS preset: No processing; audio is digitized and low-pass filtered only. Adjustable gain (–18 to +15dB).

TONE Preset: Frequency programmable 30Hz-15kHz. Level programmable 0-121% total modulation. Modulation type (L,R, L+R, L-R, MONO L, MONO R), Pilot ON/OFF.

Automatic Preset Switching

Function: Changes presets on a programmed event schedule.

Programming: Date (specific date, time, function) or daily (specific day or days of the week, time, function).

Events: Up to 99 events.



Pascode Security

Function: To prevent unauthorized adjustment of controls by persons without pascodes.

Number of Pascodes: 10.

Access: Each Pascode can be programmed to permit or deny access via front panel or computer to RECALL PRESET, RECALL TEST PRESETS, MODIFY PROCESSING, OBSERVE METERS and PRESET NAMES, PROGRAM AUTOMATION (Automatic Preset Switching), PROGRAM SYSTEM SETUP and PROGRAM SET PASCODE.

Remote Control with Orban 8200PC Remote Control Software

Metering: Same as On-Screen Metering, above.

Control: All user-adjustable processing parameters, Preset functions and System Setup.

Circuit Characteristics

Analog-To-Digital Converter

(A/D Converter subject to change as technology improves.)

Device: Analog Devices AD1879.

Performance: >97dB dynamic range (overload-to-noise ratio).

Digital Signal Processing

Device: Motorola DSP56001.

Performance: 24-bit processing. 144dB internal dynamic range.

Digital Input Conditioning

Subsonic Filter: Switchable in/out third-order Chebychev with 30Hz cutoff and 0.5dB pass-band ripple; -0.5dB @ 30Hz, -10.5dB @ 20Hz, -31.5dB @10Hz.

Time Dispersion Network: All-pass network to make speech more symmetrical to reduce processing distortion. (Normal Two-Band and Multi-Band structures only.)

Digital Output Conditioning

Passband Response: Typically +0, −0.26dB to 15kHz.

Stopband Rejection (Referenced to 100% Modulation): To reduce spectrum in stereo composite baseband above 57kHz to <-75dB.

Digital-To-Analog Converter

Device: Analog Devices AD1864.

Performance: 18-bit. 4X oversampled output. Linear-phase reconstruction filters.

Pilot

Frequency: 19kHz.

Stability: ±0.005%. See "Ultrastable Pilot" on page 1-9.

Injection: Adjustable, 7.5-10%.

Stereo Baseband Encoder

(Test signals applied to analog inputs of stereo baseband encoder.)

Noise (De-Emphasized, Referenced to 100% Modulation): <-100dB, 20Hz-15kHz.

Distortion (De-Emphasized, 100% Modulation): <0.006% THD, 20Hz-15kHz; <0.010% SMPTE Intermodulation Distortion.

Stereo Separation: >65dB, 20Hz-15kHz; 70dB typical.

Crosstalk — Linear (Referenced to 100% Modulation): <-80dB, main channel to subchannel or subchannel to main channel.

Crosstalk — **Non-linear (referenced to 100% modulation):** <-80dB, main channel to subchannel or subchannel to main channel.

38kHz Subcarrier Suppression (Referenced to 100% Modulation): >70dB; 75dB typical.

76kHz and Sideband Suppression (Referenced to 100% Modulation): >70dB.

CIT25 Composite Isolation Transformer

Ground loops are a problem in some transmitter plants. A ground loop among OPTIMOD-FM and one or more exciters may occur, causing an increase in hum and noise. This is especially likely when OPTIMOD-FM is installed some distance from the exciter.

The Composite Isolation Transformer provides the solution. Designed to be installed adjacent to each exciter, it provides ground isolation between the OPTIMOD-FM composite output and the exciter, and presents OPTIMOD-FM with a balanced floating load.

Performance

Frequency Response: +0.01, -0.03dB, 30Hz-53kHz.

Group Delay: Deviation from linear phase <±0.3°, 30Hz-53kHz.

Separation: >50dB, 50Hz-15kHz.

Gain: Adjustable from full attenuation to 0dB.

Installation

Location

Location: As close to FM exciter as practical.

Interconnect Between OPTIMOD-FM and Transformer

Interface at OPTIMOD-FM: Adapter cable, BNC male to 3-pin XLR-type male cable connector supplied.

Cable: Two-conductor foil-shielded audio cable, Belden 8451 or equivalent. Maximum length 100ft/30m, user-supplied. 3-pin XLR-type male and female cable connectors supplied.

Composite Baseband Input

Connector: 3-pin XLR-type female. Pin 1 capacitively-coupled to chassis ground, Pins 2 and 3 transformer balanced, floating and symmetrical.

Maximum Level: 4Vp-p.

Composite Baseband Output

Connector: BNC, shell insulated from chassis ground.

Interconnect Between Transformer and Exciter

Maximum Recommended Cable Length: 6ft/1.8m RG-58A/U cable or similar, to avoid excessive RF pick-up on cable. 2ft/.6m cable supplied.

Exciter Input: $1k\Omega$ or greater; 1000pF or less. Replace 50Ω or 75Ω termination resistor, if present, with $1k\Omega$ resistor, supplied.

Dimensions

Dimension: 7in/17.8cm wide, 3in/7.6cm high, 1.72in/4.4cm deep.

Warranty

One Year, Parts and Labor: Subject to the limitations set forth in Orban's Standard Warranty Agreement.

Specifications subject to change without notice.

Circuit Description

This section provides a detailed description of each circuit used in the 8200. It starts with an overview of the 8200 system, identifying all the circuit boards and describing their purpose. Then each board is treated in detail by first giving an overview of the circuits followed by a component-by-component description.

1. Overview

The 8200 has 9 types of circuit boards: Mother, Analog I/O, Stereo Encoder, DSP (digital signal processing), Control, Display, Power Supply, Input Filter and D-Connector.

The block diagram on page 6-46 illustrates the following overview of 8200 circuit boards.

The Motherboard contains no active circuitry and serves only to connect all the other boards together properly.

The Analog I/O Card provides the circuitry to interface the analog audio inputs and outputs to the digital processing.

The Stereo Encoder Card generates the composite output signal.

The DSP Cards implement the audio processing using digital signal processing. The 8200 has slots for four DSP Cards. The base unit is shipped with two DSP Cards. The Multi-Band structure requires a third board. A fourth slot is provided for future options.

The Control Card administrates control of the 8200 system.

The Display Board provides circuitry for the LCD display, push buttons, front panel knobs.

The Power Supply Board provides power for all 8200 boards.

The Input Filter Board provides the connectors and RF filtering for the left and right audio inputs and outputs, the digital audio input and output, the two composite outputs, and the SCA input.

The D-Connector Board provides the connectors, RF filtering, and circuitry for the remote control inputs, RS-232 interface, and RS-422 interface.

Motherboard

The Motherboard is used to connect all parts of the 8200 system together. Only connectors are mounted to it. It is a four layer board with nearly all signal traces on the outer two layers. The inner layers contain ground and power connections.

Under no circumstances should you try to replace any components on this board. Soldering or desoldering can permanently damage the inner layers and ruin the board.

Analog I/O Card

1. Overview

The Analog I/O Card provides the circuitry to interface analog audio to and from the DSP Cards. The input buffer scales the input audio level to match it to the audio processor. The analog-to-digital (A/D) converter converts the analog input audio to digital audio. The digital audio is transmitted to the DSP Cards. The DSP Cards transmit the processed digital audio output back to the Analog I/O Card. The digital output audio is converted to an analog signal by the digital-to-analog (D/A) converter. The low-pass reconstruction filters remove high frequency images from the D/A converter output and feed the output buffer. The output buffer is made up of a programmable gain amplifier, a programmable time constant de-emphasis filter, and a balanced output buffer. The board also provides logic circuitry to generate the system sample rate clocks and interface the board to the Control Card and DSP Cards.

2. Input Buffer

The signal enters the input buffer in balanced form. It comes from the Input Filter Board via the Motherboard. The signal is applied to a resistor load and a resistor pad. The pad and the load are enabled or disabled by jumpers that are positioned by hand. The loaded and padded signal is applied to a balanced amplifier that has an adjustable gain. The gain is set by FET transistors and analog switches. The state of the FETs and switches is set by the outputs of a latch. The Control Card controls the gain according to what the user specifies from the front panel controls by writing data to the latch. The balanced amplifier output feeds a servoed buffer which feeds an RC low-pass filter applying the signal to the analog-to-digital converter.

Component-level description:

The balanced audio input signal is applied to the pad and load network made up of R200, R203, R204 and R205-7. JA is a jumper that removes or inserts a 600Ω termination load on the input signal. JB is a jumper that removes or inserts a resistive divider that pads the input signal before being applied to IC15, a balanced amplifier. R215-222, FETs Q202-203, and IC14, a quad analog switch, make up the circuit that sets gain of IC15. The FETs are used as switches along with IC14 to change the resistive paths in the circuit. The state of the FET switches is set by the outputs of IC19, a digital latch. The latch outputs feed IC7, a quad comparator, which outputs 0V to turn on a FET and -15V to turn off a FET. The Control Card writes data directly to IC14 to control the state of the switches on IC14. IC8 and IC9 buffer and gain-scale the signal prior to its application to the A to D converter.

3. Analog-to-Digital Converter (A/D)

The A/D is a single chip, stereo, 18-bit sigma-delta type converter. The A/D oversamples the audio at 2.048MHz. It applies noise shaping, then it filters and decimates to a 32kHz sample rate. The samples are output in twos complement format and transmitted to the DSP Cards.

Component-level description:

The right analog input is applied to pin 13. Pin 26 is a 8.192MHz clock input used by the chip to oversample the input. Pins 3 and 25 place the A/D in its slave mode allowing it to rum form an external bit and L/R clock. Pin 27 is the serial data output. Both the left and right samples are multiplexed on to it and synchronized to the 2.048MHz clock. The left sample starts on the rising edge of the L/R clock.

4. Digital-to-Analog Converter

The D/A is a single chip, stereo, 18-bit resistor ladder type. It has two synchronous serial inputs that receive the left and right audio samples from the DSP Cards. A NAND gate outputs a signal to clock the data in. A 128kHz clock signal controls the timing of when the output switches between analog sample output voltages.

Component-level description:

IC39 is the digital-to-analog converter. Pins 15 and 10 are the left and right serial data inputs from the DSP Cards. Pin 12 is a gated 6.75MHz clock input from the DSP Cards that clocks in the serial data. Pins 11 and 14 receive a 128kHz clock input. Pins 17 and 8 are the left and right voltage outputs. The voltages change to the current sample value on the falling edge of the 128kHz clock. A full scale output is approximately 3.0 Volts peak. IC40 is a NAND gate that processes the bit clock and word clock supplied by the DSP Cards.

5. Reconstruction filter

The reconstruction filter is a 5th order elliptic filter with 90dB stopband attenuation at 113kHz. It filters the ultrasonic energy "images" present at the D/A output. There are two filters, one each for the left and right signals.

Component-level description:

The reconstruction filter is an active RC analog of a passive LC ladder filter, realized by resistors, capacitors, and frequency-dependent negative resistors (FDNRs). An FDNR is realized with a dual opamp, three resistors, and two capacitors. When the passive LC filter is transformed into an active RC filter, inductors become resistors, resistors become capacitors, and capacitors become FDNRs.

Each FDNR resonates with a series resistor to create a notch in the frequency response of the filter. This is analogous to a series LC circuit to ground. The notches are located in the "stopband" (beyond 15kHz).

The frequency response of the filter CANNOT be measured by applying a swept sine wave at the 8200 analog inputs. This is because the filter has bandwidth much larger than the analog-to-digital converter. The analog-to-digital converter band limits the input to 16kHz. To test the filter response, see step 3, page 4-23.

6. Output Buffer

The output buffer buffers the output of the reconstruction filters in three stages. The first stage of the output buffer is an inverting amplifier with gain programmable by the Control Card. The second stage is a programmable de-emphasis filter. The de-emphasis response is controlled by JFET switches. The third stage is a balanced floating line amplifier. It has a $30\Omega, \pm 5\%$ output impedance.

Component-level description:

The first stage is a programmable gain inverting amplifier formed by R170, R171, C132, IC12 and IC5a. IC12 is an 8-bit MDAC, which is a resistor ladder with a programmable resistance. The Control Card writes an eight-bit word to the chip which has a latch on board to store the value and set the resistance. The resistance determines the gain. The output at pin 1, IC5a feeds the second stage, a programmable de-emphasis filter. It is formed by IC5b, Q102, Q103, and the associated resistors and capacitors. Q103 and Q102 are JFET transistors used to switch C127 or C126 in or out of the circuit. If none of the JFETs are on, the circuit is a unity-gain inverting amplifier. With capacitor C127 in circuit, it becomes a first-order low-pass filter with a 75µs time constant. With capacitor C126 in circuit, it becomes a first-order low-pass filter with a 50µs time constant. The fourth stage is a balanced floating line amplifier formed by IC6 and IC13. The 412 opamp used in the balanced output module is a low-offset servo amplifier which centers the average DC level at the (+) and (-) outputs of the module around ground. The floating characteristic is achieved by complex cross-coupled positive and negative feedback between two 5532 opamps, and its operation is not readily explainable except by a detailed mathematical analysis. Opamps may be replaced; resistors are specially matched and should not be replaced.

7. Logic Circuitry

The Control Card reads and writes data from and to the Analog I/O Card. The control logic section decodes the address lines and enables the proper latch to be read from or written to.

Component-level description:

IC37 compares the slot address hard-wired into the Motherboard with the address lines A8-11. If the address lines match the slot address, IC37, pin 6 is asserted and partially enables the address decoder IC28. The address bits A3-5 feed IC28 to select one of eight output signals to assert low. The eight outputs are used to select various devices that the Control Card reads from and writes to. The output buffer MDACs and the input buffer's analog switches and latch require further decoding to be selected. This is accomplished by IC27, a three-to-eight decoder.

8. Clock logic

A crystal oscillator provides the timing reference for all signals related to the system sample rate. Divider circuitry produces the various signals used by the system. Logic is used to gate the sample rate clocks and serial input data. A latch provides for the control of a variety of functions.

A crystal oscillator circuit generates an 8.192MHz clock that provides the reference for all signals related to the sample rate of the system. The 8.192MHz is first divided by two to 4.096MHz. The 4.096MHz signal feeds the A/D, which divides that by two and produces a 2.048MHz clock. The 2.048MHz clock is divided further to generate the 128kHz, 64kHz, and 32kHz signals. Those signals are inverted to make the signals 128kHz and 64kHz. The signals 32kHz, 64kHz, and 128kHz are gated and buffered to make the signals 1 x frameclock, 2 x frameclock, and 4 x frameclock. These signals are gated "on" at the rising edge of the 128kHz signal just prior to the falling edge of the 32kHz signal. This is necessary because any one of these signals can be used by the DSP Cards to generate interrupts on a falling edge and the first interrupt must occur simultaneously with all DSP chips. The 64kHz signal is also gated to make the signal IFRAME. IFRAME marks the start of sample words transmitted from the A/D to the DSP Cards. It is gated "on" so that two words of data are transmitted to the DSP Cards before they start processing.

Component-level description:

Y1, IC33a, and IC33b make up an 8.192MHz square wave oscillator. IC35a divides it to 4.096MHz. The A/D chip, IC20, divides it by two to 2.048MHz which feeds IC34. IC34, IC32, and IC31 are set up as dividers and produce clock signals down to the sample rate, 32kHz. IC41 and IC42a are used to create two control signals that drive IC43, a quad "AND" gate. The "AND" gates act as switches for signals that drive the DSP Cards. IC36 is a 74HC244 buffer that connects the sample rate clocks and the serial input data to the DSP Cards. The buffer is enabled by bit 2 of latch IC30. The Control Card writes to this latch and clears the bit if it selects the Analog I/O Card as the source of sample rate clocks and input data. IC30 also provides control of other circuits. Bit 1 is set high to start a DSP algorithm. Bit 3 is set high to select a $50\mu s$ de-emphasis. Bit 4 is set high to select a $75\mu s$ de-emphasis. Bit 7 is set high to select J.17 de-emphasis. Bit 8 is set high to calibrate the A/D chip.

Stereo Encoder Card

1. Overview

The 8200 Stereo Encoder Card combines the left and right processed audio signals into one composite signal. A single composite signal is needed to feed an external FM exciter for FM broadcast.

The composite signal is made up of four elements. The first two are the main channel and the subchannel. The main channel is the L+R baseband signal. The subchannel is the L-R signal, double-sideband suppressed-carrier modulated with a 38kHz subcarrier frequency. The third is the pilot tone. It is a 19kHz sine wave in phase with the 38kHz subcarrier. The fourth is the optional SCA subcarrier which must be generated externally with an SCA generator and connected to the 8200's SCA input.

There may be more than one SCA subcarrier in the frequency range of 57 to 100kHz in the baseband. For example, there might be a 57kHz subcarrier for digital paging or RDS, a 67kHz subcarrier, and 92kHz subcarrier.

The main channel, the subchannel, the pilot tone, and the SCA are added to form the composite signal. Two output buffers with separate level controls provides two composite outputs.

The subchannel would ideally be produced by an ideal multiplier circuit that multiplies the L–R signal by a 38kHz sine wave. The 8200's Hadamard-Transform Stereo Baseband Encoder closely approximates an ideal multiplier by a switching technique. The L–R signal is passed through two analog switches whose outputs are summed together. These switches are turned on and off by pulse trains produced by a Read Only Memory (ROM). The ROM controls the switches so that all harmonics of 38kHz prior to the 7th harmonic are cancelled. By comparison to a conventional switching modulator, performance requirements of the output low-pass filter (to remove harmonics above 98kHz) are greatly eased, and excellent separation and spurious rejection can be obtained from a relatively modest filter.

The stereo pilot tone is generated by multiplying a DC voltage by three individual pulse trains from the ROM with three analog switches. Harmonics up to the 14th are cancelled. The resulting waveform is passed through the same low-pass filter as the stereo subchannel, ensuring correct phasing between the pilot tone and stereo subcarrier. JFET switches driven by CMOS logic are controlled by the Control Card. The switches alter the circuitry to facilitate stereo/mono mode switching and to provide the two "test" modes, main-channel-to-subchannel crosstalk and subchannel-to-main-channel crosstalk.

2. Stereo Modulator

The L and R signals are applied to a differential amplifier, which produces the L–R signal. The L–R signal is applied to a buffer amplifier. This amplifier has a DC servo that eliminates virtually all the DC offset that might have accumulated in earlier circuitry. (DC offset must be eliminated because it otherwise translates into loss of subcarrier suppression after modulation.) The L–R buffer output is applied to two analog switches, which modulate the L–R signal by the subcarrier.

The L and R signals are summed together to form the L+R signal. The L+R signal is summed with the L-R signal and servoed. This servo forces the DC at the outputs of the analog switches to be equal to zero, further reducing any subcarrier leakage. A separation control adjusts the amplitude of the L+R signal, permitting the L+R and L-R to be mixed with equal gains, thus maximizing separation.

The analog switches effectively multiply their inputs by +1 or 0, depending on whether the switches are on or off. Thus, the L–R signal is multiplied not only by the subcarrier, but also by an average DC voltage. Therefore, a substantial undesired baseband L–R component appears at the output of the analog switches. This is cancelled by mixing L–R that is out-of-phase into the output of the switches. The sub-to-main crosstalk trimmer maximizes cancellation.

Equal (+) and (-) DC voltages are applied in parallel to three pairs of analog switches to generate the pilot tone. The amplitude of the pilot tone is determined by the DC voltage level. The pilot tone is turned off by reducing the DC voltage to zero.

High order harmonics generated in the switching process are eliminated by a fifth-order passive elliptic filter followed by a group delay corrector. The corrector group delay is adjusted with the 15kHz separation trimmer to maximize overall separation. Separation of 70dB is theoretically possible with this filter design.

The filter output is applied to two power buffers each capable of driving two 75Ω loads in parallel. The external SCA input is mixed into these buffers.

Component-level description:

The L and R signals are applied to differential amplifier IC1a. This produces the L–R signal which is buffered by IC1b. IC3a is a DC servo to remove DC offsets. CR1 and CR2 are clamping diodes to protect the analog switch IC10 from being driven beyond its ± 5 V range. In mono mode the switching signals S0 and S1 stay at 0V and thereby turn off the subchannel.

IC8a and IC8b provide (+) and (-) reference voltages for the pilot tone generator. These voltages are applied to analog switches within IC11 and IC12. When mono mode is selected, the "PILOTEN" signal at R48 changes from +5VDC to 0V and the pilot reference voltage is reduced to 0V. The pilot switching waveforms P0, P1, P2, and P3 applied to IC11 and IC12 are also removed in mono mode. The L and R signals are summed by inverting amplifier IC2a. The JFET Q9 is "on" in stereo mode and the amplifier has unity gain. In mono mode, Q9 turns off and the

amplifier gain increases by 6.9dB to use modulation headroom otherwise used by the subchannel and the pilot. JFETs Q2 and Q3 select the left or right signal as the source in mono mode. The output of IC2a is summed with the L–R signal by inverting amplifier IC2b. R37 adjusts the L+R gain to maximize separation. R35 adjusts the gain of the L–R signal to minimize sub-to-main crosstalk. IC4a is a DC servo that prevents DC from appearing at the outputs of analog switches IC10, IC11, and IC12.

L1, L2, C6-C11, and C25 form a passive fifth-order elliptic filter with a cutoff frequency of approximately 70kHz. This is buffered by non-inverting amplifier IC5 and applied to all-pass group-delay corrector IC6.

The stereo modulator output and externally generated SCA signal are summed into two separate output buffers. The first is made up by IC15 and IC16. IC16 is a special high slew rate power buffer which is located within the overall amplifier feedback loop. It isolates IC15 from the destabilizing effects of capacitive loads and also permits 75Ω loads to be driven without degradation. This line driver will drive up to 1.5V peak into $0.047\mu F$ in parallel with 37.5Ω before significant nonlinear errors (increases in spurious components as observed on a baseband spectrum analyzer) or linear errors (noticeable deterioration of baseline flatness at 15kHz in the separation test mode) are apparent. Output level is adjusted by varying the feedback resistor R66. The second output buffer made by IC26 and IC27 is functionally identical to the one just described.

3. Switching Waveform Generator

A crystal oscillator generates a clock signal that is divided to a lower frequency, which drives a counter. The counter addresses a Read Only Memory (ROM). The ROM's data outputs drive the analog switches synchronized to the subcarrier.

Component-level description:

Y1, IC24a, and IC24b form a 4.864MHz square wave oscillator. IC23a and IC23b divide this clock down to 1.216MHz which drives IC22, a dual binary counter. The four least significant bits of the counter output form an address for ROM IC31. The address counts from 0000B to 1111B and is then reset back to 0000B to repeat the process. The counter only provides half the word that addresses the ROM. The other four are provided by half the outputs of IC17, a latch. The Control Card writes to this latch. The four bits address different blocks of the ROM and control whether the pilot and subcarrier are on. IC18 (a latch) buffers the ROM data output and ensures that the signals appearing at the output are changing state in precise synchronism with the clock edges. This ensures high spectral purity of the subcarrier and pilot tone.

4. Mode Switching Logic

The 8200 Stereo Encoder operates in several modes. These modes are changed by altering the circuitry with a mechanical switch and various JFET switches. The microprocessor operating system sets the mode based upon three things: the state of the mechanical switch, the remote control interface status, and selections made by the user through the operating system. The 8200 Stereo Encoder has a manual switch that switches between three operating modes: operate, sub-to-main crosstalk, and main-to-sub crosstalk. The two latter are used only when making stereo performance verification measurements. When in the "operate" mode, there are three sub-modes possible: stereo, mono left, or mono right. These are changed by the remote control interface or by the user's selecting the sub-mode from the front panel operating system. Table 1 shows the state of each JFET switch in the system under all the operating modes and sub-modes.

Component-level description:

Switch S1a switches the right input to the sum and difference amplifiers IC1a and IC2a. The other half of the switch, S1b, switches one pole to 0V and leaves the other two poles to be pulled up to +5V. The Control Card reads the state of these three signals through the buffer IC21. That way, the Control Card knows which mode the user is selecting and can control the JFET switches properly. The Control Card sets the JFET switches by writing to latch IC17. The logic level outputs of IC17 drive the comparators on IC13 and IC14. The comparators' outputs are 0V or -15V to turn the JFET switches on or off, respectively. A +5V signal output from IC17 makes the comparator output -15V and thus turns the JFET switch off.

Table 1: JFET Switch States (Under Operating Modes and Sub-Modes)

		LFET	RFET	LGAIN	SUM FET	STM FET	DIF FET
	STEREO	ON	ON	ON	ON	ON	ON
OPERATE	MONO L	ON	OFF	ON	OFF	ON	OFF
	MONO R	OFF	ON	ON	OFF	ON	OFF
SUB-TO-MAIN		OFF	OFF	OFF	ON	OFF	ON
MAIN-7	O-SUB	ON	ON	ON	ON	ON	ON

5. Composite Metering

The composite signal prior to the output buffers is applied to a peak detector circuit. Its output feeds an 8-bit analog-to-digital converter which measures the signal level. The Control Card reads the level value from the analog-to-digital converter and translates the data to the front panel LCD display.

Component-level description:

IC32 is an 8-bit analog-to-digital converter. R133, C92, and CR20 create a 1.2V reference used by IC32 to determine the input level seen at pin 16. IC32 has eight data outputs that are connected to the Control Card. The outputs are normally tri-stated and are enabled by the signal at pin 2.

DSP Cards

1. Overview

The DSP Cards use general purpose DSP chips that use software programs to implement digital signal processing algorithms. The algorithms filter, compress, and limit the audio signal. Each board has three DSP chips on it. Each DSP chip has two FIFO buffer circuits associated with it: one for transmitting data to another DSP chip, the other for receiving data from another DSP chip. The DSP chips are cascaded with the FIFO circuits between them to interface the DSP chips. The DSP chips are cascaded so that the first generates output to the second which generates output to the third. The first receives input from the third DSP chip on a separate DSP Card. The third DSP chip generates output to the first DSP chip on a separate DSP Card. The DSP chip communication is through a FIFO interface. The FIFO is 24 bits wide and 16 words deep. The FIFO is dual ported so that reads and writes can occur simultaneously. The control logic interfaces the DSP chips and the interrupt logic with the Control Card. The Control Card reads from and writes to the DSP chips through the DSP chip host ports. The board has two latches on it that the Control Card writes to. The latch output bits are used to reset the DSP chips and to control how the DSP chips are synchronized to the sample rate clocks.

Component-level description:

IC9, IC15, and IC30 are the DSP chips. The chips can be ruined by static discharge or by damage to their delicate pins.

2. FIFO Buffers

A FIFO buffer is used by a DSP chip to write data to another DSP chip. There are three FIFO buffers on a DSP Card. Each FIFO buffer is paired with a DSP chip. The FIFO/DSP pairs are cascaded in a line. The first FIFO is written to by a DSP chip on a previous DSP Card, if there is one. The first DSP chip reads from the first FIFO and writes to the second FIFO. The second DSP chip reads from the second FIFO and writes to the third FIFO. The third DSP chip reads from the third FIFO and writes to the first FIFO on the next DSP Card, if there is one. A FIFO buffer is made up of three 74HC373 latches and six 74HC40105 4X16 FIFOs. The 74HC373s latch the data from the DSP chip writing to the FIFO buffer. The 74HC373 outputs are shifted into the 74HC40105 FIFO chips. The DSP chip that reads from the buffer reads the data from the 74HC40105 FIFO chips and shifts it out.

3. Control Logic

The control logic decodes the address lines and selects the proper device for the Control Card to read from or write to.

Component-level description:

IC45 is an address magnitude comparator used to decode the board address. It compares the address bits A8-11 with the slot address from the Motherboard. If they match, the comparator output, pin 6, partially enables IC42, a 74HC138 3-to-8 line address decoder. It decodes the address bits A3-5 to select one of three DSP chips or one of two latches. IC42 is fully enabled when the Control Card asserts the E signal high at pin 6. When that happens, one of its eight outputs goes low and provides a control signal to the device being addressed.

4. DSP Reset and Interrupt Logic

The Control Card writes to two latches on the DSP Card that reset the DSP chips and control four multiplexers. The multiplexers select which of three signals is connected to the IRQB pin on each DSP chip. The IRQB pin is an interrupt request pin that is negative edge-triggered. When the DSP chip detects an interrupt, it runs its algorithm on the current audio sample. The multiplexers are necessary because the algorithms are designed to run at one of three rates: 32kHz, 64kHz, or 128kHz.

Component-level description:

IC44 is the reset control latch. It is a 74HC373 transparent latch. It is written to by the Control Card to initiate hardware resets on the DSP chips. Only the four least significant bits are used. When IC4 is not being written to, its outputs are tri-stated and pulled high by the pull-up resistors R2–5. Three of the outputs are connected to the reset pin on each DSP chip which is active low.

When the Control Card writes to the reset latch, IC44, the outputs are briefly enabled and the DSP chips will be reset if the Control Card has written a low logic level. The outputs of IC44 also connect to inverters on IC41. The inverted signals connect to pin 1 on IC36, 37, 38 and 40. If the Control Card resets the DSP chips, pin 1 on IC36, 37, 38 and 40 goes high and tri-states pin 7 on IC36, 37, 38 and 40. This is necessary to make the DSP chips boot properly. The purpose of IC36, 37, 38 and 40 is described below. The three signals 1 x frameclock, 2 x frameclock, and 4 x frameclock are 32kHz, 64kHz, and 128kHz clock signals respectively. ICs 36, 37, 38 and 40 are 74HC253B multiplexers that select which of the three frameclock signals interrupt each DSP chip. IC43 is a 74HC373 latch that supplies four pairs of logic signals to address the multiplexers. The address signals are applied to pins 14 and 2 of the 74HC253B. The selected input is output at pin 7. IC36's output is not connected to anything and is a spare IC.

Control Card

1. Overview

The Control Card processes and executes all user initiated requests to the system. This includes changes to the DSP processing such as program change and modifications through the front panel keyboard, the serial port, and the eight remote contact closures. The Control Card also provides the housekeeping functions like the real time clock, gain reduction and input/output metering, analog signal path setup levels, and security password functions.

2. Power Monitoring Circuit

The +5 volt supply voltage is monitored to ensure it is within the correct operating range.

The system \overline{RESET} is activated if the +5V supply drops below the minimum acceptable voltage. Battery voltage is also monitored to ensure it is above its minimum operating voltage.

Component-level description:

Voltage comparator IC11 provides the system reset function. The 5-volt source is divided by resistors R202 and 203 and compared to the 1.2V voltage reference created by R204 and CR200. When the 5V line is above the 4.8V minimum operating voltage, timing network R210 and C207 will begin to charge to 5V. Inverters IC13c and IC13d buffer the signal and \overline{RESET} goes high, enabling the Z180 \overline{RESET} input.

Battery voltage is buffered by IC11a with stabilizing network R208 and C206, divided by R209 and R211, and compared to the 1.2V reference by IC11b. The output of IC11b goes low when the battery voltage falls below 2.4V. This signal

is read periodically by the Z180 through buffer IC12 to detect acceptable battery voltage.

CR201 and CR202 switch the Vbat line between 5V and battery 3V to retain real time clock and RAM data retention during mains voltage outages.

Security Reset Switch is debounced by R216 and C208 and buffered by IC13e.

This signal is read periodically by the Z180 through buffer IC12 to detect if security should be disabled.

3. Microprocessor and Input/Output Circuit

A Z-180 microprocessor runs the software required to provide the functions described above. Crystal Y100 connected to the XTAL port of the Z180 oscillates at 12.288MHz and is internally divided down to 6.144MHz to provide the system clock frequency.

Module M1 contains control software for the Z180. IC15 and IC9 decode Z180 memory addresses to select M1 to access instructions to execute. User presets and system setup information are stored in both RAM IC22 and the module to enable board swapping without losing data.

IC10 decodes I/O addresses to select real time clock circuitry, host port buffers IC19, IC26, and IC20, remote contact closures, ROM.

4. Real Time Clock Circuit

IC1 with crystal oscillator Y101 provides time, date and alarm functions. Vbat is used for supply voltage to allow continued operation when AC mains power is removed. The Z180 accesses IC1 with decoder IC10 and timing circuitry IC3, IC4, IC6, and IC8. IC2 is a data buffer and IC14 is an address latch between the Z180 and IC1. Pin 8 of IC3 goes low for read and pin 11 of IC3 goes low for write operations. A Z180 interrupt is generated by IC1 every 0.5 second with pin 19 going low. The Z180 will then read the current data from IC1. Pin 22 of IC1 and R108 with C102 is held high by Vbat. This port will go low and is then internally latched should Vbat go low, interrupting timing updates.

5. Host Port Interface

The Z180 communicates to the Analog I/O, Stereo Encoder, and the DSP Cards through the host port. IC19, IC26, and IC20 buffer the address and data bus with control signals HOST, E, RD, and WR. The host port can be selected as a standard I/O mapped device with pin 14 of IC10.

The Z180 sends the signal processing software required by the DSP Cards through the host port. IC10 pin 9 selects buffers IC19, IC26, and IC20 and address generating components IC5, IC6, IC7, and IC8. The address generating circuit modifies the port address and allows speedier memory transfers for DSP function changes like recalling a different processing structure.

Display Board

1. Overview

The Display Board supports the front panel keys, LCD display, and rotary encoder. The keys are configured in a switch matrix circuit controlled by the Control Card. The LCD display has its own special purpose driver IC, RAM, and address and data buffers and support circuitry. The rotary encoder circuit includes filtering components, a pulse counter and buffers.

2. Switch Matrix

The switch matrix is configured as two columns and six rows. Decoder IC15 selects latch IC16 to drive one of the two columns low. Decoder IC15 then selects buffer IC17 which reads the six rows to determine if one or more of the switches in that column are closed. If no switches are closed, pull-up resistors R204D-R204I drive the buffer inputs to +5 volts. The HELP key has a dedicated row so that it can be read in combination with any other key.

3. Rotary Encoder

The rotary encoder provides two pulsed outputs when it is rotated. The outputs are out of phase so that direction can be determined. The Z180 on the Control Card reads the switch circuitry approximately every 4 milliseconds to check if any switches or the rotary encoder have been turned.

Component-level description:

IC9a and IC9b buffer and invert the rotary encoder outputs. Flip-flop IC8a is clocked and the output goes low to indicate the encoder has been turned. IC9c, IC9d, IC9e, and IC9f with associated resistors and capacitors provide filtering so that the directional phase information can be determined. The output of IC8b will go high if the encoder is turned to clockwise and will go low if turned counterclockwise. The output is read by buffer IC17. Pulse counter IC19 counts how far the encoder was turned. IC19s output is buffered by IC18.

4. Display circuit

The LCD display uses a special purpose display driver to interface to the LCD and to refresh the display data. The Z180 microprocessor on the Control Card writes display data to a static RAM on the Display Board. The display driver IC uses this data to refresh and update the LCD. Data and address latches allow the Z180 and the display driver to access the current display data.

Component-level description:

Display driver IC4 uses crystal Y100 to generate its clock frequency. IC4 is selected by the Control Card with signal DISPLAY. IC4 is initialized on power-up. All updates to the LCD are done through RAM IC3 with data and address latches IC1, IC2, IC13, and IC14. IC11c, IC11d, and IC10a decode the READ, WRITE, and MDISPLAY signals to determine if the Control Card is requesting a read or write operation. Asynchronous RAM access between the Control Card and LCD driver IC4 is accommodated with logic circuitry IC5, IC6, IC7, IC11, and IC12.

5. LCD display



The LCD is a 128-by-256-dot graphics display incorporating a florescent backlight. Screen saver circuitry for the backlight helps extend its lifetime. The backlight's voltage source is a 300V 30kHz AC signal and requires caution to avoid user injury. All components described below other than the LCD unit reside on the Display Board.

Component-level description:

The LCDs power and control signals connect to the Display Board with a 14-pin connector. The LCD unit consists of the display and an integral control circuit board containing the driver circuitry for each screen element. The output of the front panel CONTRAST control provides the LCD operating voltage of approximately -8 volts. Adjusting this voltage will change the optimum viewing angle of the LCD. The backlight's power is generated by power inverter A100. The inverter's +12 volt power source is switched on or off with Q100, R100, and R101 by bit 7Q of latch IC16. Diode CR100 protects transistor Q100 against reverse bias voltages.

Power Supply

The power supply converts an AC line voltage input to various power sources used by the 8200. It consists of three main parts: the Regulator Board, the Finger Board, and the Switching Power Supply. The Regulator Board circuitry supplies power to the 8200 analog circuits. The Finger Board is used to connect the power signals to the Motherboard. The switching power supply supplies power to the 8200 digital circuits. Other than a full replacement, the switching power supply is not intended to be serviced.

Component-level description:

L1 is a power line filter that filters out RFI. T1 is a conventional power transformer used to step down the input voltage for the ± 15 VDC supply. S2 is a switch used to select between a 115V or 230V power source. CR1 is a full wave rectifier. C1, C2, C5, and C6 smooth and condition the rectified voltage signal for input to the voltage regulators, IC1 and IC2. The regulators output the +15V and -15V sources used to power the analog circuits in the 8200.

The Finger Board holds the test points and bypass capacitors before connecting the power signals to the Motherboard.

Input Filter Board

The Input Filter Board serves as a mount for the audio input and output connectors, the AES/EBU connectors, the composite outputs and the SCA input. It provides RFI filtering for all the above inputs and outputs.

D-Connector Board

The D-Connector Board holds the connectors and circuitry for the RS-232, RS-422, and remote control interfaces.

Component-level description:

The RS-232 interface is comprised of J1, IC1, and IC2. J1 is a 9-pin D-connector. IC1 and IC2 provide logic circuitry to interface the RS-232 signals with the microprocessor on the Control Card.

The RS-422 interface consists of J2, IC3, IC4 and associated resistors. J2 is a 9-pin D-connector. IC3 and IC4 provide logic circuitry to interface the RS-422 signals with the microprocessor on the Control Card.

J3 is a 25-pin D-connector that connects the remote control input signals. The associated resistors and capacitors filter out RFI from the input signals. The associated optoisolators (e.g. IC12) isolate the inputs from the detector circuitry on the Control Card. The associated diodes prevent the optoisolators from breaking down under a reverse bias.

S1 is the ground lift switch used to connect or lift circuit ground from chassis ground.

Parts List

Parts are listed by ASSEMBLY, then by TYPE, then by REFERENCE DESIGNATOR. Widely used common parts are not listed; such parts are described generally below (examine the part to determine exact value). See the following assembly drawings for locations of components.

SIGNAL DIODES, if not listed by reference designator in the following parts list, are:

Orban part number 22101-000, Fairchild (FSC) part number 1N4148, also available from many other vendors. This is a silicon, small-signal diode with ultra-fast recovery and high conductance. It may be replaced with 1N914 (BAY-61 in Europe).

(BV: 75V min. @ Ir = 5μ A; Ir: 25nA max. @ Vr = 20V; Vf: 1.0V max. @ If = 100mA; trr: 4ns max.) See Miscellaneous list for ZENER DIODES (reference designator VRxx).

RESISTORS should only be replaced with the same style and with the exact value marked on the resistor body. If the value marking is not legible, consult the schematic or the factory. Performance and stability will be compromised if you do not use exact replacements.

Unless listed by reference designator in the following parts list, you can verify resistors by their physical appearance:

Metal film resistors have conformally-coated bodies, and are identified by five color bands or a printed value. They are rated at $^{1}/_{8}$ watt @ 70° C, $\pm 1\%$, with a temperature coefficient of 100 PPM/ $^{\circ}$ C. Orban part numbers 20038-xxx through 20045-xxx, USA Military Specification MIL-R-10509 Style RN55D. Manufactured by R-Ohm (CRB-1/4FX), TRW/IRC, Beyschlag, Dale, Corning, and Matsushita.

Carbon film resistors have conformally-coated bodies, and are identified by four color bands. They are rated at $\frac{1}{4}$ watt @ 70°C, $\pm 5\%$. Orban part numbers 20001-xxx, Manufactured by R-Ohm (R-25), Piher, Beyschlag, Dale, Phillips, Spectrol, and Matsushita.

Carbon composition resistors have molded phenolic bodies, and are identified by four color bands. The 0.090 x 0.250 inch (2.3 x 6.4 mm) size is rated at $^{1}\!\!/_{4}$ watt, and the 0.140 x 0.375 inch (3.6 x 9.5 mm) size is rated at $^{1}\!\!/_{2}$ watt, both \pm 5% t numbers 2001x-xxx, USA Military Specification MIL-R-11 Style RC-07 ($^{1}\!\!/_{4}$ watt) or RC-20 ($^{1}\!\!/_{2}$ watt). Manufactured by Allen-Bradley, TRW/IRC, and Matsushita.

Cermet trimmer resistors have $\frac{3}{8}$ -inch (9 mm) square bodies, and are identified by printing on their sides. They are rated at $\frac{1}{2}$ watt @ 70° C, = $\pm 10\%$, with a temperature coefficient of 100 PPM/°C. Orban part numbers 20510-xxx and 20511-xxx. Manufactured by Beckman (72P, 68W- series), Spectrol, and Matsushita.

Obtaining Spare Parts

Special or subtle characteristics of certain components are exploited to produce an elegant design at a reasonable cost. It is therefore unwise to make substitutions for listed parts. Consult the factory if the listing of a part includes the note "selected" or "realignment required."

Orban normally maintains an inventory of tested, exact replacement parts that can be supplied quickly at nominal cost. Standardized spare parts kits are also available. When ordering parts from the factory, please have available the following information about the parts you want:

Orban part number Reference designator (e.g., C3, R78, IC14) Brief description of part Model, serial, and "M" (if any) number of unit — see rear-panel label

To facilitate future maintenance, parts for this unit have been chosen from the catalogs of well-known manufacturers whenever possible. Most of these manufacturers have extensive worldwide distribution and may be contacted through their local offices. Addresses for each manufacturer's USA headquarters are given on page 6-44.

REF DES	DESCRIPTION	ORBAN P/N	VEN (1)	VENDOR <u>P/N</u>	ALTERNATE VENDORS (1)	<u>NOTES</u>
ANALOG B	OARD ASSEMBLY					

Capacitors

C98,99	Ceramic, Disc, 1KV, 10%; 12pF	21112-012	MEP	120K20S2L	
C100-102	Polypropylene, 50V, 1%; 4700pF	21701-247	NOB	CQ15P1H472FPP	WES
C103-107	Met. Polyester, 63V, 5%; 0.1uF	21442-410	MAL	168104J63A	WIM
C108,109	Polypropylene, 50V, 1%; 4700pF	21701-247	NOB	CQ15P1H472FPP	WES
C110	Met. Polyester, 63V, 5%; 0.1uF	21442-410	MAL	168104J63A	WIM
C111-113	Polypropylene, 50V, 1%; 4700pF	21701-247	NOB	CQ15P1H472FPP	WES
C114	Mica, 500V, 1%; 2400pF	21022-224	CD	CD19-FD242F03	SAN
C115-118	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C119,120	Polypropylene, 50V, 1%; 4700pF	21701-247	NOB	CQ15P1H472FPP	WES
C121	Mica, 500V, 1%; 2400pF	21022-224	CD	CD19-FD242F03	SAN
C122	Mica, 500V, 1%; 1500pF	21022-215	CD	CD19-FD152F03	SAN
C123	Mica, 500V, 1%; 1000pF	21022-210	CD	CD19-FD102F03	SAN
C124,125	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C126	Mica, 500V, 1%; 1000pF	21022-210	CD	CD19-FD102F03	SAN
C127	Mica, 500V, 1%; 1500pF	21022-215	CD	CD19-FD152F03	SAN
C128,129	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C130,131	Met. Polyester, 63V, 5%; 0.1uF	21442-410	MAL	168104J63A	WIM
C132,133	Mica, 500V, +1/2pF -1/2pF; 33pF	21017-033	CD	CD15-CD330D03	SAN
C134,135	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C136,137	Met. Polyester, 100V, 10%; 0.0056uF	21441-256	WES	160C 562K630	SIE,WIM
C200,201	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C202,203	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CRL	DD-102	MUR
C213	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C216	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CRL	DD-102	MUR
C217,218	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C220	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C224-227	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C300-303	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C304	Met. Polyester, 100V, 10%; 0.01uF	21441-310	WES	160C 103K630	SIE,WIM
C305,306	Mica, 500V +1/2pF -1/2pF; 39pF	21017-039	CD	CD15-CD390D03	SAN
C307,308	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM
C400	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	ECE-A1EV101S	
C401	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050B	KEM

FOOTNOTES:

- See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication
 Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

Orban Model 8200 Analog Board Assembly - Capac

REF				VEN			ALTERN	ΔΤΕ	
DES	DESCRIPTION	0	RBAN P/N	(1)	VE	ENDOR P/N	VENDOR		NOTES
		_ l -							
	/ · · · · · · · · · · · · · · · · · · ·								
Capacitor	rs (continued)								
C402	Alum., Radial, 25V, -20% +100%; 100uF		21206-710	PA	·Ν	ECE-A1EV101S			
C403-408	Monolythic Ceramic, 50V, 20%; 0.1uF		21123-410	SF	PR	1C25 Z5U104M050I	B KEM		
C410-412	Monolythic Ceramic, 50V, 20%; 0.1uF		21123-410	SF	PR	1C25 Z5U104M050I	B KEM		
C413	Alum., Radial, 25V, -20% +100%; 100uF		21206-710	PA	·Ν	ECE-A1EV101S			
C414	Monolythic Ceramic, 50V, 20%; 0.1uF		21123-410	SF		1C25 Z5U104M050I	B KEM		
C415,416	Alum., Radial, 25V, -20% +100%; 100uF		21206-710	PA		ECE-A1EV101S			
C596-601	Monolythic Ceramic, 50V, 20%; 0.1uF		21123-410	SF		1C25 Z5U104M050I			
C617	Ceramic Disc, 1KV, 10%; 0.001uF		21112-210	CF		DD-102	MUR		
C801	Polypropylene, 50V, 2.5%; 100pF		21702-110		DВ	CQ15P1H101GPP	WES,V		
C804-806	Polypropylene, 50V, 2.5%; 100pF		21702-110		DΒ	CQ15P1H101GPP	WES,V	VIM	
C807-810	Ceramic, 100V, 5%; .01uF		21125-310		JR	RPE113C0G103J11			
C811,812	Tantalum, 20V, 10%; 10uF		21305-610	SF		196D 106X9020JA1			
C813,814	Ceramic, 50V, 5%; 4700pF		21124-247	CF		CN30C472J245	KEM		
C815	Tantalum, 20V, 10%; 10uF		21305-610	SF		196D 106X9020JA1			
C817-820	Tantalum, 20V, 10%; 10uF		21305-610	SF		196D 106X9020JA1		000	
C821,822	Ceramic Disc, 25V, 20%; 0.01uF		21106-310	CF	ΚL	UK25-103	MUR,	SPR	
<u>Diodes</u>									
CR400,401	Diode, Rectifier, 400V, 1A		22201-400	M	TC	1N4004	MANY		
Integrated	d Circuits								
IC1	Linear, Dual Opamp		24207-202	SI	G	NE5532N	TI,EXF	}	
IC2	Quad SPST Switches		24728-302	ΑĽ)	ADG222			
IC3	Audio Preamp		24727-302	ΑĽ)	SSM-2017			
IC4,5	Linear, Dual Opamp		24206-202	TI		TL072CP	MOT		
IC6	Linear, Dual Opamp		24209-202	N/	١T	LF412CN			
IC7	Quad Comparator		24710-302	N/	١T	LM339			
IC8,9	Linear, Dual Opamp		24207-202	SI	G	NE5532N	TI,EXF	₹	
IC10	Linear, Dual Opamp		24206-202	TI		TL072CP	MOT		
IC11,12	Digital, Multiplying DAC		24714-302	ΑĽ)	AD7524JN			
IC13	Linear, Dual Opamp		24207-202	SI	_	NE5532N	TI,EXF	₹	
IC14	Quad SPST Switches		24728-302	ΑĽ		ADG222			
IC15	Audio Preamp		24727-302	ΑĽ)	SSM-2017			
IC16,17	Linear, Dual Opamp		24206-202	TI		TL072CP	MOT		
FOOTNOTES	s·								SPECIFICATIONS
(1) See pa	ge 6-26 for Vendor abbreviations	(4)				uired if replaced,			REPLACE
	rnate Vendors known at publication	. ,		escriptio	n ai	nd/or Alignment		OPTIMA	DD-FM 8200
	part is specially selected from ed, consult Factory		Instructions						Board Assembly - Capac
Partiist	od, odriodic i dotory								des, Integrated Circuits.

REF	DESCRIPTION	OB	DANI D/NI	VEN	\/⊏	NDOD D/N	ALTERNA		NOTES
DES	DESCRIPTION	UK	BAN P/N	<u>(1)</u>	VΕ	NDOR <u>P/N</u>	VENDOR	(<u>)</u>	NOTES
Integrated	d Circuits (continued)								
	<u>-</u> <u>-</u>	,	24740 202	N I A	.Τ	LM220			
IC18	Quad Comparator		24710-302	NA		LM339			
IC19	Digital, Octal Flip-Flop		24553-302	NA		MM74HC374			
IC20	Digital, A/D Converter		24730-000	AD		AD1879	TI NACE	-	
IC21	D.C. Regulator, 5V Negative		24308-901	NΑ		LM79M05C	TI,MOT		
IC22 IC23	D.C. Regulator, 5V Positive Linear, Dual Opamp		24307-901	NA NA		LM78M05C	TI,MOT	ı	
			24209-202			LF412CN	MOT		
IC24-26	Linear, Dual Opamp		24206-202	TI		TL072CP	MOT		
IC27,28	Digital, Line Decoder		24569-302	NA		MM74HC138N	TI		
IC29	Digital, Buffer		24568-302	NA NA		MM74HC244N	TI		
IC30	Digital, Octal Flip-Flop		24553-302			MM74HC374	elC		
IC31,32	Digital, Dual Flip-Flop		24567-302	RC		CD74HC74N	SIG		
IC33	Digital, Hex Inverter		24572-302	NA DC		74HC04N	TI		
IC34,35	Digital, Dual Flip-Flop		24567-302	RC		CD74HC74N	SIG		
IC36	Digital, Buffer		24568-302	NA		MM74HC244N	TI		
IC37	Digital, Magnitude Comparator		24574-302	SIC		74HC85N	TI		
IC38	Linear, Dual Opamp		24206-202	TI		TL072CP	MOT		
IC39	Digital, Audio DAC		24824-302	AD		AD1864	Τ.		
IC40	Digital, NAND Gate		24585-000	RC		CD74HC132E	TI		
IC41,42	Digital, Dual Flip-Flop		24567-302	RC		CD74HC74N	SIG		
IC43	Digital, AND Gate		24576-302	RC		CD74HC08	TI E. (5)		
IC44	Linear, Dual Opamp	2	24207-202	SIC	ن	NE5532N	TI,EXR	(
Miscellan	neous								
Y1	Crystal; 8.192 MHz	2	28052-001	NE	L	NE-18-8.192MHz			
Resistors	<u>i</u>								
R109a,b	Resistor Set, MF; 2.00K	2	28520-002	OF	RB				3
R111a,b	Resistor Set, MF; 2.00K	2	28520-002	OF	RB				3
R126a,b	Resistor Set, MF; 2.00K	2	28520-002	OF	RB				3
R128a,b	Resistor Set, MF; 2.00K	2	28520-002	OF	RB				3
R136a,b	Resistor Set, MF; 13.3K/10.2K	2	28522-003	OF	RB				3
R139a,b	Resistor Set, MF; 4.64K/4.53K	2	28522-005	OF	RB				3
R146a,b	Resistor Set, MF; 13.3K/10.2K		28522-003	OF	RB				3
R148a,b	Resistor Set, MF; 4.53K/3.01K	2	28522-004	OF	RB				3
FOOTNOTES	S :								SPECIFICATIONS
	ge 6-26 for Vendor abbreviations	(4)	Realignment i	may be	requ	uired if replaced,			REPLACE
(2) No Alternate Vendors known at publication			see Circuit De			nd/or Alignment		 OPTIMOD	_
	part is specially selected from	1	Instructions						o-FM 8200 Pard Assembly - Integr
part list	ted, consult Factory								ellaneous, Resistors.

REF DES	DESCRIPTION	ORBAN P/N	VEN (1)	VENDOR <u>P/N</u>	ALTERNATE VENDORS (1)	NOTES
Resistor	(continued)					
R153a,b	Resistor Set, MF; 13.3K/10.2K	28522-003	OR	В		3
R156a,b	Resistor Set, MF; 4.64K/4.53K	28522-005	OR	В		3
R163a,b	Resistor Set, MF; 13.3K/10.2K	28522-003	OR	В		3
R165a,b	Resistor Set, MF; 4.53K/3.01K	28522-004	OR	В		3
Transisto	<u>rs</u>					
Q100-105	Transistor, JFET/N	23406-101	NA	Г J113	SIL	
Q200-203	Transistor, JFET/N	23402-101	NA	Г J108		
Q400-402	Transistor, Signal, PNP	23002-101	МО	T 2N4402	FSC	
CONTROL	BOARD ASSEMBLY					
Capacito	rs					
C100,101	Mica, 500V, +1/2pF -1/2pF; 22pF	21017-022	CD	CD15-CD220D03	SAN	
C102,103	Mica, 500V, 1%; 100pF	21018-110	CD		SAN	
C200-202	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	N ECE-A1EV101S		
C203-205	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPF		B KEM	
C206	Alum., Radial, 50V, -20% +100%; 47uF	21208-647	SPF	R 502D 476G050CD1	C PAN	
C207	Alum., Radial, 63V, -20% +100%; 2.2uF	21209-522	SPF	R 502D 225G063BB1	C PAN	
C208	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CRI	L DD-102	MUR	
C209	Alum., Radial, 63V, -20% +100%; 2.2uF	21209-522	SPF	R 502D 225G063BB1	C PAN	
C210	Ceramic Disc, 25V, 20%; 0.1uF	21106-410	CRI	L UK25-104	MUR	
C211-214	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPF	R 1C25 Z5U104M050	B KEM	
C300-311	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPF	R 1C25 Z5U104M050	B KEM	
C313	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPF	R 1C25 Z5U104M050	B KEM	
C316,317	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPF	R 1C25 Z5U104M050	B KEM	
Diodes						
CR200	Diode, Voltage Reference	22081-112	NA	Γ LM385	MOT	
CR201,202	Diode, Signal, Hot Carrier	22102-001	HP	HP5082-2800	MANY	

FOOTNOTES:

- See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication
 Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200

Analog Board Assembly - Resis Control Board Assembly - Capa

REF				VEN		ALTERN	ATE
DES	DESCRIPTION	0	RBAN P/N	<u>(1)</u>	VENDOR P/N	VENDO	
							·
Integrate	d Circuite						
IC1	Digital, RAM, RTA		24809-302	MC			
IC2	Digital, Tranceiver		24570-302	NA		TI	
IC3	Digital, Quad OR Gate		24571-302	NA		TI	
IC4	Digital, Dual Flip-Flop		24567-302	RC		SIG	
IC5	Digital, Binary Counter		24583-302	RC			
IC6	Digital, Hex Inverter		24572-302	NA		TI	
IC7	Digital, AND Gate		24576-302	RC			
IC8	Digital, Quad OR Gate		24571-302	NA		TI —:	
IC9,10	Digital, Line Decoder		24569-302	NA		TI	
IC11	Quad Comparator		24710-302	NA			
IC12	Digital, Buffer		24568-302	NA	-	TI	
IC13	Digital, Schmitt Trigger Inverter		24582-302	MC	=		
IC14	Digital, Buffer		24568-302	NA		TI	
IC15	Digital, Line Decoder		24569-302	NA		TI	
IC16	Digital, Hex Inverter		24572-302	NA		TI	
IC17	Digital, Schmitt Trigger Inverter		24582-302	MC	=		
IC18	Digital, MPU		24813-302	ZI	Z8018006PSC		
IC19	Digital, Buffer		24568-302	NA	_	TI	
IC20	Digital, Tranceiver		24570-302	NA		TI	
IC22	Digital, RAM		24811-302	TC	S TC5565APL15L		
IC25,26	Digital, Buffer		24568-302	NA	T MM74HC244N	TI	
Miscellan	<u>eous</u>						
None	Battery Holder, Coin Cell		28031-000	KE	Y 106		
B200	Coin Cell, Lithium; 3V		28041-000	DL	IR DL2032	GE	
Y100	Crystal; 12.288 MHz		28055-000	RA	L A-12.288-5		
Y101	Oscillator; 32.768 KHz		28056-000	NE	L HS426-32.768MI	Hz	
Resistors	:						
R100,101	Resistor Network, SIP; 100K		20221-101	BE	K L10-1C104		
R105-107	Resistor Network, SIP; 100K		20221-101	BE			
R200	Resistor Network, SIP; 100K		20221-101	BE			
R215	Resistor Network, SIP; 100K		20221-101	BE	K L10-1C104		
FOOTNOTE	S:						SPECIFICATIONS
(1) See pa	ge 6-26 for Vendor abbreviations	(4)			required if replaced,		REPLACE
				escriptio	n and/or Alignment		OPTIMOD-FM 8200
	part is specially selected from ed, consult Factory		Instructions				Control Board Assembly - Integr
Partilisi	ed, consult actory						Miscellaneous, Resistors.

REF DES	DESCRIPTION	ORBAN P/N	VEN (1) V	ENDOR <u>P/N</u>	ALTERNATE VENDORS (1)	NOTES
Switches						
S1	Switch, MOM.; SPST	26302-001	SCH	D6-01-01		
D-CONNEC	TOR BOARD ASSEMBLY					
Capacito	rs					
C1-16	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CRL	DD-102	MUR	
C17	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	ECE-A1EV101S		
C18,19	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050	B KEM	
C20	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	ECE-A1EV101S		
C21,22	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050)B KEM	
C23	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	ECE-A1EV101S		
C24,25	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050)B KEM	
Diodes						
CR1-8	Diode, Rectifier, 400V, 1A	22201-400	MOT	1N4004	MANY	
Inductors						
L1	Inductor, RF Choke; 7uH	29501-004	OHM	Z-50		(2)
Integrate	d Circuits					
IC1	Digital, Quad Line Driver	24661-302	NAT	DS14C88N		
IC2	Digital, Quad Line Receiver	24662-302	NAT	DS14C89A		
IC3	Digital, Quad Line Drivers	24717-302	MOT	SN75174N		
IC4	Digital, Quad Line Receivers	24718-302	MOT	SN75175N		
IC5-12	Optoisolator, NPN	25003-000	SIE	SFH-601-1		
Miscellan	neous					
FB1-18	Ferrite Bead, with wire	29506-001	FR	2743001111		
Switches						
S1	Switch, Slide; SPDT	26142-000	ITW	124-230-020		

FOOTNOTES:

See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication

Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200

Control Board Assembly - Switc D-connector Board Assembly - (Inductors, Integrated Circui Switches.

Capacito	<u>rs</u>						
C1,2	Alum., Radial, 63V, -20% +100%; 22uF		21209-622	SPR	502D 226G063CC1C	PAN	
C3-40	Monolythic Ceramic, 50V, 20%; 0.1uF		21123-410	SPR	1C25 Z5U104M050B	KEM	
Integrate	d Circuits						
C1	Digital, NOR Gate		24581-302	SIG	74HC02N	TI	
C2	Digital, Quad OR Gate		24571-302	NAT	MM74HC32N	TI	
C3	Digital, Latch		24577-302	SIG	74HC373N	TI	
C4-6	Digital, Register		24578-302	SIG	74HC40105N		
C7	Digital, NOR Gate		24581-302	SIG	74HC02N	TI	
C8	Digital, Quad OR Gate		24571-302	NAT	MM74HC32N	TI	
C9	Digital, DSP		24835-000	MOT	DSP56001FC27		
C10,11	Digital, Latch		24577-302	SIG	74HC373N	TI	
C12-14	Digital, Register		24578-302	SIG	74HC40105N		
C15	Digital, DSP		24835-000	MOT	DSP56001FC27		
C16	Digital, NOR Gate		24581-302	SIG	74HC02N	TI	
C17	Digital, Quad OR Gate		24571-302	NAT	MM74HC32N	TI	
C18-20	Digital, Register		24578-302	SIG	74HC40105N		
C21	Digital, Latch		24577-302	SIG	74HC373N	TI	
C22-24	Digital, Register		24578-302	SIG	74HC40105N		
C25	Digital, Latch		24577-302	SIG	74HC373N	TI	
C26-28	Digital, Register		24578-302	SIG	74HC40105N		
C29	Digital, Latch		24577-302	SIG	74HC373N	TI	
C30	Digital, DSP		24835-000	MOT	DSP56001FC27		
C31-33	Digital, Register		24578-302	SIG	74HC40105N		
C34,35	Digital, Latch		24577-302	SIG	74HC373N	TI	
C36-38	Digital, Multiplexer		24579-302	SIG	74HC253BN	TI	
C39	Digital, Latch		24577-302	SIG	74HC373N	TI	
C40	Digital, Multiplexer		24579-302	SIG	74HC253BN	TI	
C41	Digital, Hex Inverter		24572-302	NAT	74HC04N	TI	
C42	Digital, Line Decoder		24569-302	NAT	MM74HC138N	TI	
C43,44	Digital, Latch		24577-302	SIG	74HC373N	TI	
C45	Digital, Magnitude Comparator		24574-302	SIG	74HC85N	TI	
2) No Alte	S: ge 6-26 for Vendor abbreviations ernate Vendors known at publication part is specially selected from	(4)			uired if replaced, nd/or Alignment		SPECIFICATION REPLAC

VEN (1)

VENDOR P/N

ORBAN P/N

ALTERNATE VENDORS (1)

NOTES

REF DES

DESCRIPTION

REF DES	DESCRIPTION	ORBAN P/N	VEN (1)	VENDOR <u>P/N</u>	ALTERNATE VENDORS (1)
Miscellan	eous				
Y1	Oscillator; 27 MHz	28054-000	NE	EL HS-350-27.000	
FINGER BO	ARD ASSEMBLY				
Capacito	rs				
C12	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C13	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C14	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C15	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C16	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C17	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C18	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C19	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C20	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C21	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C22	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C23	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C26	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C27	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C28	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C29	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C30	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C31	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR
C32	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SP	R 1C25 Z5U104M05	OB KEM
C33	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CR	RL DD-102	MUR

FOOTNOTES:

- See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication
 Actual part is specially selected from
 part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200 DSP Board Assembly - Miscella Finger Board Assembly - Capac

NOTES

REF DES	DESCRIPTION	ORBAN P/N	VEN (1) VE	ENDOR <u>P/N</u>	ALTERNATE VENDORS (1)	<u>NOTES</u>
FRONT PAN	NEL ASSEMBLY					
Miscellan	<u>eous</u>					
	LCD Display	42025-000	ORB			
INPUT FILT	ER BOARD ASSEMBLY					
Capacito	r <u>s</u>					
C2-5	Ceramic Disc, 1KV, 10%; 0.001uF	21112-210	CRL	DD-102	MUR	
Inductors						
L1-4	Inductor, RF Choke; 1.2mH	29503-000	MIL	73F123AF		
L5-13	Inductor, RF Choke; 7uH	29501-004	OHM	Z-50		(2)
L14-21	Filter, EMI, W/INDUCT, 50V,470PF	29509-147	TAI	LC471M1RO		
L22-25	Filter, EMI, W/BEAD, 50V,1000PF	29508-210	TAI	STB102KB		
Miscellan	eous					
FB1	Ferrite Bead, with wire	29506-001	FR	2743001111		

- See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication
 Actual part is specially selected from part listed, consult Factory
- (4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200 Front Panel Assembly - Miscella Input Filter Board Assembly - Ca Miscellaneous.

REF DES	DESCRIPTION	ORBAN P/N	VEN (1) V	ENDOR <u>P/N</u>	ALTERNATE VENDORS (1)	NOTES
MAIN DISP	LAY BOARD ASSEMBLY					
Capacito	rs					
C100,101		21017-022	CD	CD15-CD220D03	SAN	
C200,201	Mica, 500V, 1%; 270pF	21018-127	CD	CD15-FD271F03	SAN	
C300-302	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	ECE-A1EV101S		
C303-327	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050	B KEM	
Diodes						
CR100	Diode, Rectifier, 400V, 1A	22201-400	MOT	1N4004	MANY	
Integrate	d Circuits					
IC1,2	Digital, Octal Flip-Flop	24553-302	NAT	MM74HC374		
IC3	Digital, RAM	24811-302	TOS	TC5565APL15L		
IC4	Digital, LCD Controller	24723-000	OKI	MSM62556GS		
IC5	Digital, Schmitt Trigger Inverter	24582-302	MOT	74HC14A		
IC6-8	Digital, Dual Flip-Flop	24567-302	RCA	CD74HC74N	SIG	
IC9	Digital, Schmitt Trigger Inverter	24582-302	MOT	74HC14A		
IC10	Digital, AND Gate	24576-302	RCA	CD74HC08		
IC11	Digital, Quad OR Gate	24571-302	NAT	MM74HC32N	TI	
IC12	Digital, Dual Flip-Flop	24567-302	RCA	CD74HC74N	SIG	
IC13,14	Digital, Octal Flip-Flop	24553-302	NAT	MM74HC374		
IC15	Digital, Line Decoder	24569-302	NAT	MM74HC138N	TI	
IC16	Digital, Octal Flip-Flop	24553-302	NAT	MM74HC374		
IC17,18	Digital, Buffer	24568-302	NAT	MM74HC244N	TI	
IC19	Digital, Binary Counter	24583-302	RCA	CD74HC393		
IC20	Digital, Quad 2-Input NAND	24559-302	RCA	74HCT132E	TI	
Miscellar	neous					
Y100	Crystal; 4.9152 MHz	28051-003	MID	C1700		
Modules						
A100	Digital, Inverter, DC to AC	24722-000	TDK	CXAM10L		
FOOTNOTE	S·					SPECIFIC

FOOTNOTES:

See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication

Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200

Main Display Board Assembly -Integrated Circuits, Miscella

REF DES	DESCRIPTION	ORBAN P/N	VEN (1) V	ENDOR <u>P/N</u>	ALTERNATE VENDORS (1)	NOTES
Resistors	1					
R104	Pot, Single; 500 OHM (5050)	20747-000	ORB			Linear
R204	Resistor Network, SIP; 100K	20221-101	BEK	L10-1C104		
Transisto	<u>rs</u>					
Q100	Transistor, Power, NPN; TO-220	23604-201	TI	TIP122	RCA	
MISCELLA	NEOUS					
Miscellan	eous					
	Extender Card 48/48	31510-002				
	Line Cord, CEE	28102-002	BEL	17500	MANY	
POWER SU	PPLY CHASSIS					
Integrate	d Circuits					
IC1	D.C. Regulator, 15V Positive	24304-901	NAT	LM78M15UC	TI,MOT	
IC2	D.C. Regulator, 15V Negative	24303-901	NAT	LM79M15AUC	TI,MOT	

- See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication
 Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200

Main Display Board Assembly -Miscellaneous - Miscellaneous. Power Supply Cord - Integrated

REF DES	DESCRIPTION	ORBAN P/N	VEN (1) VE	ENDOR <u>P/N</u>	ALTERNATE VENDORS (1)	<u>NOTES</u>	
REGULAT	OR BOARD ASSEMBLY						
Capacit	ors .						
C1	Alum., Axial, 40V, -10% +100%; 1000uF	21224-810	SIE	B41010-1000-40	PAN		
C2	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050I	B KEM		
C3	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	ECE-A1EV101S			
C4	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050I	B KEM		
C5	Alum., Axial, 40V, -10% +100%; 1000uF	21224-810	SIE	B41010-1000-40	PAN		
C6	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050I	B KEM		
C7	Alum., Radial, 25V, -20% +100%; 100uF	21206-710	PAN	ECE-A1EV101S			
C8	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPR	1C25 Z5U104M050I	B KEM		
Diodes							
CR1	Diode, Bridge, 200V, 1A	22301-000	VARO	VE-27	GI		
CR2,3	Diode, Rectifier, 400V, 1A	22201-400	MOT	1N4004	MANY		
Inducto	<u>rs</u>						
L1	Filter, Line	28012-000	DEL	03ME1			
Miscella	aneous						
F1	Fuse, 3AG, Slo-Blo, 1/2A	28004-150	LFE	313.500	BUS	Dom	nestic
F1	Fuse, Type T, 1/4A	28025-125	LFE	218.250		Euro	opean
F2	Fuse, 3AG, Slo-Blo, 4A	28004-240	LFE	313.004		Dom	nestic
F2	Fuse, Type T, 2A	28025-220	LFE	218.002		Euro	opean
F3,4	Fuse, Type T, 1/2A	28025-150	LFE	218.500		Euro	opean
PS1	Switcher, Power Supply	42026-000	ORB				
T1	Transformer, Power; 51VCT	55015-000	ORB				
V1	Varistor; 430V	22500-431	PAN	ERZ-C10DK431			
Resisto	<u>rs</u>						
R1-3	Resistor, 1/4W; 0 OHM (Jumper)	20020-025	ROHM	1 JPW-02A			
Switche	<u>es</u>						
S1	Switch, Push-Push; DPST	26118-000	SCH	NE18-2AEESP			
S2	Switch, Slide, Mains voltage selector	26143-000	SW	EPS2-PC3			

- See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication
 Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200

Regular Board Assembly - Capa Inductors, Miscellaneous, F

REF DES	DESCRIPTION	ORBAN P/N	VEN (1)	VENDOR P/N	ALTERNATE VENDORS (1)	NOTES
	ENERATOR BOARD ASSEMBLY		1 22 1	<u> </u>		
Capacito	ors .					
C1	Mica, 500V, +1/2pF -1/2pF; 5pF	21017-005	CD	CD15-CD050D03	SAN	
C2,3	Ceramic, Trim.; 0.5pF-3pF	21811-000	ME	2502AOR503V		
C5	Met. Polyester, 100V, 10%; 0.22uF	21441-422	WES	S 160D224K100	SIE	
C6	Mica, 500V, 1%; 510pF	21022-151	CD	CD19-FD511F03	SAN	
C7	Mica, 500V +1/2pF -1/2pF; 15pF	21017-015	CD	CD15-CD150D03	SAN	
C8	Mica, 500V, 1%; 1000pF	21022-210	CD	CD19-FD102F03	SAN	
C9	Mica, 500V, +1/2pF -1/2pF, 47pF	21017-047	CD	CD15-CD470D03	SAN	
C10	Mica, 500V, +1/2pF -1/2pF; 33pF	21017-033	CD	CD15-CD330D03	SAN	
C11	Mica, 500V, 1%; 470pF	21022-147	CD	CD19-FD471F03	SAN	
C12	Met. Polyester, 100V, 10%; 0.1uF	21441-410	WIN	MKS-4100V5.0.1	WES,SIE	
C13,14	Mica, 500V, 1%; 1000pF	21022-210	CD	CD19-FD102F03	SAN	
C15	Mica, 500V, +1/2pF -1/2pF; 10pF	21017-010	CD	CD15-CD100D03	SAN	
C16	Polypropylene, 50V, 2.5%; 0.01uF	21702-310	NOE	B CQ15P1H103GPP	WES	
C19	Monolythic Ceramic, 50V, 20%; 0.1uF	21123-410	SPF	R 1C25 Z5U104M050	B KEM	
C20	Met. Polyester, 100V, 10%; 0.1uF	21441-410	WIN	MKS-4100V5.0.1	WES,SIE	
C21,22	Mica, 500V, 1%; 1500pF	21022-215	CD	CD19-FD152F03	SAN	
C23,24	Mica, 500V, +1/2pF -1/2pF, 22pF	21017-022	CD	CD15-CD220D03	SAN	
C25	Mica, 500V, +1/2pF -1/2pF; 3pF	21017-003	CD	CD15-CD030D03	SAN	
.						

21017-039

21123-410

21206-710

21123-410

21206-710

21123-410

21206-710

21123-410

21206-710

21123-410

21206-710

21123-410

21441-310

21123-410

21123-410

FOOTNOTES:

C40,41

C42,43

C45,46

C48,49

C51,52

C54,55

C57-60

C61,62

C63-84

C90

C44

C47

C50

C53

C56

- (1) See page 6-26 for Vendor abbreviations
- (2) No Alternate Vendors known at publication

Mica, 500V +1/2pF -1/2pF; 39pF

Monolythic Ceramic, 50V, 20%; 0.1uF

Met. Polyester, 100V, 10%; 0.01uF

Alum., Radial, 25V, -20% +100%; 100uF

(3) Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

CD

SPR

PAN

SPR

PAN

SPR

PAN

SPR

PAN

SPR

PAN

SPR

WES

SPR

SPR

CD15-CD390D03

ECE-A1EV101S

ECE-A1EV101S

ECE-A1EV101S

ECE-A1EV101S

ECE-A1EV101S

160C 103K630

1C25 Z5U104M050B

SAN

KEM

KEM

KEM

KEM

KEM

KEM

KEM

KEM

SIE, WIM

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200

Stereo Generator Board Assem

REF DES	DESCRIPTION	0	RBAN P/N	VEN (1)	VE	ENDOR <u>P/N</u>	ALTERNA VENDOR		NOTES
						·			
Capacito	ors (continued)								
C91	Mica, 500V, 5%; 150pF		21020-115	CD		CD15-FD151J03	SAN		
C92	Monolythic Ceramic, 50V, 20%; 0.1uF		21123-410	SPI	R	1C25 Z5U104M050	B KEM		
Diodes									
CR1,2	Diode, Signal, Hot Carrier		22102-001	HP		HP5082-2800	MANY		
CR5,6	Diode, Rectifier, 400V, 1A		22201-400	МО		1N4004	MANY		
CR7-10	Diode, Signal, Hot Carrier		22102-001	HP		HP5082-2800	MANY		
CR20	Diode, Voltage Reference		22081-112	NA	Т	LM385	MOT		
Inductor	<u>s</u>								
L1	Inductor, Variable		29705-004	OR	В				
L2	Inductor, Variable		29705-005	OR	В				
Integrate	ed Circuits								
IC1,2	Linear, Dual Opamp		24207-202	SIG	}	NE5532N	TI,EXR		
IC3,4	Linear, Dual Opamp		24209-202	NA	Т	LF412CN			
IC5-7	Linear, Single Opamp		24008-202	TI		LM318N	NAT		
IC8	Linear, Dual Opamp		24207-202	SIG	}	NE5532N	TI,EXR		
IC10-12	Digital, 2-Channel Multiplexer		24562-302	NA	Т	MM7HC4053			
IC13,14	Quad Comparator		24710-302	NA	Т	LM339			
IC15	Linear, Single Opamp		24008-202	TI		LM318N	NAT		
IC16	Power Buffer		24707-102	LT		LT1010CH			
IC17,18	Digital, Octal Flip-Flop		24553-302	NA	Т	MM74HC374			
IC19	D.C. Regulator, 5V Positive		24307-901	NA	Т	LM78M05C	TI,MOT		
IC20	D.C. Regulator, 5V Negative		24308-901	NA	Т	LM79M05C	TI,MOT	•	
IC21	Digital, Buffer		24568-302	NA		MM74HC244N	TI		
IC22	Digital, Up-Counter		24508-302	RC		CD4520BE			
IC23	Digital, Dual Flip-Flop		24567-302	RC.		CD74HC74N	SIG		
IC24	Digital, Hex Inverter		24572-302	NA		74HC04N	TI		
IC25	Digital, Magnitude Comparator		24574-302	SIG	•	74HC85N	TI		
IC26	Linear, Single Opamp		24008-202	TI		LM318N	NAT		
IC27	Power Buffer		24707-102	LT	_	LT1010CH			
IC28,29	Linear, Dual Opamp		24209-202	NA ⁻		LF412CN			
IC31	Digital, PROM		44001-002	OR	В				
FOOTNOTE	ES:								SPECIFICATIONS
(1) See p	(4)				uired if replaced,			REPLACI	
(2) No Alt		escriptior	n ar	nd/or Alignment		OPTIMO	D-FM 8200		
	l part is specially selected from sted, consult Factory		Instructions					-	enerator Board Assen
Partin	siou, consult actory								acitors, Diodes, Induc grated Circuits.

REF DES	DESCRIPTION	ORBAN P/N	VEN (1) VE	NDOR <u>P/N</u>	ALTERNATE VENDORS (1)	NOTES
Integrate	d Circuits (continued)					
IC32	Digital, Converter	24726-302	AD	AD7576JN		
IC34	Digital, Line Decoder	24569-302	NAT	MM74HC138N	TI	
Miscellan	neous					
Y1	Crystal; 4.864 MHz	28052-002	NEL	NE-18-4.864MHz		
Resistors	<u>3</u>					
R37	Trimpot, Cermet, 20 Turn; 1K	20512-210	BEK	89PR1K	BRN	
R50	Trimpot, Cermet, 20 Turn; 5K	20512-250	BEK	89PR5K	BRN	
R66	Trimpot, Cermet, 20 Turn; 25K	20512-325	BEK	89PR25K	BRN	
R72	Trimpot, Cermet, 20 Turn; 25K	20512-325	BEK	89PR25K	BRN	
R102	Resistor, 1/4W; 0 OHM (Jumper)	20020-025	ROHM	JPW-02A		
R103	Resistor Network, SIP; 100K	20221-101	BEK	L10-1C104		
Switches						
S1	Switch, Rotary; 2P3T	26205-000	ELSW	080-020330NX		
Transisto	<u>ors</u>					
Q1-5	Transistor, JFET/N	23403-101	NAT	J111	INS	
Q8	Transistor, Signal, PNP	23002-101	MOT	2N4402	FSC	
Q9	Transistor, JFET/N	23403-101	NAT	J111	INS	
Q10	Transistor, Signal, NPN	23202-101	MOT	2N4400	FSC	
Q30,31	Transistor, JFET/N	23403-101	NAT	J111	INS	
SWITCH BO	DARD ASSEMBLY					
LED						
None	LED, Green	25107-002	MAT	LN322GP		
Switches						
S5	Switch, Rotary, Encoder	26080-000	CLA	600EN-128-CBL		

See page 6-26 for Vendor abbreviations
 No Alternate Vendors known at publication
 Actual part is specially selected from part listed, consult Factory

(4) Realignment may be required if replaced, see Circuit Description and/or Alignment Instructions

SPECIFICATIONS REPLACE

OPTIMOD-FM 8200

Stereo Generator Board Assemi Miscellaneous, Resistors, S Switch Board Assembly - LED, S

6-44 TECHNICAL DATA

Ve	ndor Codes			НА	Harris Semiconductor 1301 Woody Burke Rd. Melbourne, FL 32901	MAT	Matsushita Electric Corp of America One Panasonic Way Secaucus, NJ 07094	PAN	Panasonic Industrial Company Two Panasonic Way 7E-2T Secaucus, NJ 07094	S.W.	Seitchcraft A Raytheon Company 5555 N. Elation Avenue Chicago, IL 60630
AB	Rockwell Allen-Bradley 625 Liberty Ave Pittsburgh, PA 15222-3123	CTS	CTS Corporation 907 North West Blvd. Elkhart, IN 46514	НО	Hoyt Elect. Inst. Works 19 Linden St. Penacook, NH 03303	ME	Mepcopal/Centralab A North American Phillips Corp. 11468 Sorrento Valley Road	QT	Quality Technologies, Inc. 610 North Mary Ave. Sunnyvale, CA 94086	AT	Taiga America, Inc. 700 Frontier Way Bensenville, IL 60106
AD	Analog Devices, Inc. One Technology Way PO Box 9106 Norwood, MA 02062-9106	CW DBX	CW Industries 130 James Way Southampton, PA 18966	HP	Hewlett-Packard Co. Components Group 640 Page Mill Road Palo Alto, CA 94304	MID	San Diego, CA 92121 Hollingsworth/Wearnes 1601 N. Powerline Rd. Pampano, FL 33069	RAL	Raltron Electronics Corp. 2315 NW 107th Ave. Miami, FL 33172	TDK	TDK Electronics Corporation 12 Harbor Park Port Washington, NY 11050
AKG	AKG Acoustics, Inc. See Orban	DDA	A Harman International Company 8760 South Sandy Parkway Sandy, UT 84107	INS	Intersil, Inc. See Harris Semiconductor	MIL	J.W. Miller Division Bell Industries	RAY	Raytheon Company Semiconductor Division 350 Ellis Street	TI	Texas Instruments, Inc. PO Box 655012 Dallas, TX 75265
AM	Amphenol Corporation 358 Hall Avenue Wallingford, CT 06492	DEL	Delta Products Corp 3225 Laurel View Ct. Fremont, CA 94538	ITW	ITW Switches An Illinois Tool Works Co. 6615 W. Irving Park Rd. Dept. T	МОТ	306 E. Alondra Gardena, CA 90247 Motorola Semiconductor PO Box 20912	RCA	Mountain View, CA 94039 RCA Solid State See Harris Semiconductor	TOS	Toshiba America, Inc. 9740 Irvine Blvd. Irvine, CA 92718
BEK	Beckman Industrial Corporation 4141 Palm Street Fullerton, CA 92635-1025	DUR	Duracell, Inc. Berkshire Industrial Park Bethel, CT 06801	KEM	Chicago, IL 60634 KEMET Electronics Corporation Post Office Box 5928 Greenville, South Carolina 29606	MUR	Phoenix, AZ 85036 Murata Erie North America 2200 Lake Park Drive	ROHM	M Rohm Electronics 3034 Owens Dr. Antioch, TENN 37013	TRW	TRW Electronics Components Connector Division 1501 Morse Avenue Elk Grove Village, IL 60007
BEL	Belden Electronic Wire & Cable PO Box 1980 Richmond, IN 47374	ELSW	7 Electro Switch 77 King Avenue Weymouth, MA 02188	KEY	Keystone Electronics Corp. 31-07 20th Rd.	NAT	Smyrna, GA 30080 National Semiconductor Corp.	SAE	Stanford Applied Engineering, Inc 340 Martin Avenue Santa Clara, CA 95050	VARO	Micro Quality Semiconductor, Inc. PO Box 469013
BRN	Bourns, Inc Resistive Components Group 1200 Columbia Avenue Riverside, CA 92507	EMI	Crompton Modutec 920 Candia Rd. Manchester, NH 03109	LFE	Astoria, NY 11105 Littlefuse A Subsidiary of Tracor, Inc. 800 E. Northwest Hwy	NEL	2900 Semiconductor Drive PO Box 58090 Santa Clara, CA 95051 Crystal Biotech	SAN	Sangamo Weston Inc. Capacitor Division See Cornell-Dubilier	WES	Garland, TX 75046-9013 Westlake See Mallory Capacitor Co.
BUS	Bussmann Division Cooper Industries PO Box 14460 St. Louis, MO 63178	EXR	Exar Corporation 2222 Qume Dr. PO Box 49007 San Jose, CA 95161-9007	LT	Des Plaines, IL 60016 Linear Technology Corp. 1630 McCarthy Blvd.	NOB	75 South Street Hopkinton, MA 01748 Noble U.S.A., Incorporated	SCH	ITT Schadow, Inc. 8081 Wallace Road Eden Prairie, MN 55344	WIM	Wima Division 2269 Saw Mill Rd. Building 4C PO Box 217
CD	Cornell-Dubilier Electronics 1700 Rte. 23 North Wayne, NJ 07470	FR	Fair-Rite Products Corp. PO Box J Wallkill, NY 12589	LUMX	Milpitas, CA 95035 Lumex Opto/Components Inc. 292 E. Hellen Road Palatine, IL 60067	ОКІ	5450 Meadowbrook Industrial Ct. Rolling Meadows, IL 60008 OKI Semiconductor 785 N. Mary Ave.	SIE	Siemens Components Inc. Heimann Systems Div. 186 Wood Avenue South Iselin, NJ 08830	ZI	Elmsford, NY 10533 ZILOG Inc. 210 Hacienda Ave. Campbell, CA 95008
CRL	Mepcopal/Centralab See Mepcopal	FSC	Fairchild Camera & Instr. Corp. See National Semiconductor	MAL	Mallory Capacitor Co. 7545 Rockville Rd. PO Box 1284	ОНМ	Sunnyvale, CA 94086-2909 Ohmite Manufactoring Company 3601 Howard Street	SIG	Philips Components - Signetics North American Phillips Corp. 811 E. Arques Sunnyvale, CA 94088		Campoon, Cri 75000
CSC	Crystal Semiconductor Corporation 4210-T. South Industrial Dr. Austin, TX 78744	GI	General Instruments Optoelectronics Division See Quality Technologies	MAR	Indianapolis, IN 46241 Marquardt Switches, Inc. 2711-TR Route 20 East	ORB	Skokie, IL 60076 Orban A Harman International Company	SPR	Sprague Electric Co. 41 Hampden Road PO Box 9102		
					Cazenovia, NY 13035		1525 Alvarado Street		Manifold, MA 02048-9102		

San Leandro, CA 94577

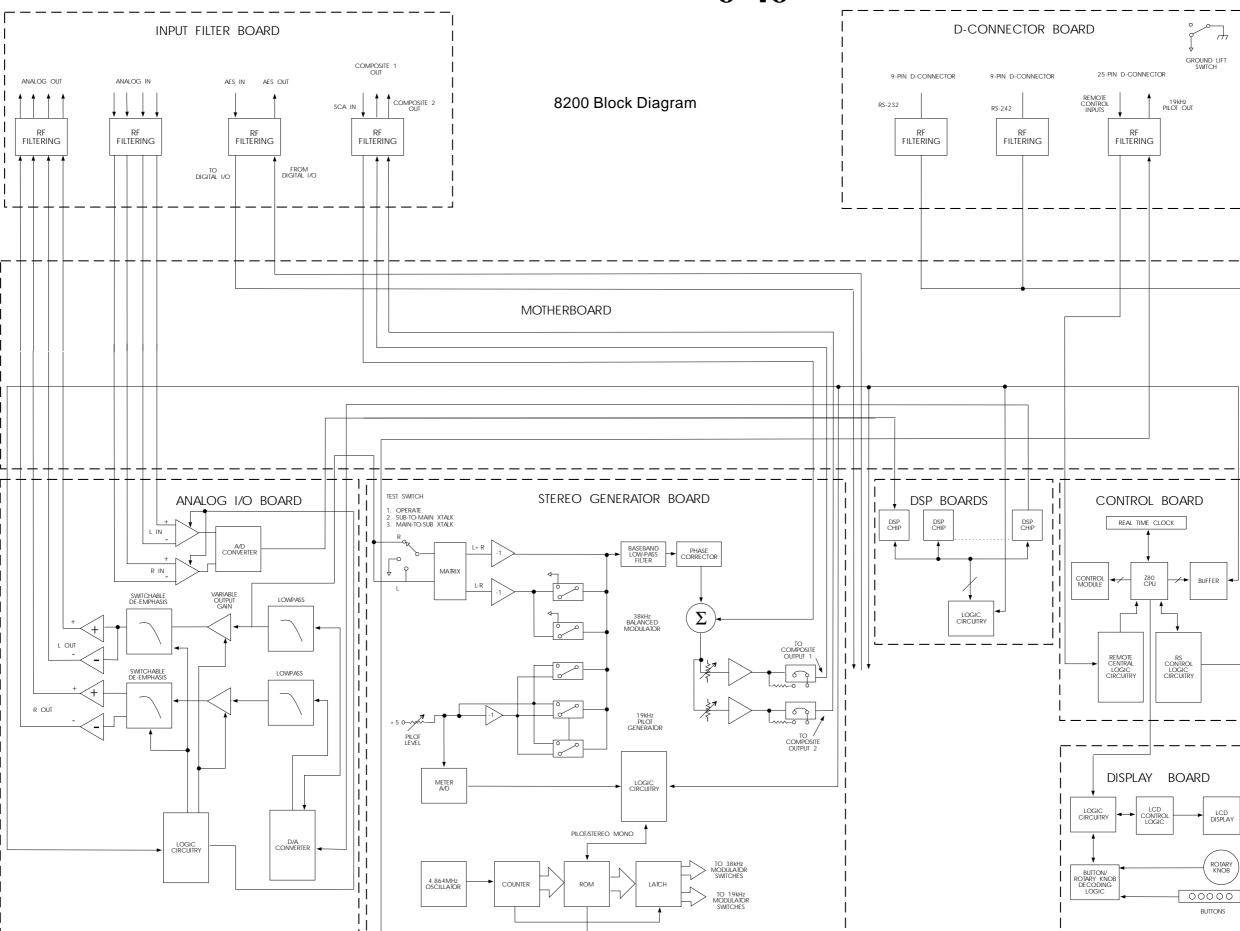
Schematics, Assembly Drawings

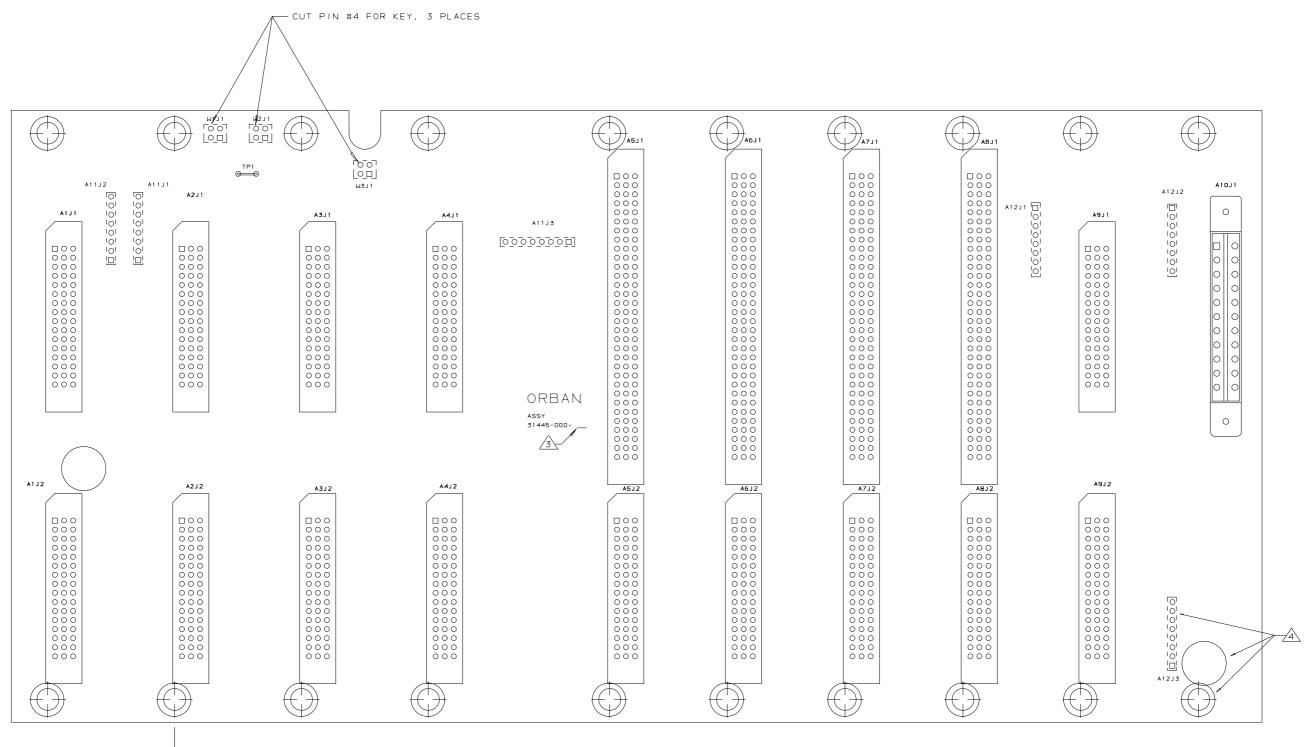
The following drawings are included in this manual:

Page	Circuit Board	Drawing
6-46	Block Diagram	Assembly Drawing
6-47	Mother	Assembly Drawing
6-48	Mother	Schematic 1 of 5
6-49		2 of 5
6-50		3 of 5
6-51		4 of 5
6-52		5 of 5
6-53	Control	Assembly Drawing
6-54	Control	Schematic 1 of 2
6-55		2 of 2
6-56	DSP	Assembly Drawing
6-57	DSP	Schematic 1 of 4
6-58		2 of 4
6-59		3 of 4
6-60		4 of 4
6-61	Analog I/O	Assembly Drawing
6-62	Analog I/O	Schematic 1 of 4
6-63	_	2 of 4
6-64		3 of 4
6-65		4 of 4
6-66	Stereo Encoder	Assembly Drawing
6-67	Stereo Encoder	Schematic 1 of 3
6-68		2 of 3
6-69		3 of 3
6-71	Display	Assembly Drawing
6-72	Display	Schematic 1 of 2
6-73		2 of 2
6-74	Regulator	Assembly Drawing
6-75	Regulator	Schematic
6-76	Input Filter	Assembly Drawing
6-77	Input Filter	Schematic
6-78	D-Connector	Assembly Drawing
6-79	D-Connector	Schematic

These drawings reflect the actual construction of your unit as accurately as possible. Any differences between the drawings and your unit are almost undoubtedly due to product improvements or production changes since the publication of this manual.

If you intend to replace parts, please read page 6-27





COMPONENT SIDE

INSERT FROM SOLDER SIDE TYPICAL, 20 PLACES

5. CONNECTORS SHOWN AS DASHED LINES TO BE MOUNTED ON SOLDER SIDE

OF PCB AFTER WAVE SOLDER OF COMPONENT SIDE CONNECTIONS.

MASK ALL MOUNTING HOLES AND HOLES FOR SOLDER SIDE CONNECTORS

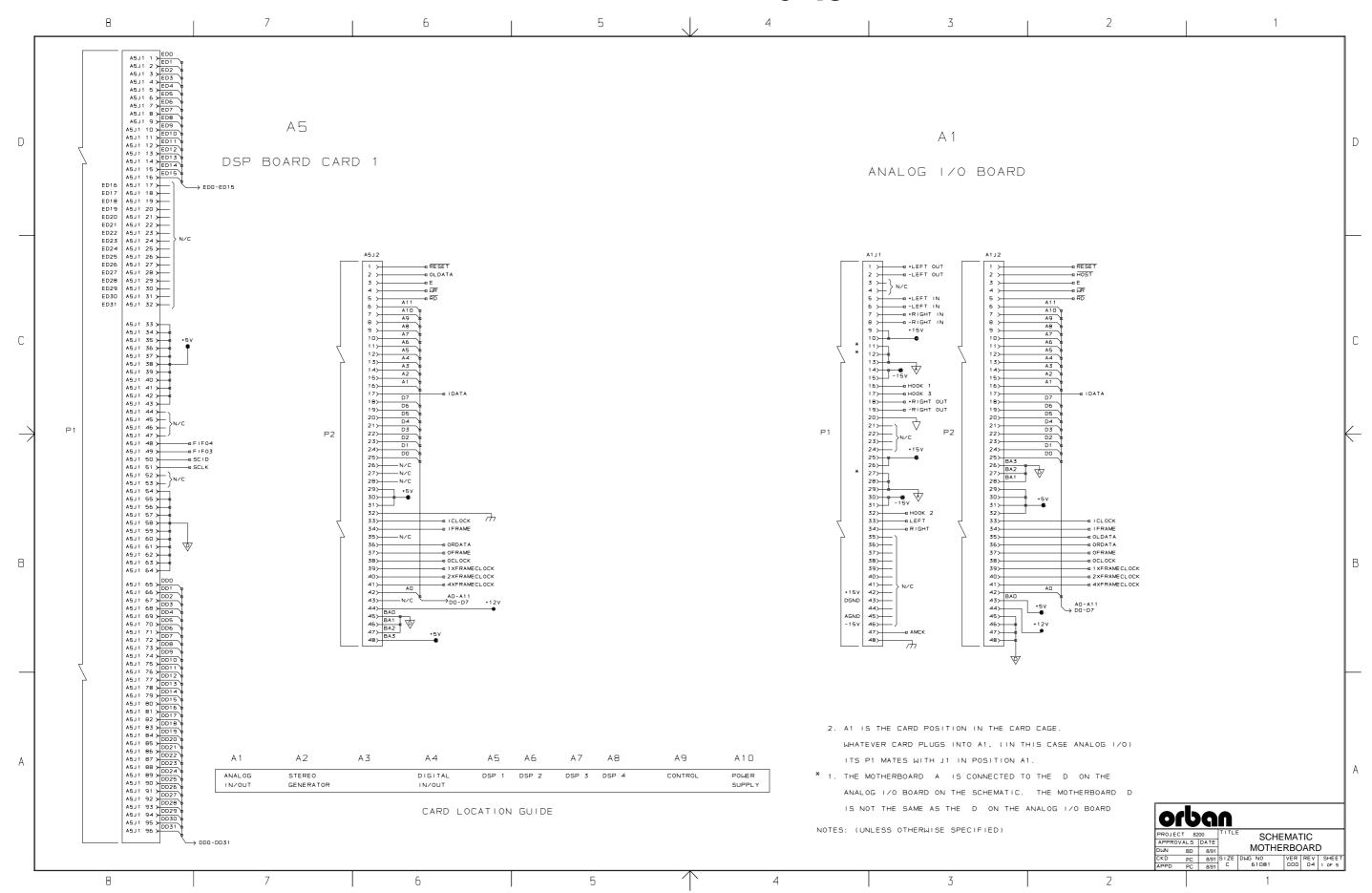
BEFORE WAVE SOLDERING.

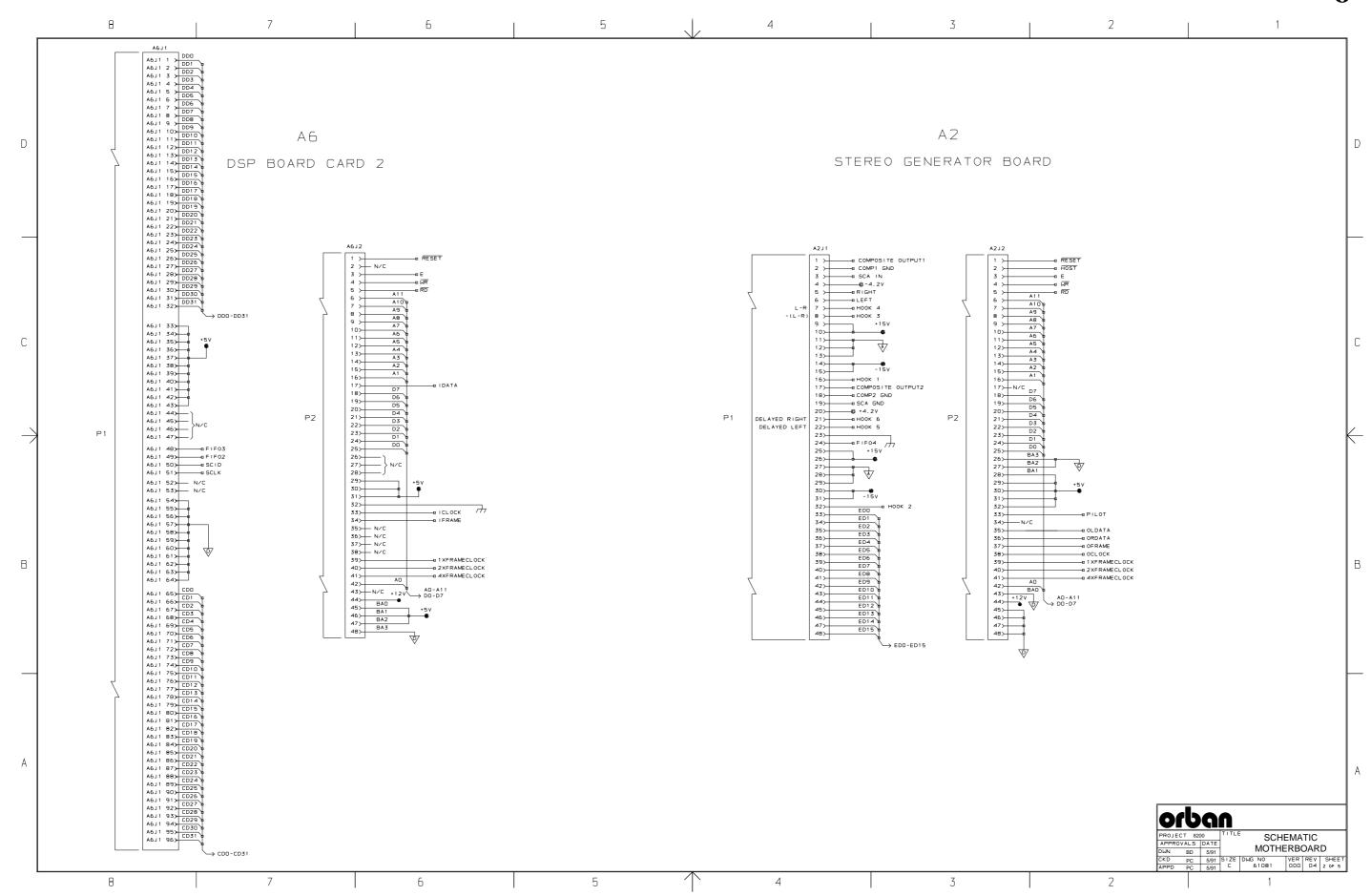
3. MARK ASSEMBLY REVISION LEVEL IN SPACE PROVIDED

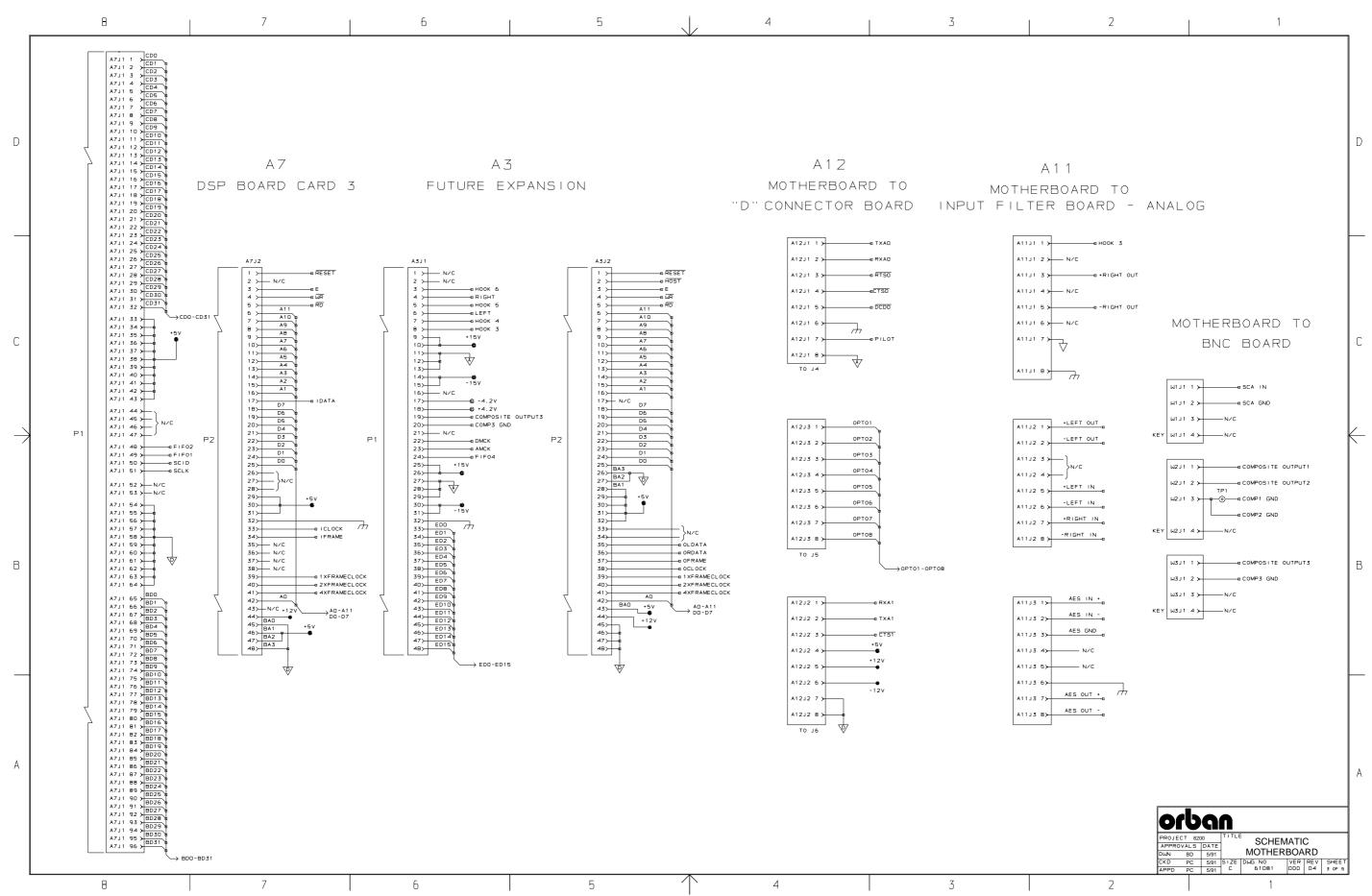
- 2. REFERENCE SCHEMATIC DRAWING NO. 61081
- 1. SQUARE PADS INDICATE PIN 1 OF CONNECTORS, CATHODE OF DIODES,
 POS. SIDE OF CAPS., PIN 1 OF ICS

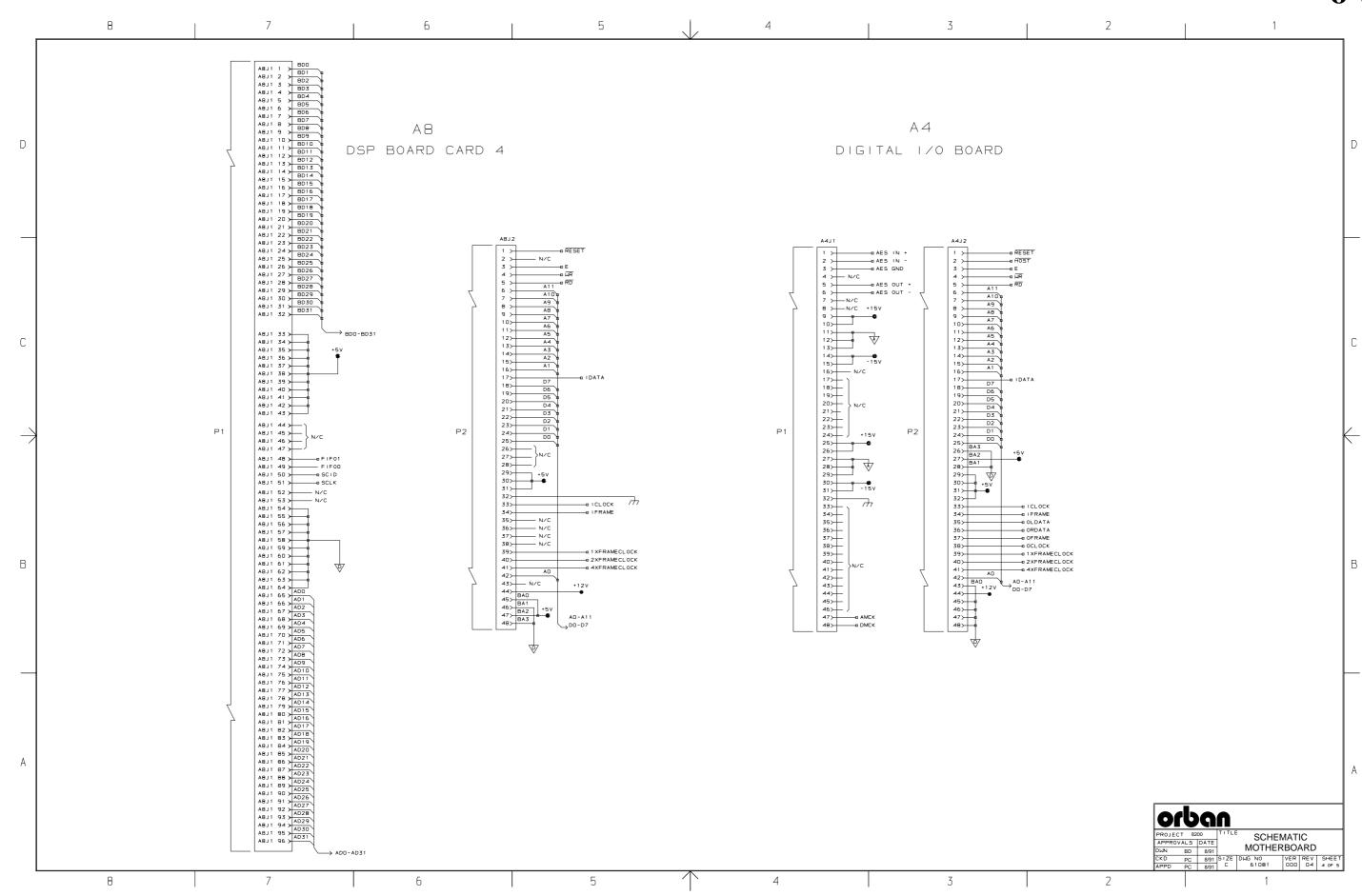
NOTES: (UNLESS OTHERWISE SPECIFIED)

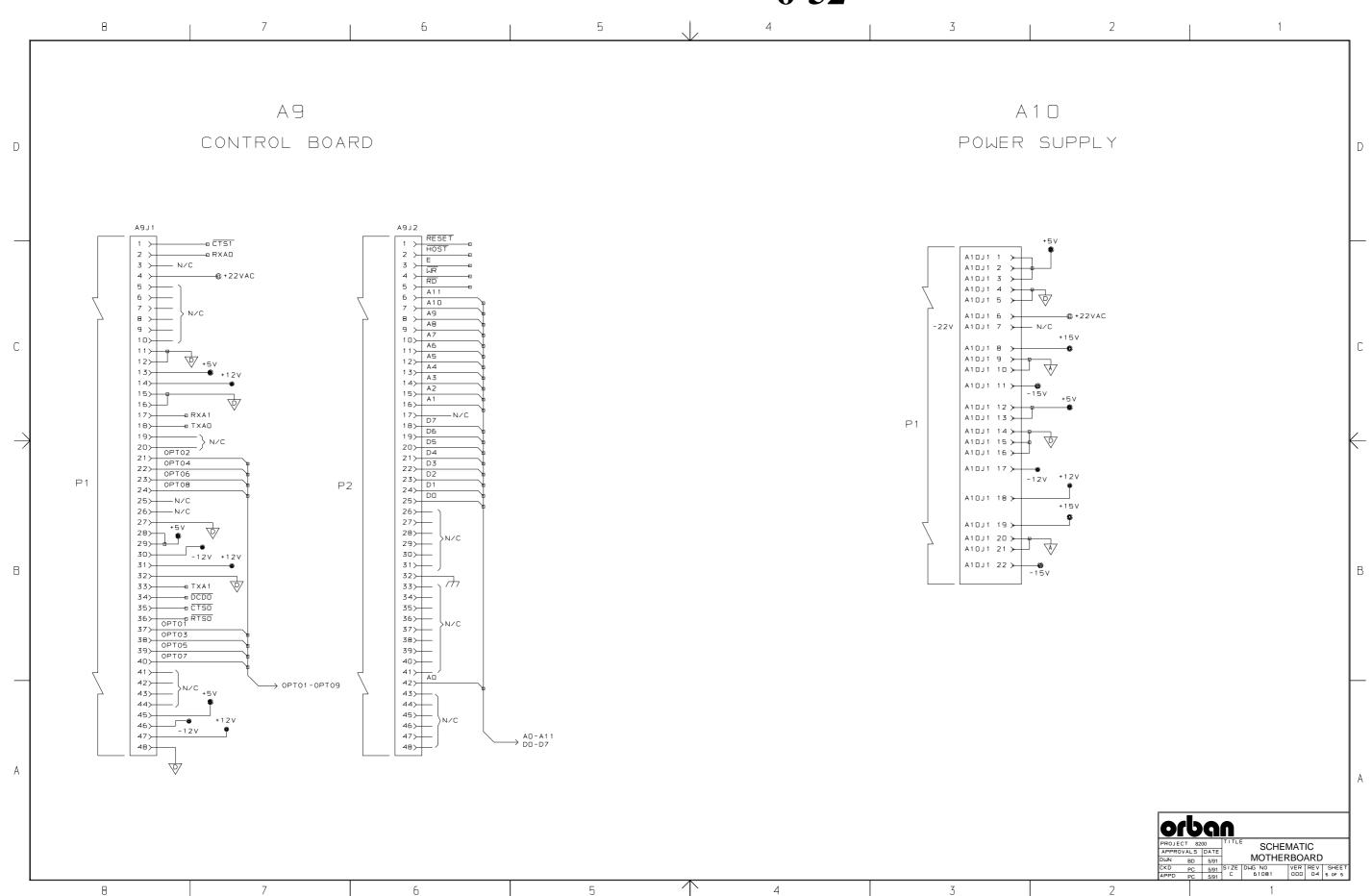
01	rb	QN								
MODEL	82	00	TITLE	PCB AS	SEM	RI V				
APPROV	ALS	DATE		MOTHERBOARD						
DWN	BD	5/91		MOTHE	KRO	ARD				
CKD	MJ	5/91	SIZE	DWG NO	VER	REV	SHEET			
APPD	MJ	5/91] C	31445	000	02	1 OF 1			

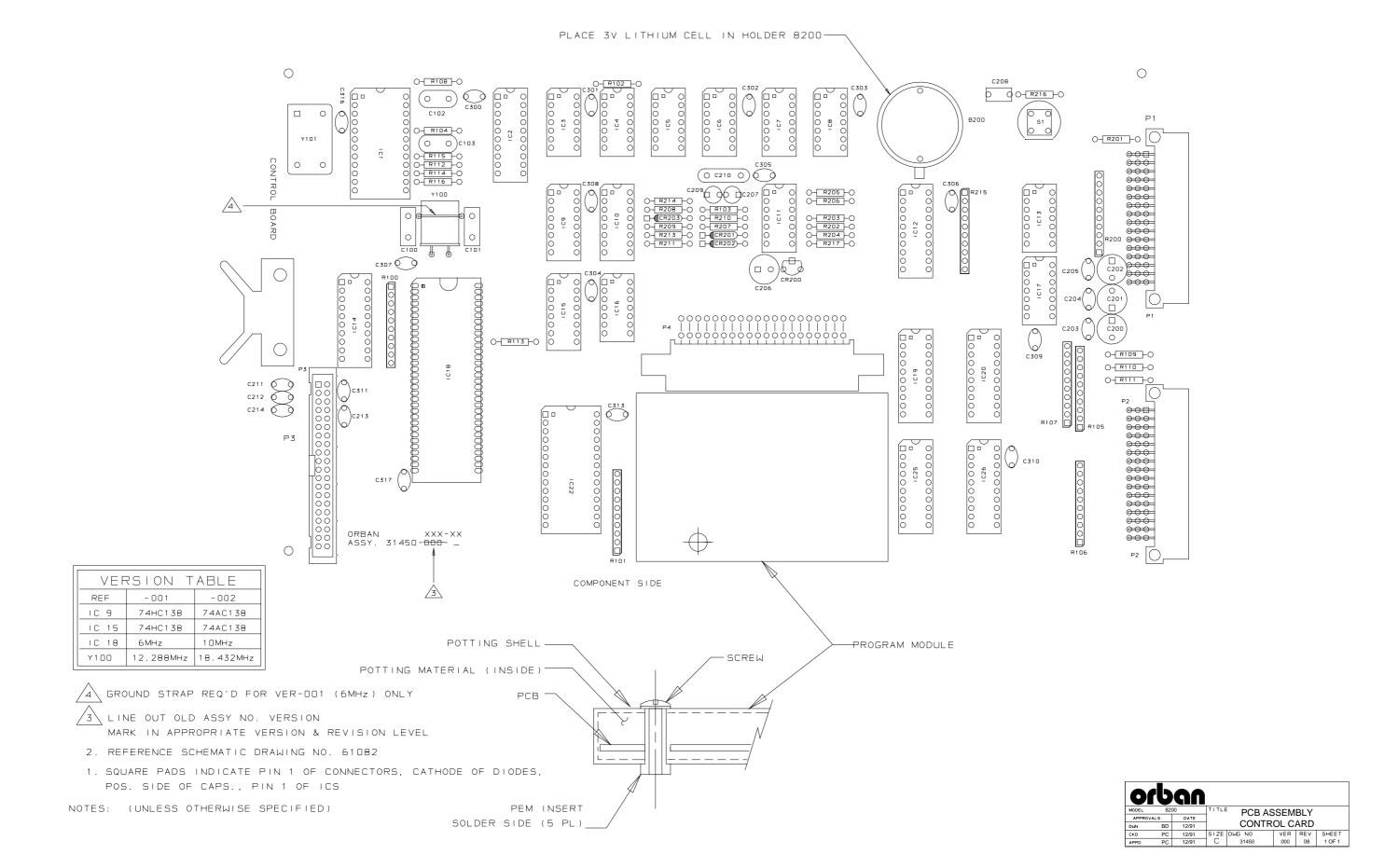


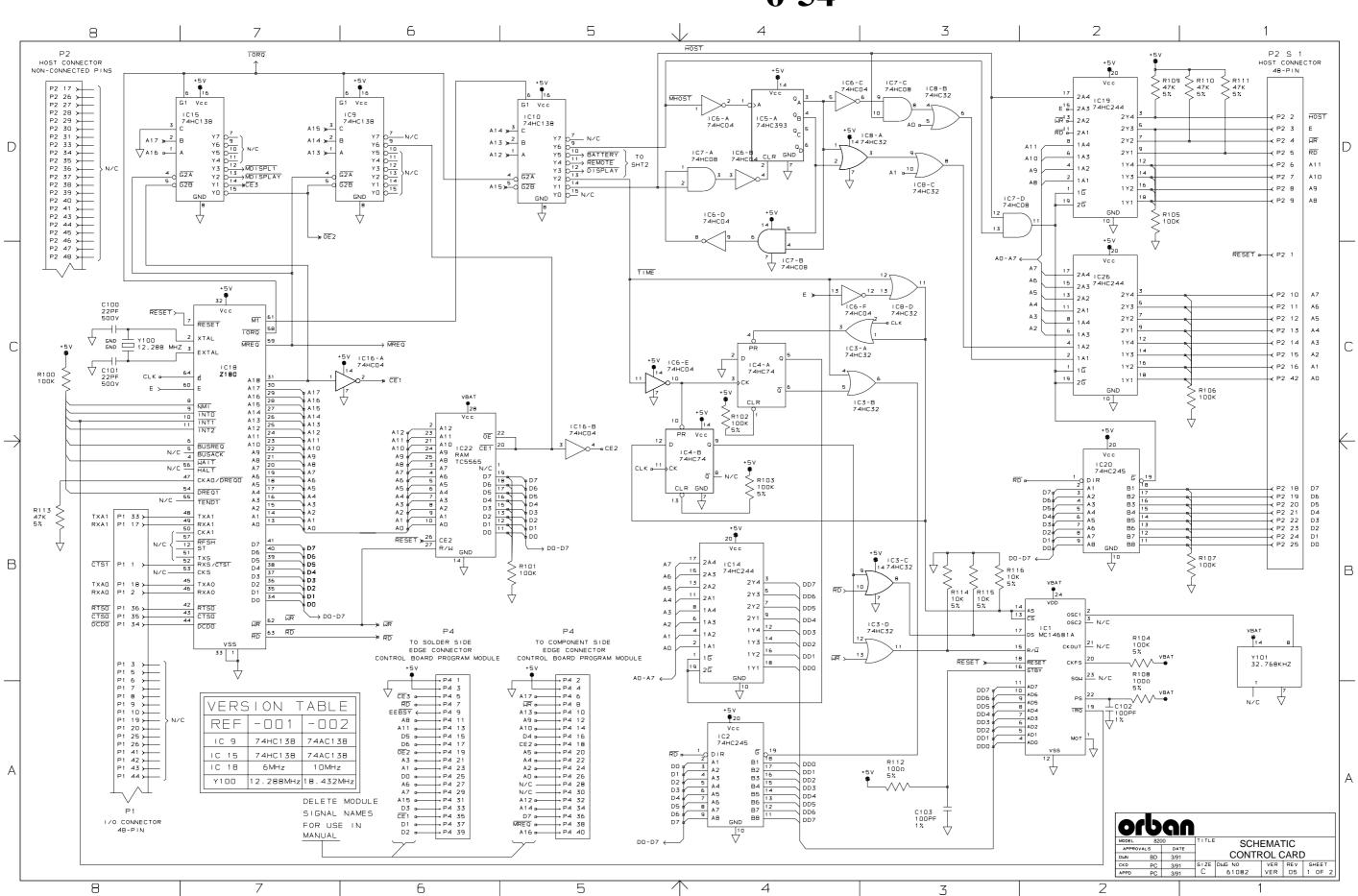


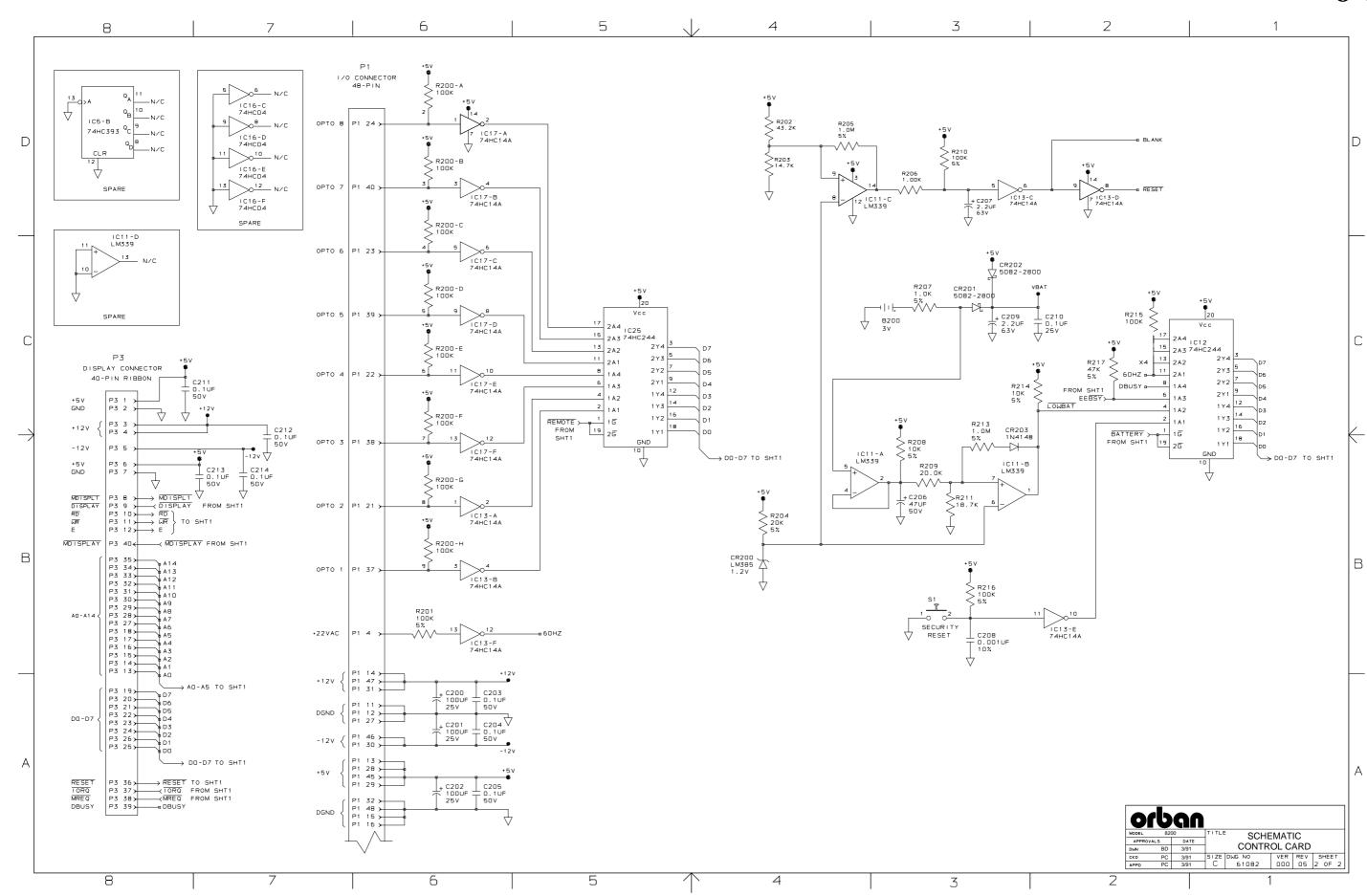




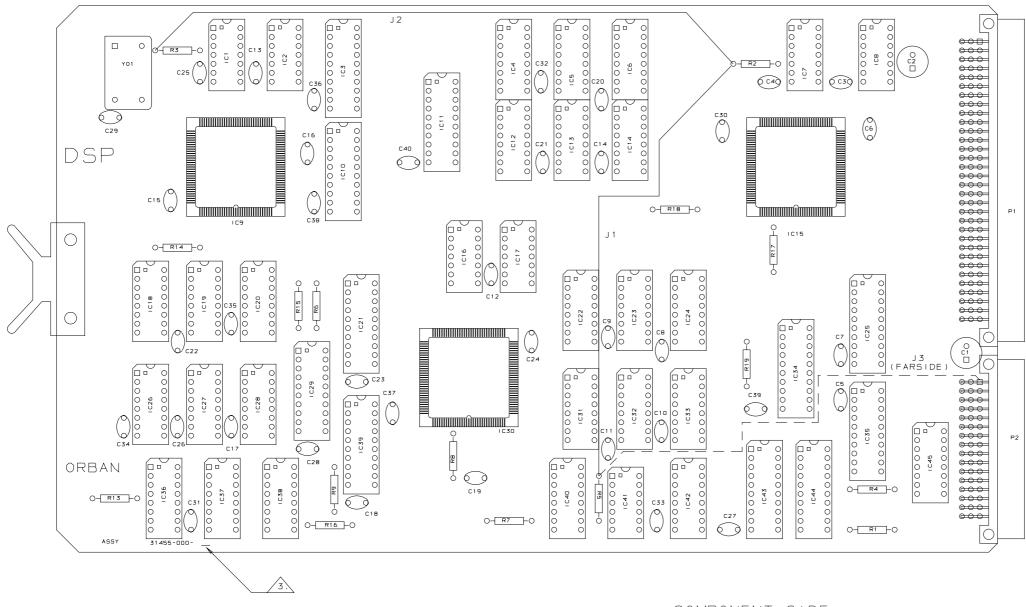












COMPONENT SIDE

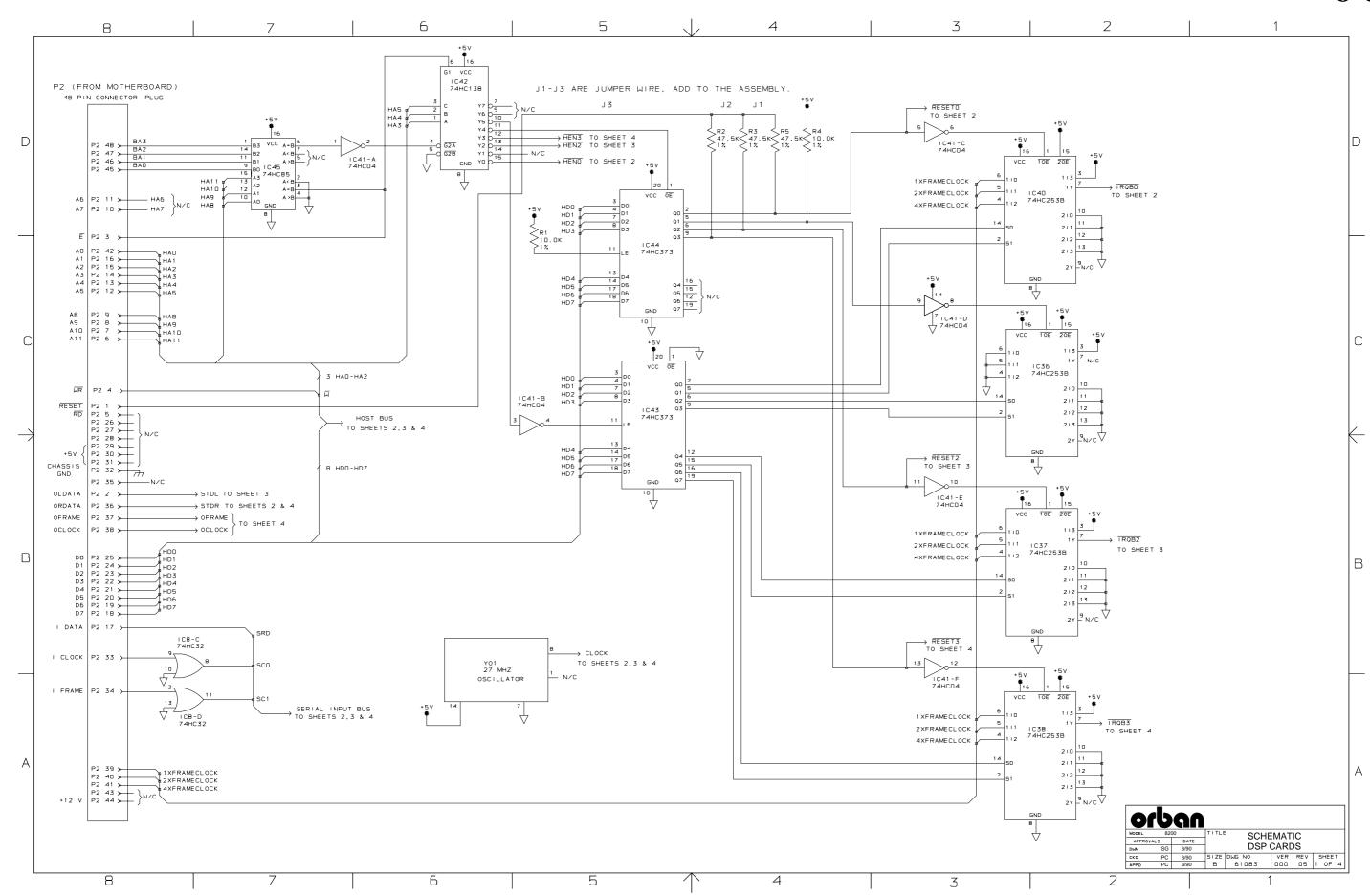
COMPONENT SIDE

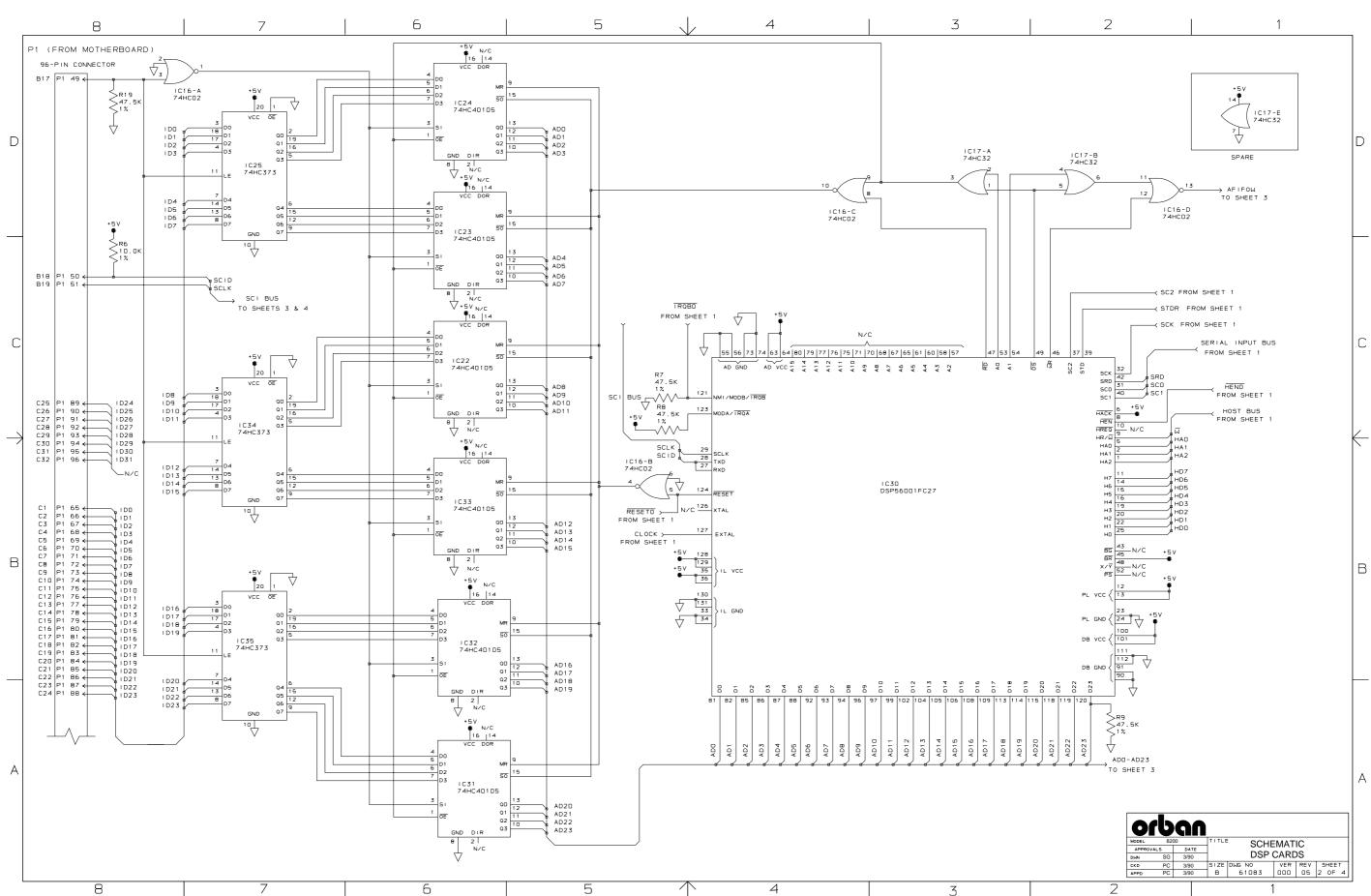
/3\ MARK ASSEMBLY REVISION LEVEL IN SPACE PROVIDED

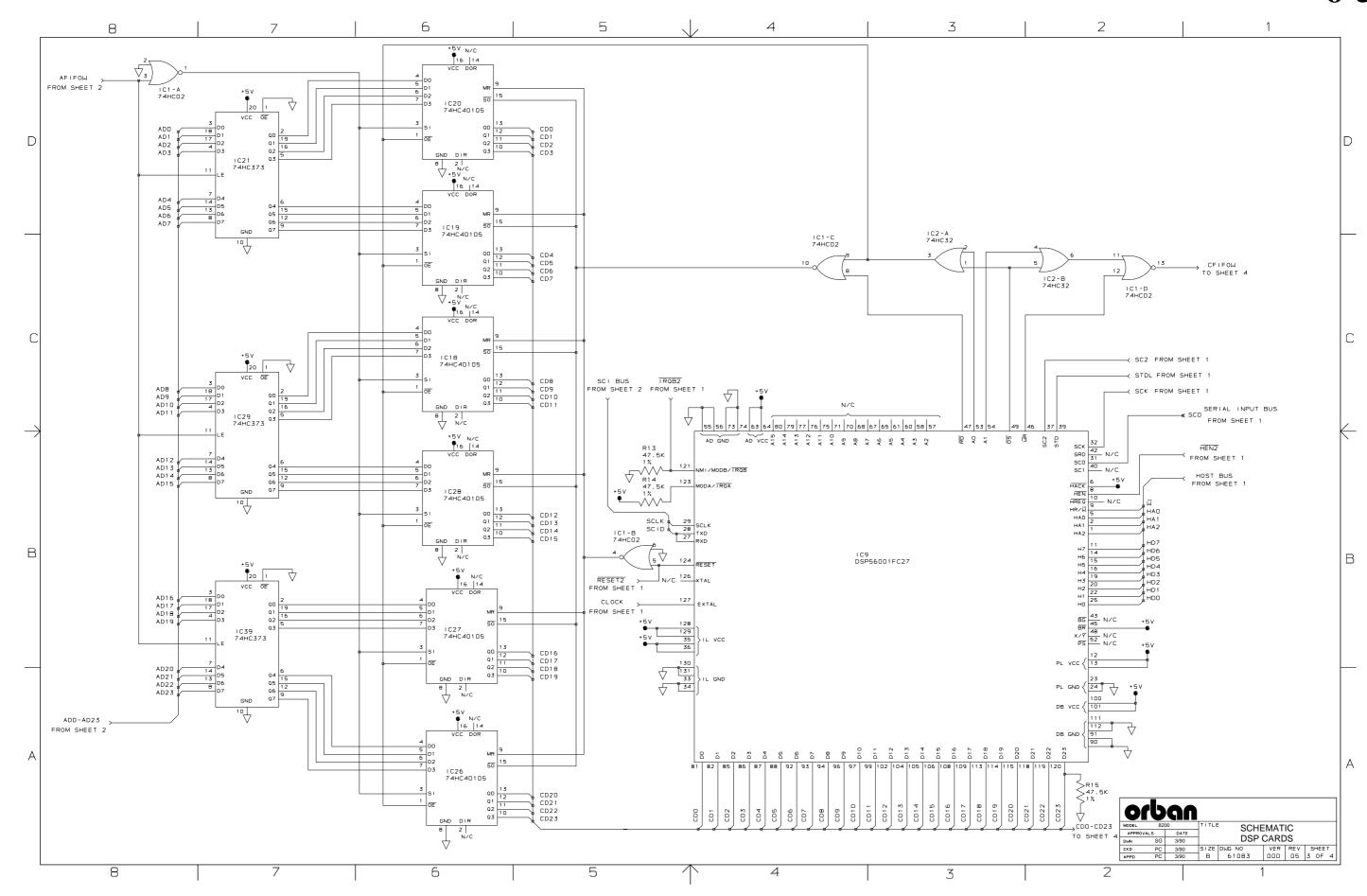
- 2. REFERENCE SCHEMATIC DRAWING NO. 61083-000-05
- 1. SQUARE PADS INDICATE PIN 1 OF CONNECTORS, CATHODE OF DIODES POS. SIDE OF CAPS., PIN 1 OF IC'S

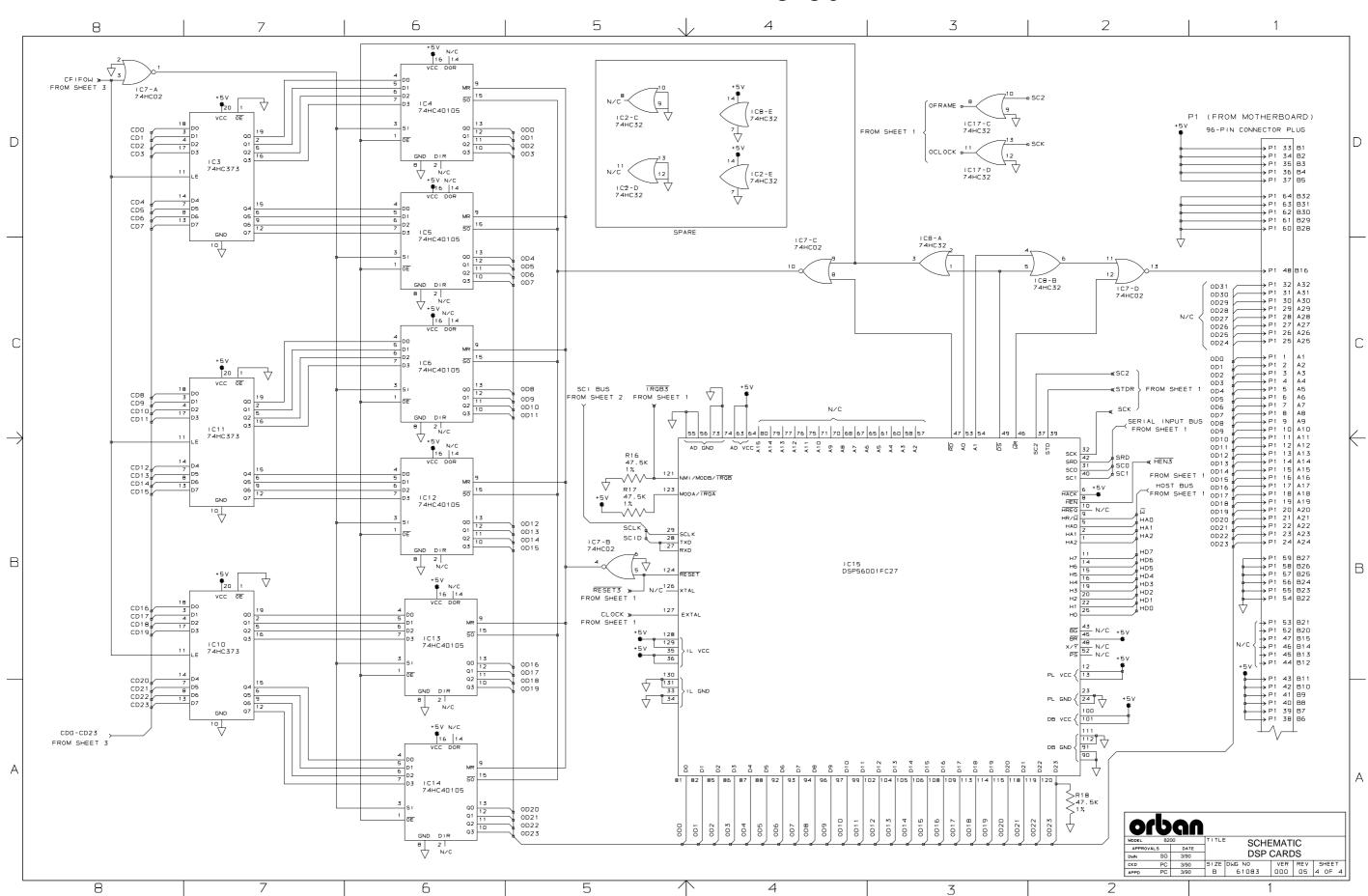
NOTES: (UNLESS OTHERWISE SPECIFIED)

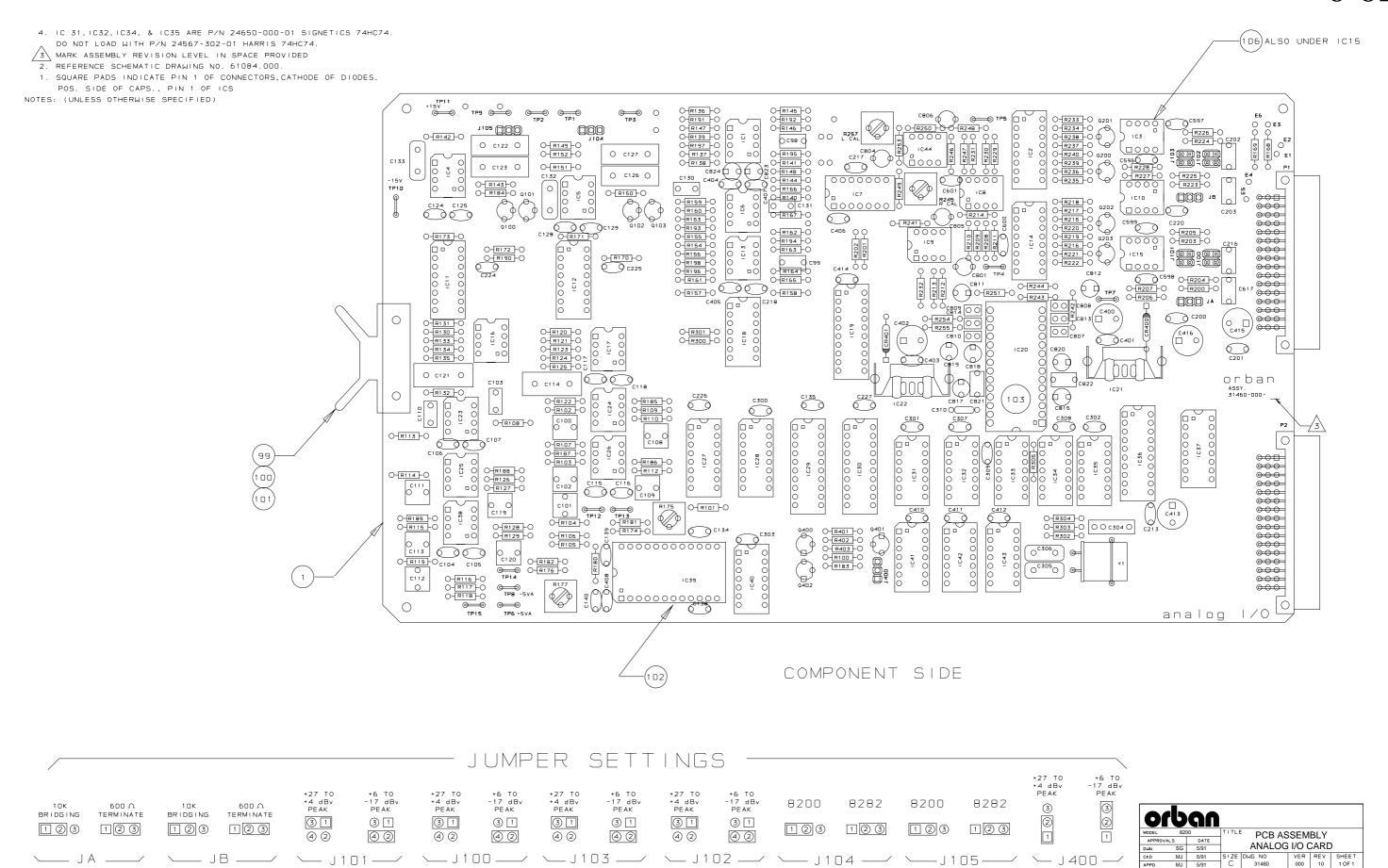
01	b	gn								
MODEL 8200 TITLE PCB ASSEMBLY										
APPROV	ALS	DATE		DSP CARDS						
DWN	BD	10/93		DSP	JARL	S				
CKD	MJ	6/93	SIZE	DWG NO	VER	REV	SHEET			
APPD	MJ	6/93	7 C	31455	000	06	1 OF 1			

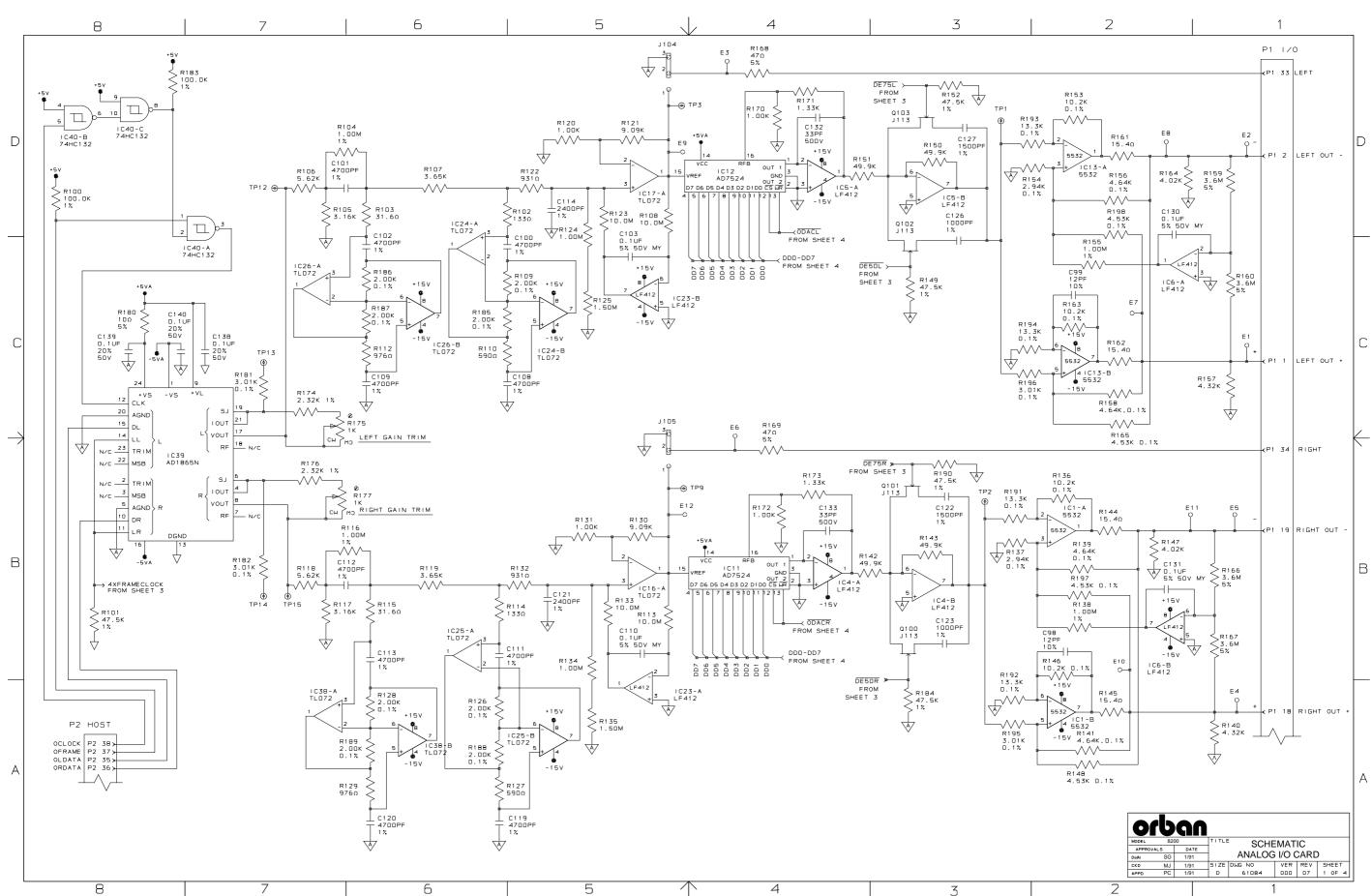


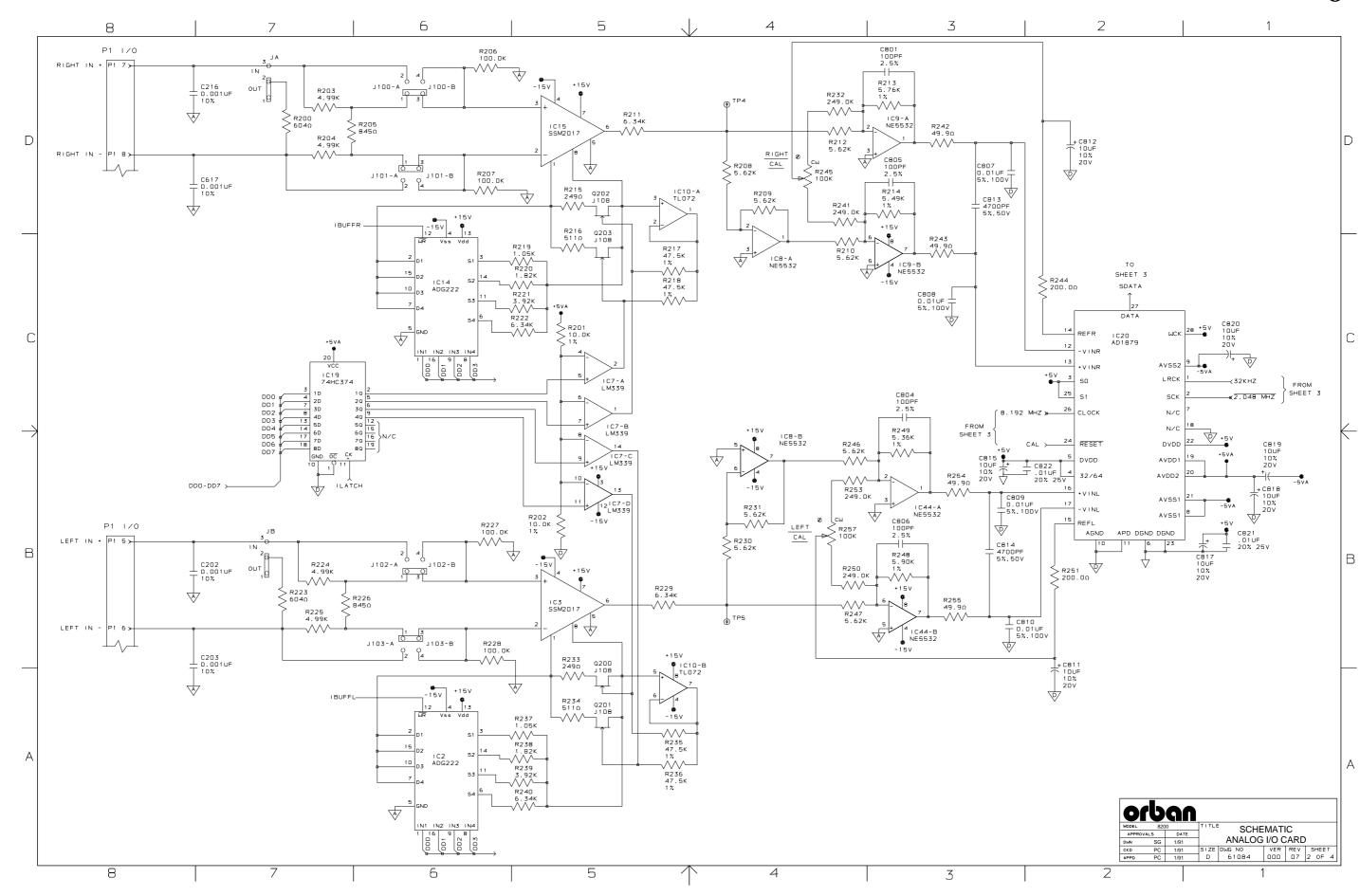


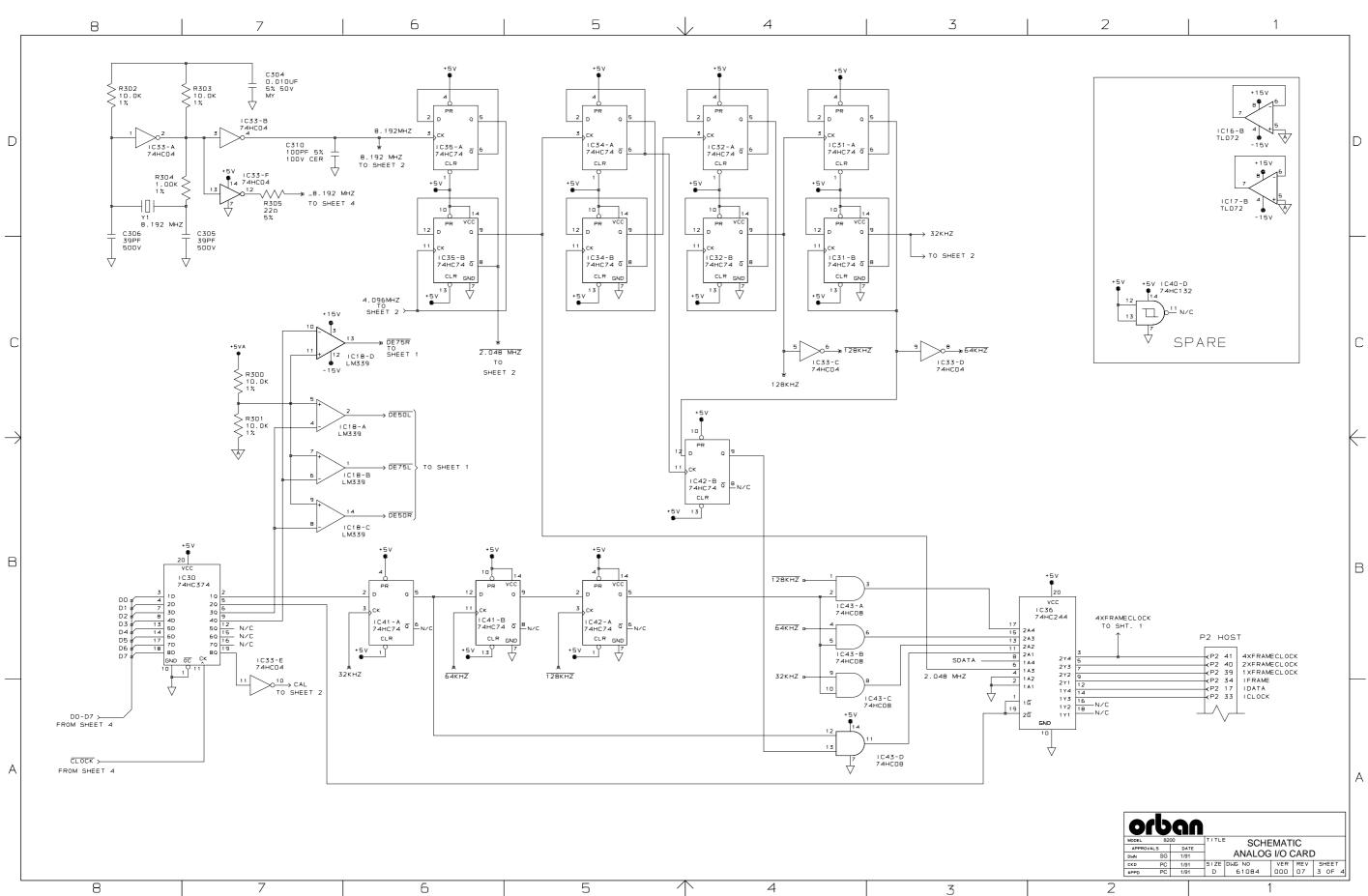


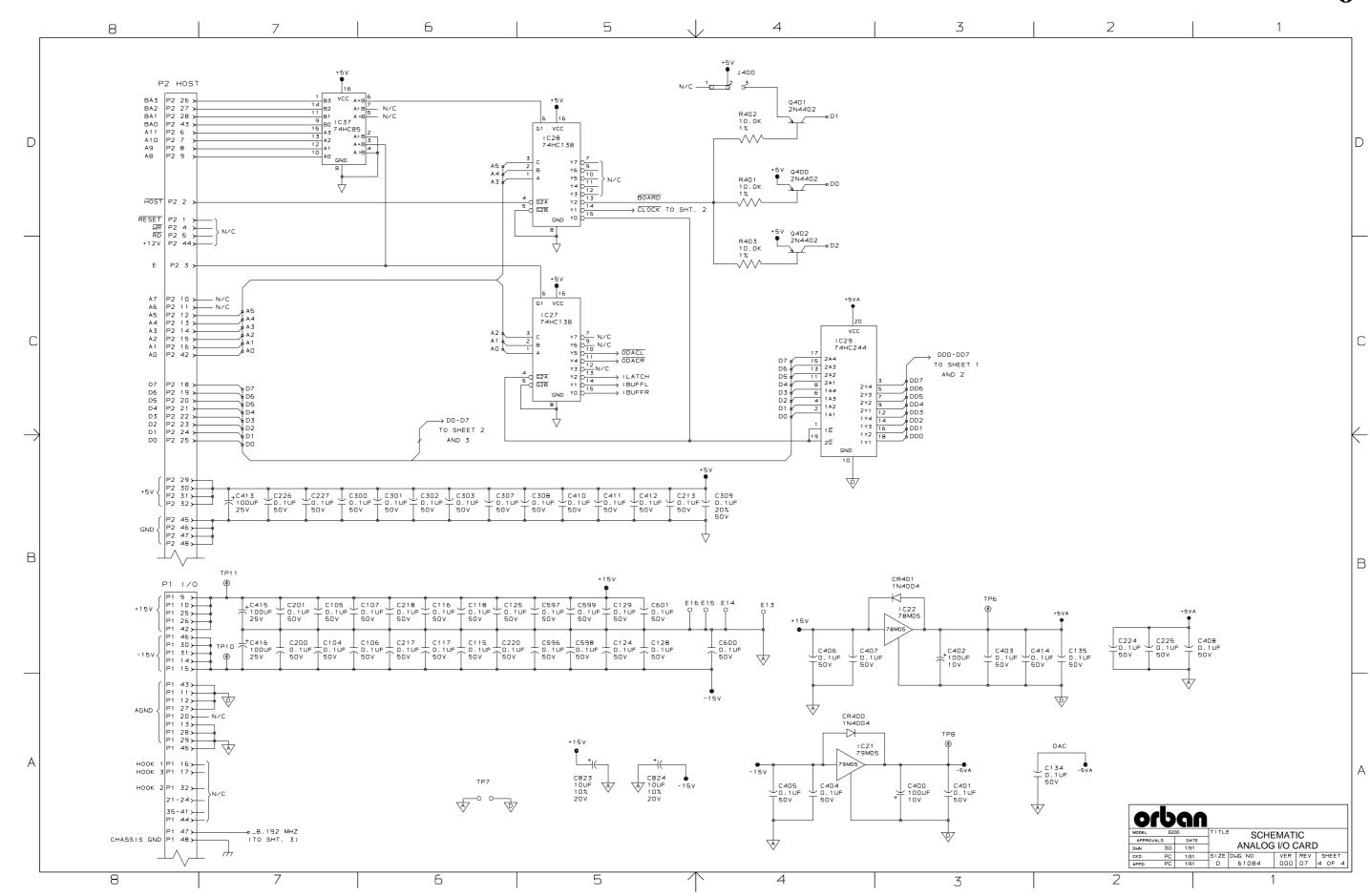




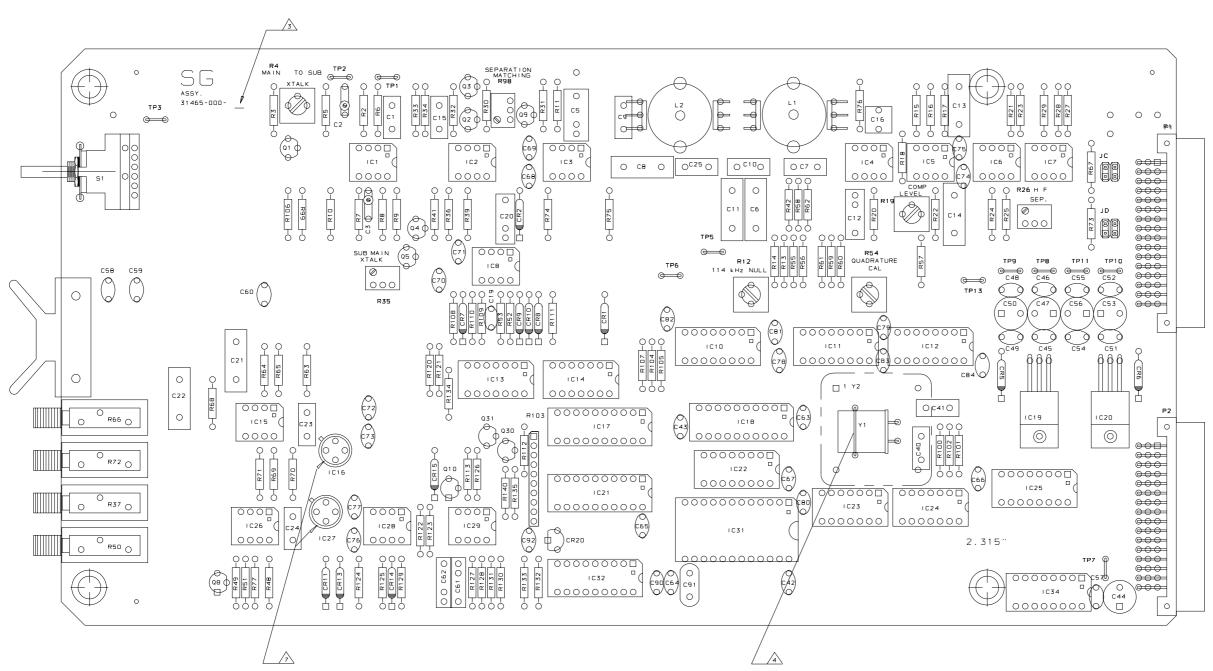












7 INSTALL AKG P/N 15051-000-01 BEFORE SOLDER FLOWING

6. ON FAB SIDE OF BOARD ADD (1) COAX CABLE FROM E1 TO E4 WITH E5 AS GND

AND ADD (1) COAX CABLE FROM E3 TO E2 WITH E6 AS GND

5. Y2 SHOWN FOR FUTURE USE ONLY

4. SOLDER RETAINING WIRE TO CRYSTAL

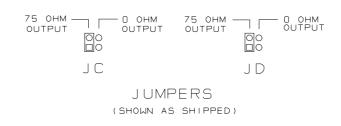
3. MARK ASSEMBLY REVISION LEVEL IN SPACE PROVIDED

- 2. REFERENCE SCHEMATIC DRAWING NO. 61085.
- 1. SQUARE PADS INDICATE PIN 1 OF CONNECTORS, CATHODE OF DIODES

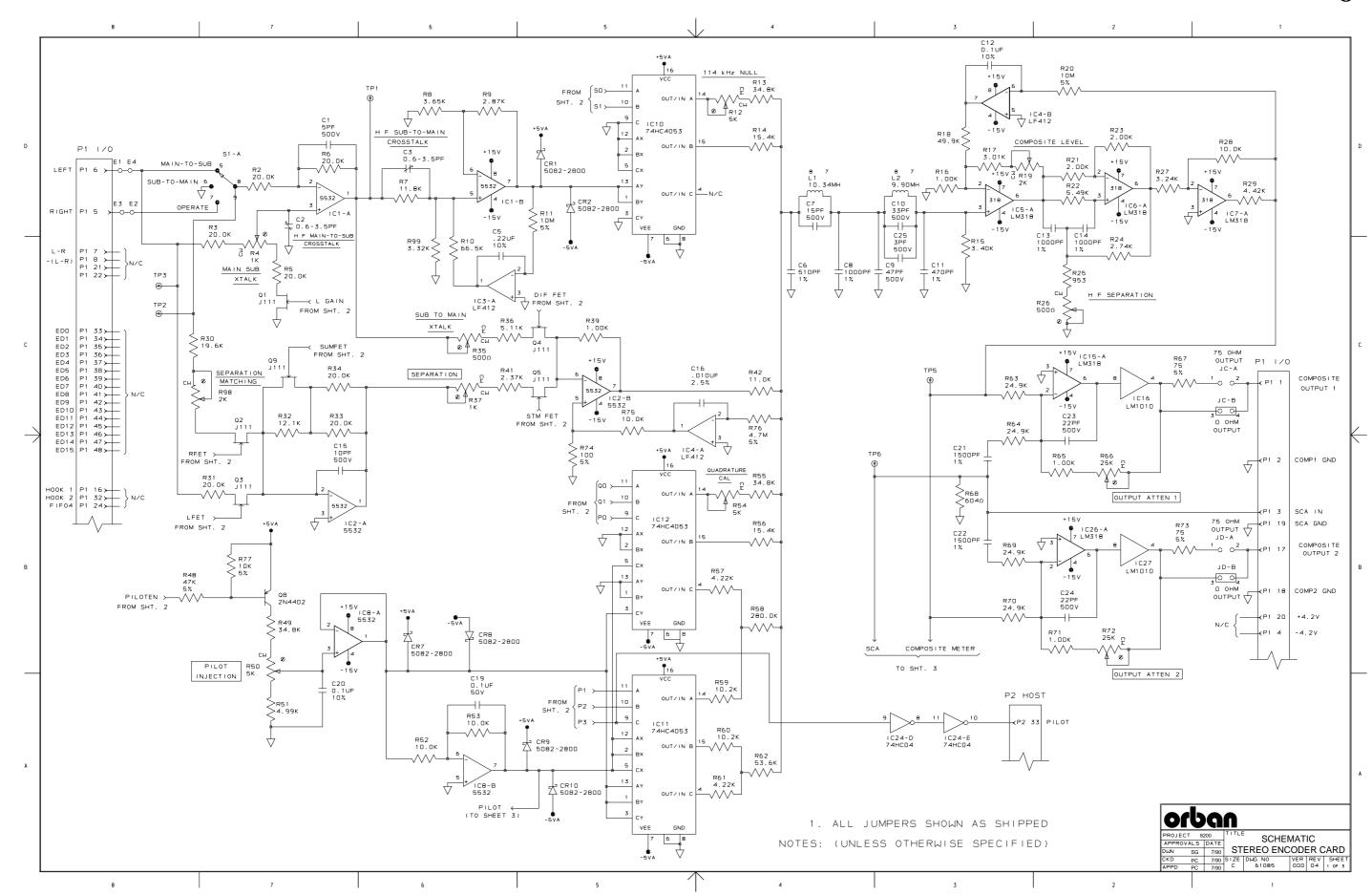
 POS. SIDE OF CAPS., PIN 1 OF ICS

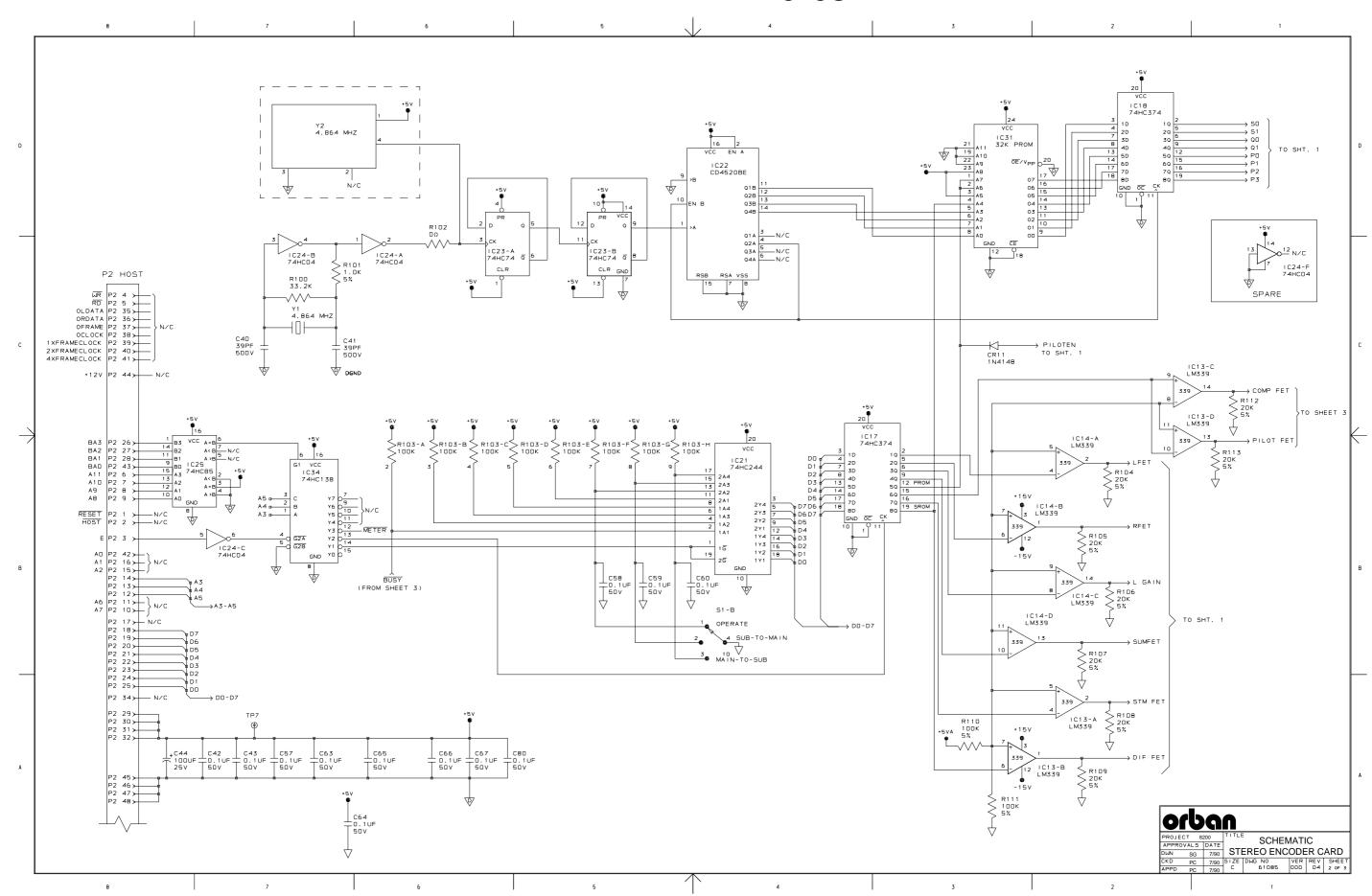
NOTES: (UNLESS OTHERWISE SPECIFIED)

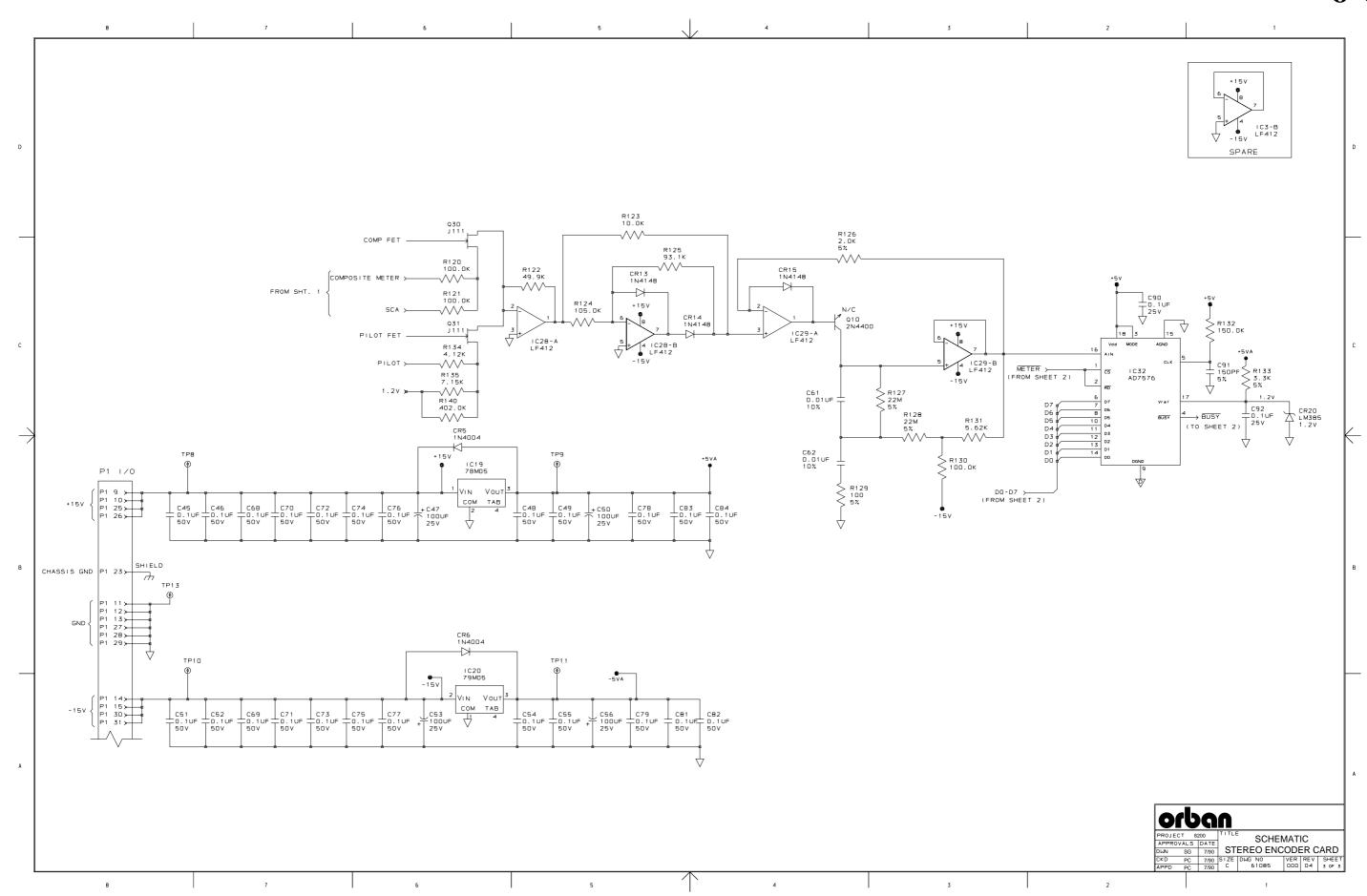
COMPONENT SIDE



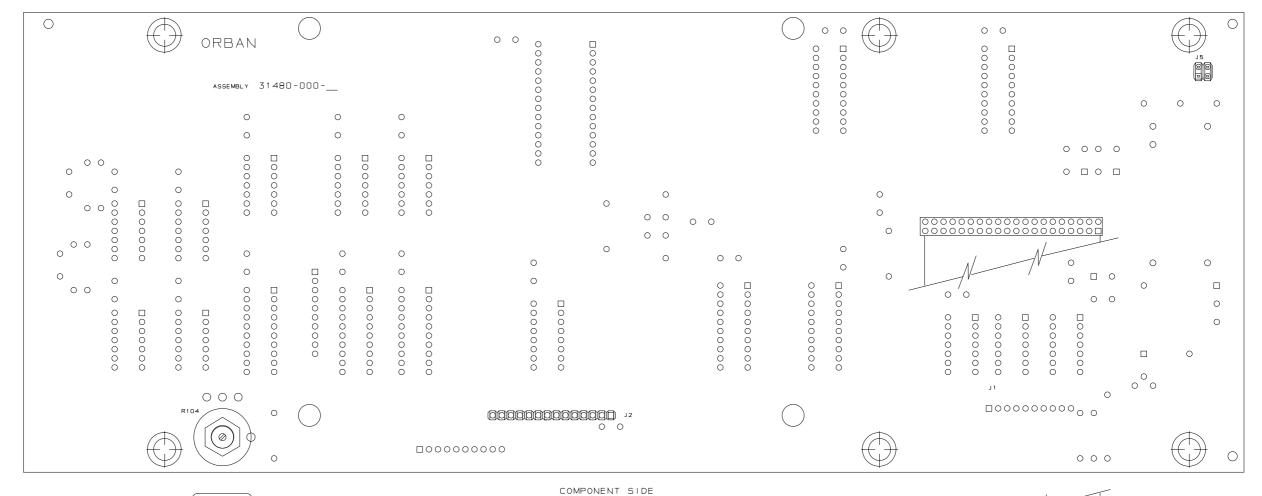
01	rb	QN								
MODEL	82	00	TITLE	PCB AS	SEM	RI V				
APPROV	ALS	DATE	1							
DWN	SG	8/91	1	STEREO G	iENE	HAI	JK			
CKD	MJ	8/91	SIZE	DWG NO	VER	REV	SHEET			
APPD	MJ	8/91	1 C	31465	000	06	1 OF 1			







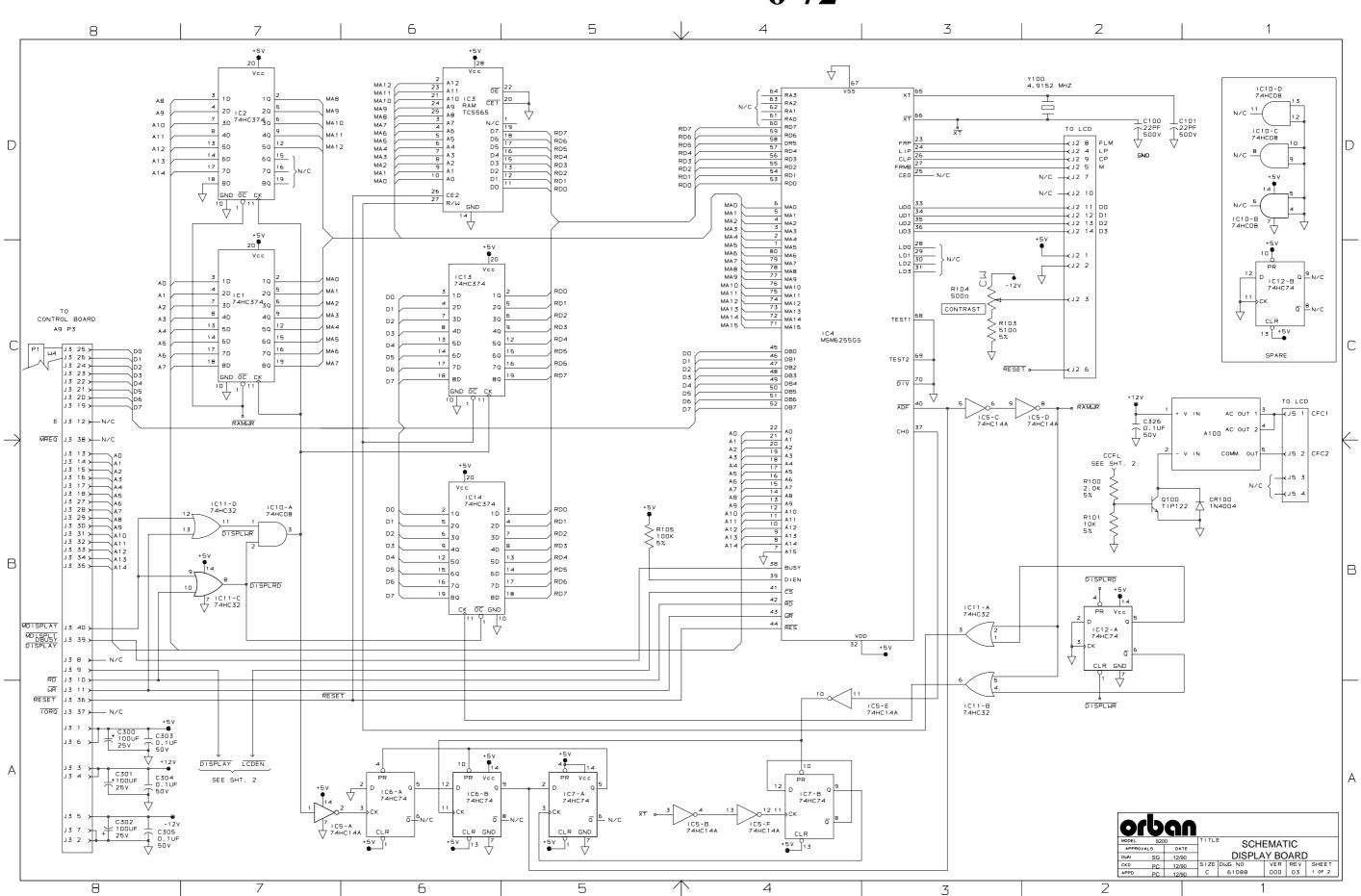
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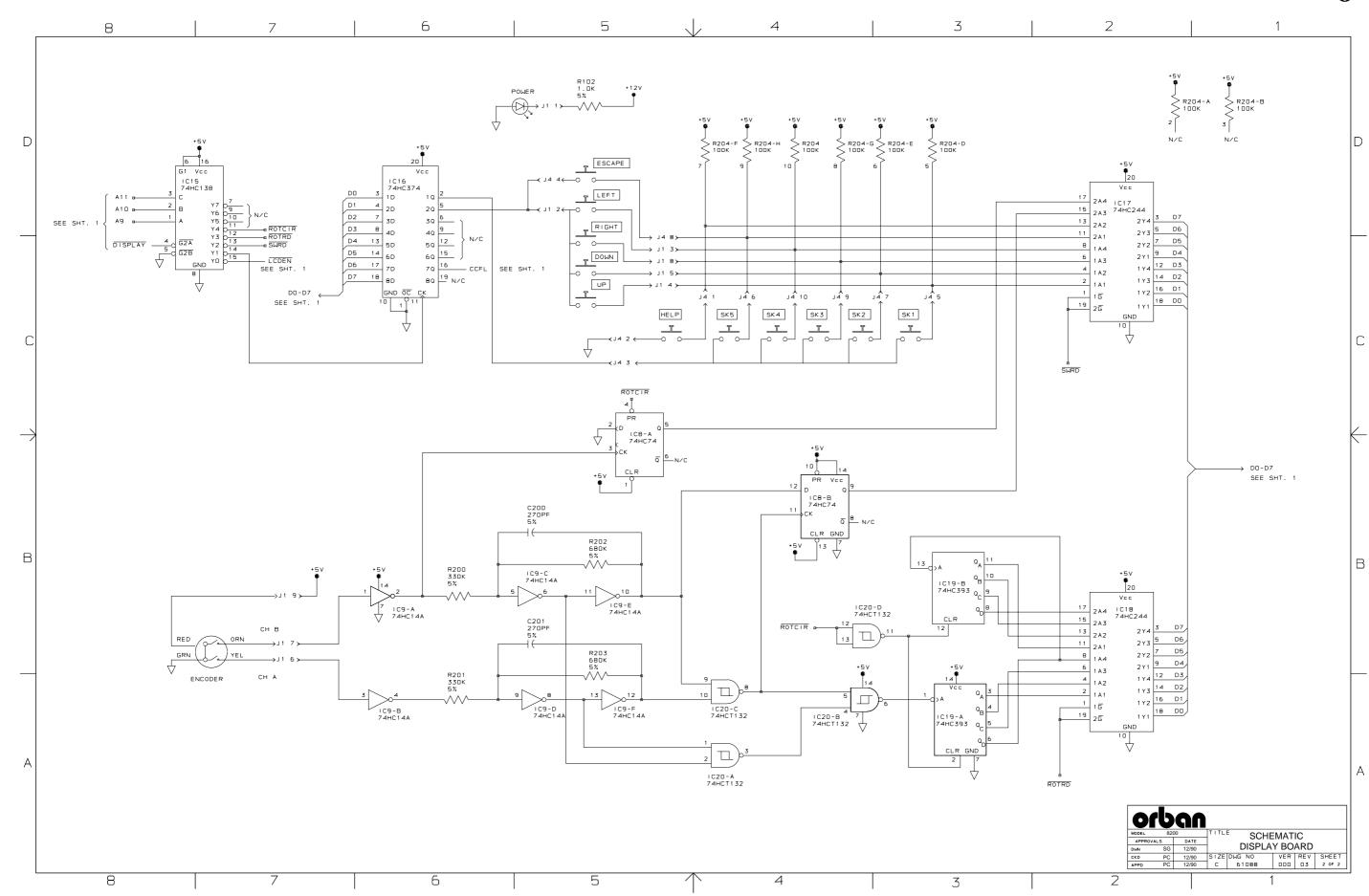


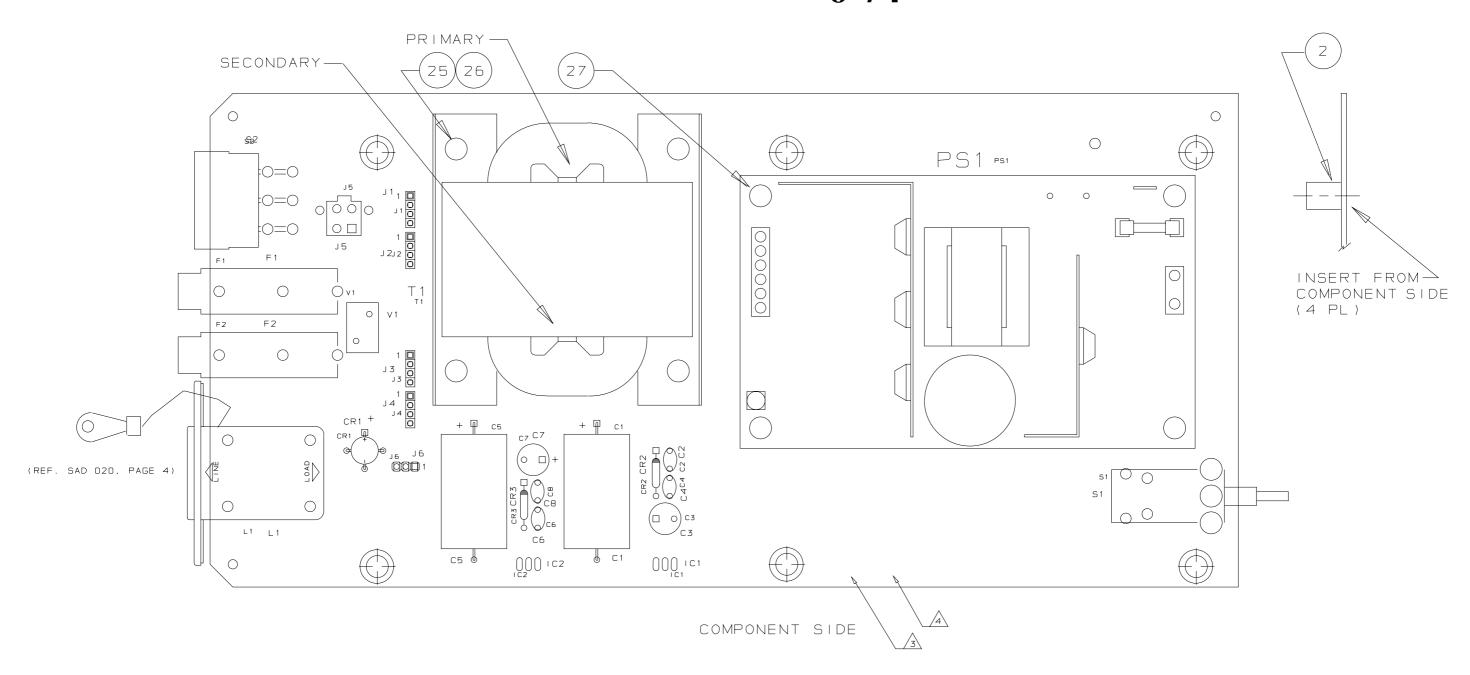
STANDOFF (4 PL)(3)



orban								
MODEL 8200			TITLE	PCB ASSEMBLY				
APPROVALS DATE								
DWN	SG	3/91	MAIN DISPLAY BOARD					
CKD	MJ	3/91	SIZE	DWG NO	VER	REV	SHEET	
APPD	MI	3/91	7 C	31480	000	05	1 OF 1	







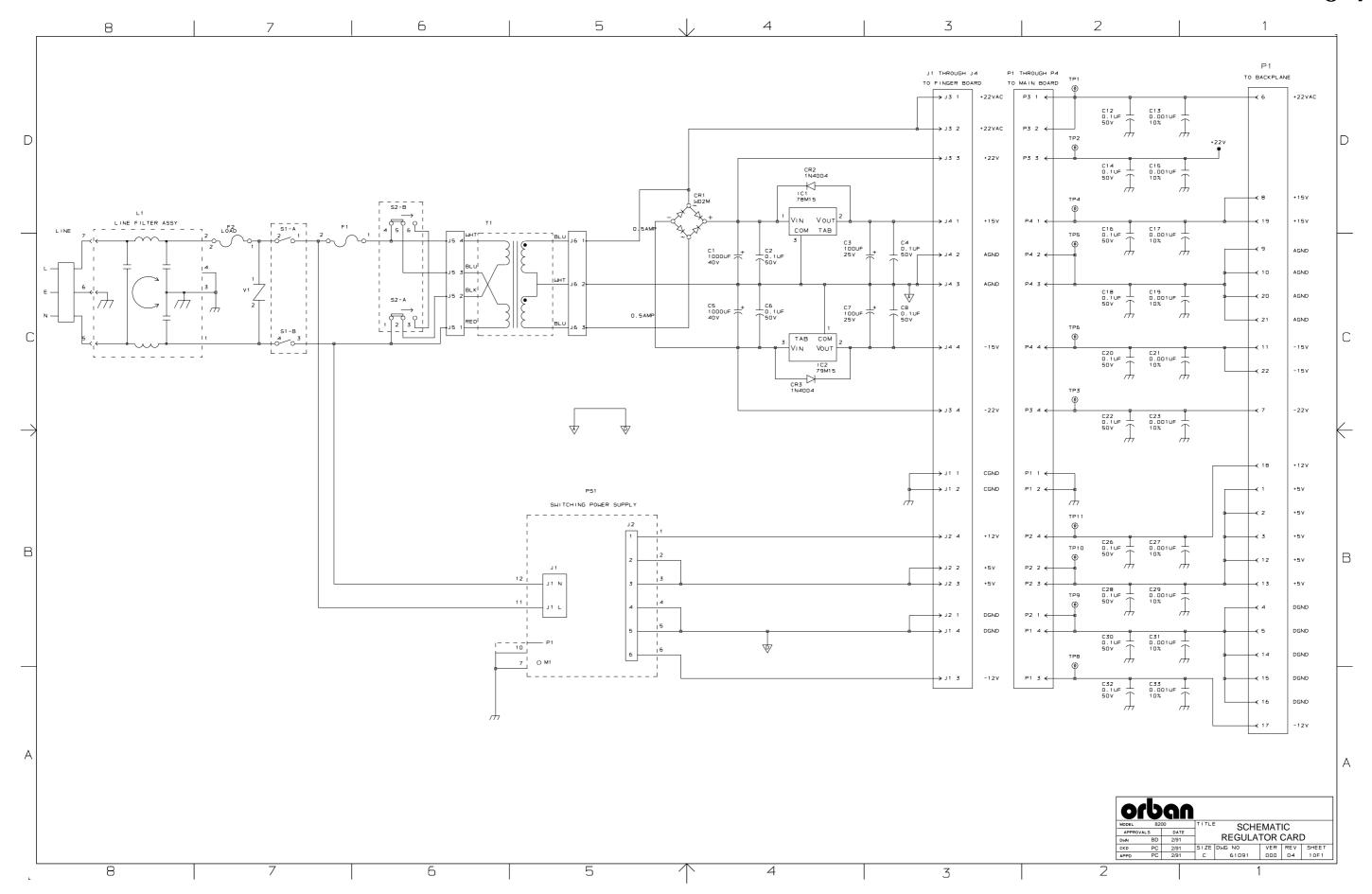
MARK VERSION NUMBER IN SPACE PROVIDED (CIRCUIT SIDE).

/3\ MARK ASSEMBLY REVISION LEVEL IN SPACE (PROVIDED)

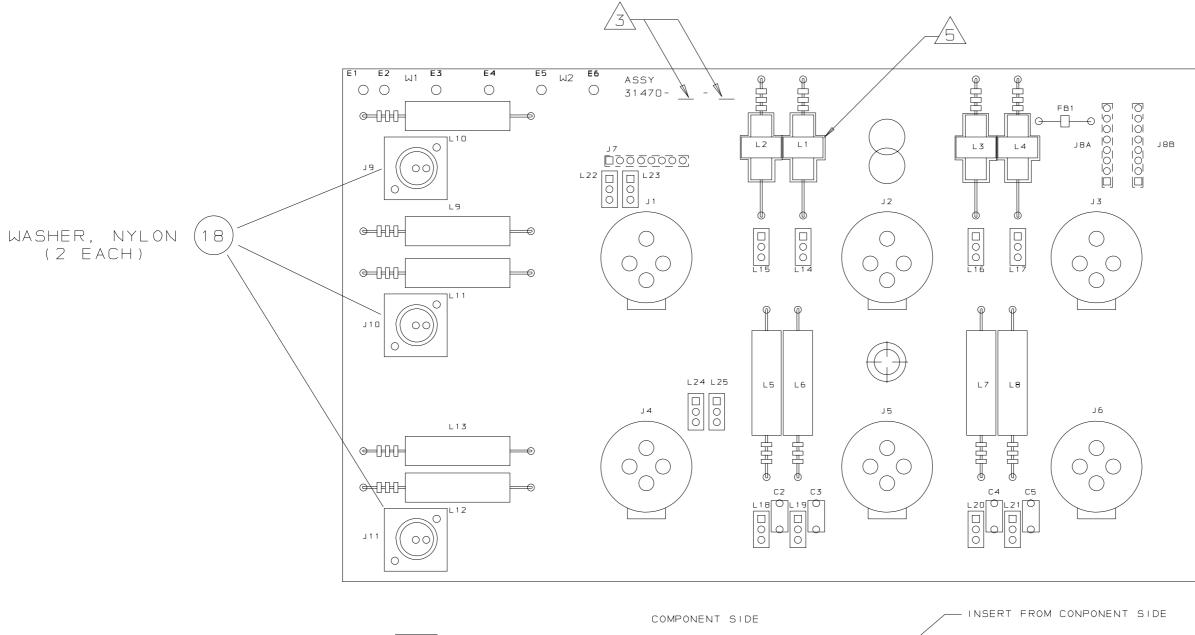
- 2. REFERENCE SCHEMATIC DRAWING NO. 61091.
- 1. SQUARE PADS INDICATE PIN 1 OF CONNECTORS, CATHODE OF DIODES,

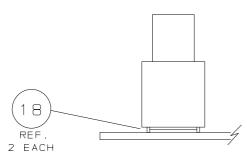
POS. SIDE OF CAPS., PIN 1 OF ICS NOTES: (UNLESS OTHERWISE SPECIFIED)

0	rb	QN)					
MODEL	82	00	TITLE	PCB AS	SEM	RI Y		
APPROVALS DATE								
DWN	BD	2/91		REGULA [®]	IOR	CARI	ر	
CKD	MJ	9/91	SIZE	DWG NO	VER	REV	SHEET	
APPD	MJ	9/91	7 C	31495	000	05	1 OF 1	



6-76 TECHNICAL DATA







SOLDER FLOWING.

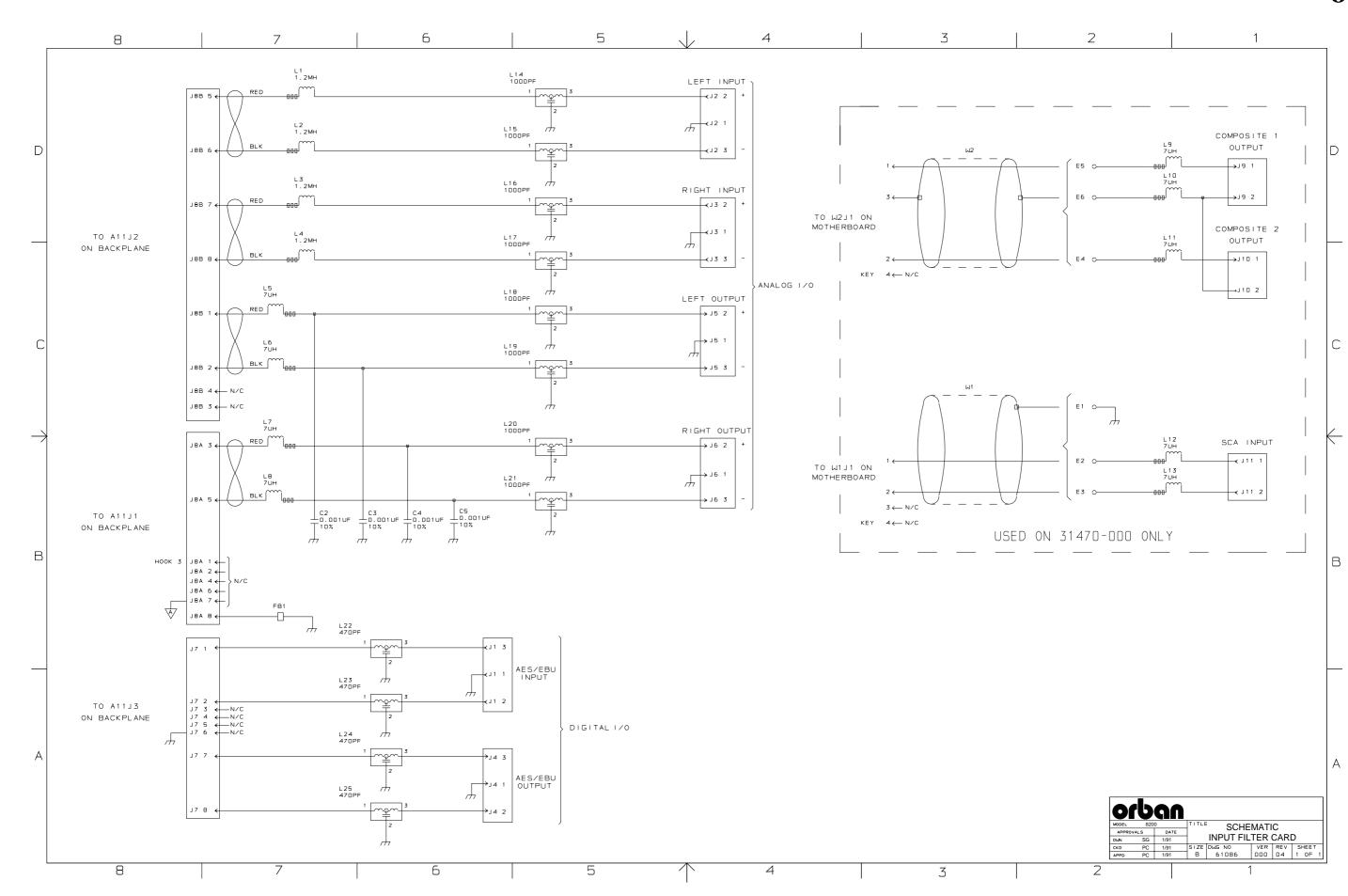
4. J7, J8A & J8B TO BE MOUNTED FROM SOLDER SIDE OF BOARD.

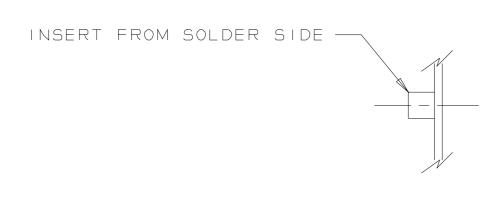
3. MARK ASSEMBLY VERSION AND REVISION LEVEL IN SPACE PROVIDED

- 2. REFERENCE SCHEMATIC DRAWING NO.
- 1. SQUARE PADS INDICATE PIN 1 OF CONNECTORS, CATHODE OF DIODES, POS. SIDE OF CAPS., PIN 1 OF ICS

NOTES: (UNLESS OTHERWISE SPECIFIED)

01	rb	QN					
MODEL	820	00	TITLE	PCB AS	SEM	RI V	
APPR0V	APPROVALS DATE		INPUT FILTER CARD				
DWN	BD	10/91	1	INPUT FIL	IER	CAR	D
CKD	MJ	10/91	SIZE	DWG NO	VER	REV	SHEET
APPD	MJ	10/91	7 C	31470	000	04	1 OF 1





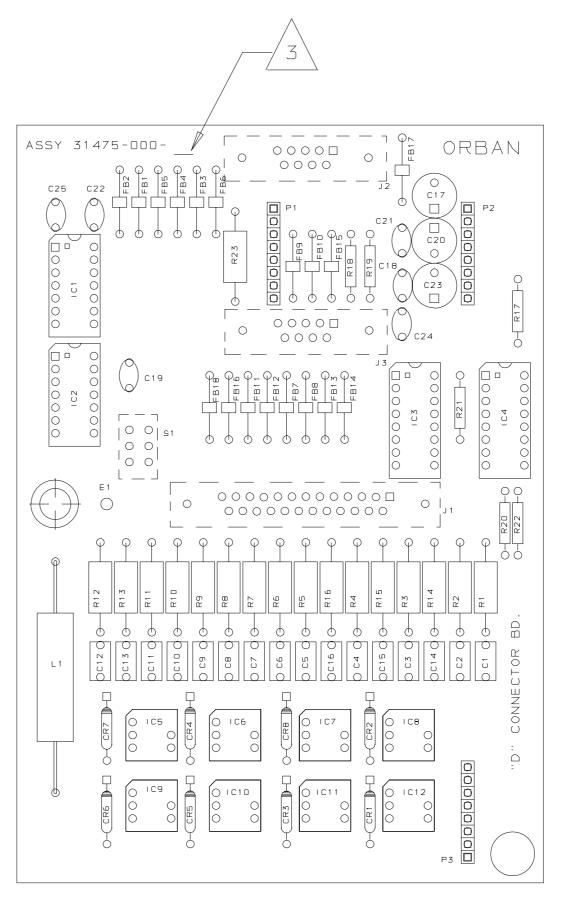
4. S1, J1, J2 & J3 ARE INSTALLED ON CIRCUIT SIDE OF BOARD.

3. MARK ASSEMBLY REVISION LEVEL IN SPACE PROVIDED

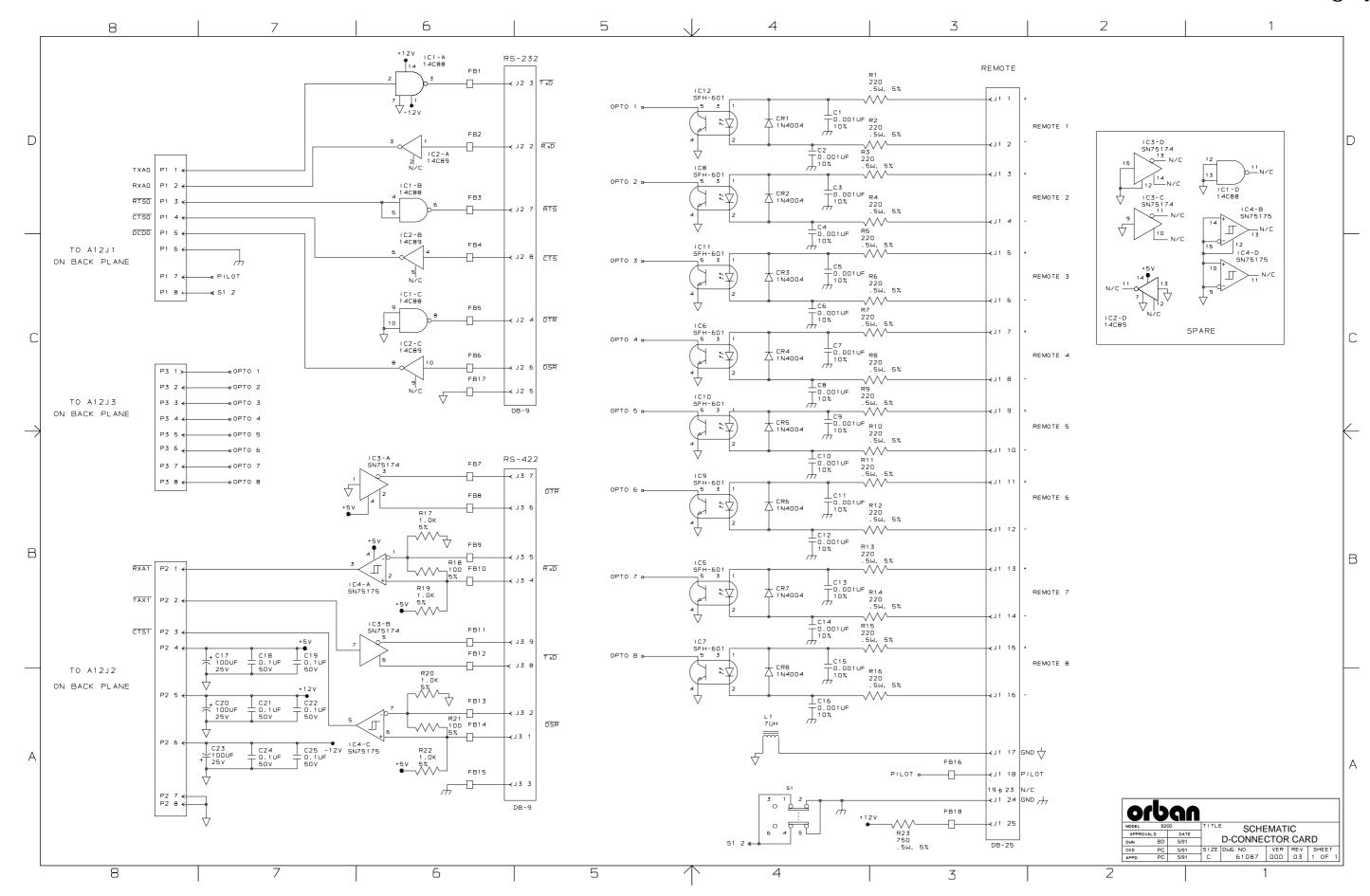
- 2. REFERENCE SCHEMATIC DRAWING NO
- 1. SQUARE PADS INDICATE PIN 1 OF CONNECTORS, CATHODE OF DIODES,

POS. SIDE OF CAPS., PIN 1 OF ICS

NOTES: (UNLESS OTHERWISE SPECIFIED)



0	rb	gn						
MODEL 8200			TITLE	TITLE PCB ASSEMBLY				
APPROVALS DATE				D-CONNECTOR CARD				
DWN	BD	5/91		D-CONNEC	JIOR	CAL	RD	
CKD	MJ	5/91	SIZE	DWG NO	VER	REV	SHEET	
APPD	MJ	5/91	7 C	31475	000	03	1 OF 1	



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OPTIMOD-FM 8200 TECHNICAL DATA 6-81

Abbreviations

Some of the abbreviations used in this manual may not be familiar to all readers:

A/D (or A to D) analog-to-digital converter
AES Audio Engineering Society
AGC automatic gain control

A-I analog input A-O analog output

AT "advanced technology" — IBM PC with 80286 or higher processor

BAL balance

BBC British Broadcasting Corporation

BNC a type of RF connector

CALIB calibrate

CIT composite isolation transformer

CMOS complementary metal-oxide semiconductor

COM serial data communications port

DA (or D to A) digital-to-analog converter

dBm decibel power measurement. 0dBm = 1mW applied to

a specified load. In audio, the load is usually 600Ω .

dBu decibel voltage measurement. 0dBu = 0.775V RMS. For this

application, the dBm-into-600 Ω scale on voltmeters can be read

as if it were calibrated in dBu.

DI digital input

DJ disk jockey, an announcer who plays records in a club or on the air

DO digital output

DOS Microsoft disk operating system for IBM PC

DSP digital signal processor

EBU European Broadcasting Union

EBS Emergency Broadcasting System (U.S.A.)

EMI electromagnetic interference

ESC escape

FCC Federal Communications Commission (USA regulatory agency)
FDNR frequency-dependent negative resistor — an element used in

rc-active filters

FET field effect transistor
FFT fast Fourier transform

FIFO first-in, first-out
G/R gain reduction
HF high-frequency

HP high-pass

IC integrated circuit

IM intermodulation (or "intermodulation distortion")

I/O input/output

JFET junction field effect transistor

LC inductor/capacitor
LCD liquid crystal display
LED light-emitting diode
LF low-frequency

LP low-pass

LVL level

MHF midrange/high-frequency
MLF midrange/low-frequency

MOD modulation

N&D noise and distortion

N/C no connection
OSHOOT overshoot

PC IBM-compatible personal computer

PCM pulse code modulation
PPM peak program meter
RAM random-access memory

RC resistor/capacitor

REF reference

RF radio frequency

RFI radio-frequency interference

RMS root-mean-square ROM read-only memory

SC subcarrier

SCA subsidiary communications authorization — a non program-related

subcarrier in the FM baseband above 23kHz (monophonic) or

57kHz (stereophonic)

S/P-DIF Sony/Philips digital interface

TRS tip-ring-sleeve (2-circuit phone jack)

THD total harmonic distortion

TX transmitter μs microseconds

VCA voltage-controlled amplifier

VU volume unit (meter)

XLR a common style of 3-conductor audio connector

XTAL crystal

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